



**The Abdus Salam
International Centre for Theoretical Physics**



2269-27

Workshop on New Materials for Renewable Energy

17 - 21 October 2011

**Novel growth technology for thin film photovoltaics: II-VI semiconductors and
TCO**

Carlo TALIANI
*ISMN - CNR, Bologna
Italy*

Novel growth technology for thin film photovoltaics: II-VI semiconductors and TCO

Carlo Taliani
ISMN - CNR
Bologna



Carlo Taliani background

- '70 Chemical physics of aromatic molecules (AM)
- Solid state spectroscopy of AM synonymous of Organic Semiconductors (OSemicon)
- Solid state properties of OSemicon
- '86 High Tc superconductors, growth, PIA, polarons
- '92 first UHV growth of OSemicon
- '90 OLED, FET, OPV developments
- '2001 invention of Organic Spintronics (OS)
- '2003 PPD ablation technique and establishment of OS company
- '2007 II-VI thin film PV growth by PPD at 2SN SpA

- Bologna is a 3000 yr. old town with a large well preserved medieval centre.
- Is the site of the oldest (900yr) University in the world.



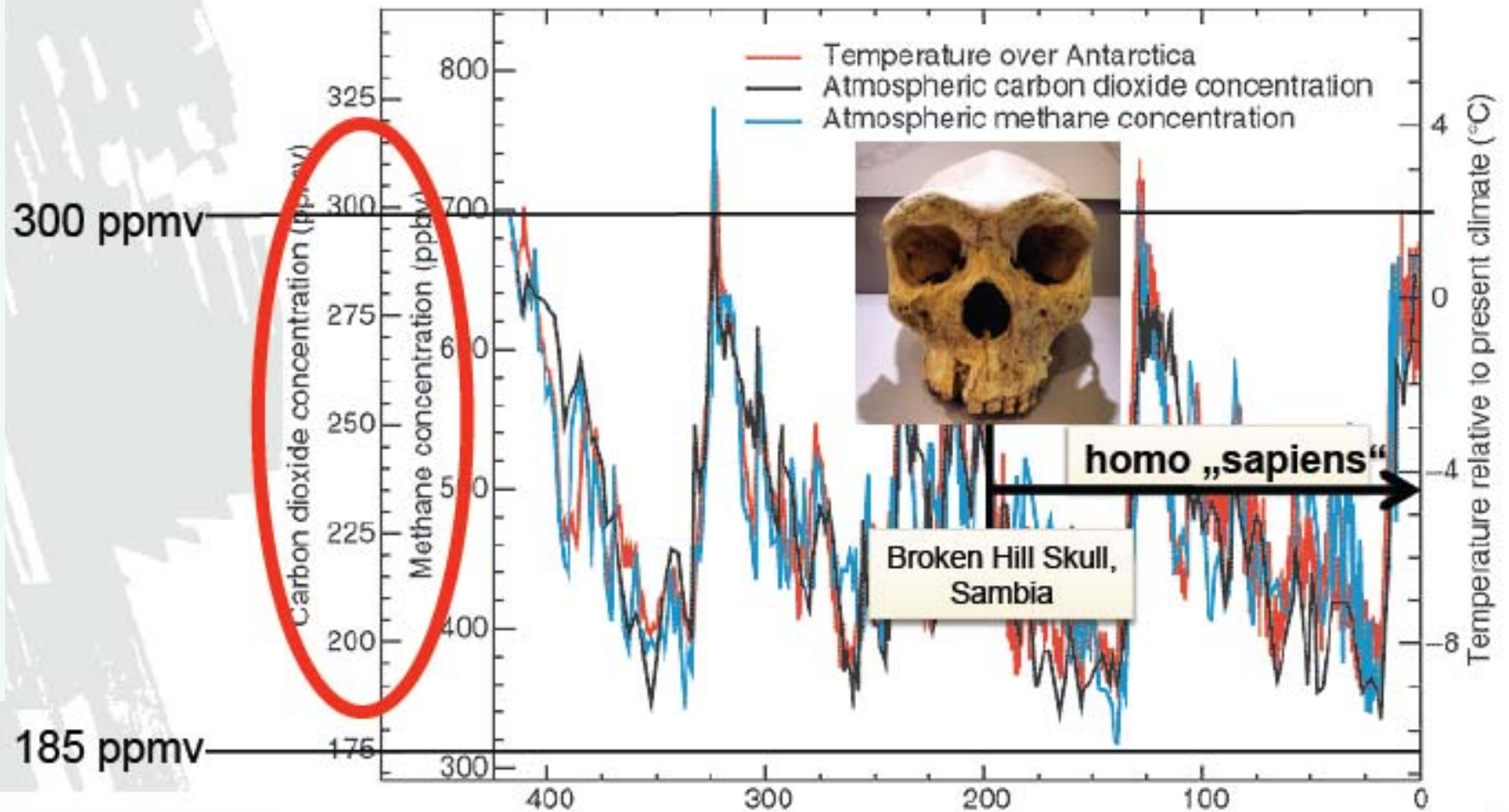
Outline

- PV and Grid Parity
 - Second Generation Photovoltaics
 - Thin Film Growth Technologies
- PPD Ablation
 - sustainable thin film deposition process
 - environmentally friendly process
- CdTe PV on glass and metal
 - integrated in the building structure
- Transparent Conductor
 - Transparency vs Conductivity
 - TCO on plastic
 - Inverted TOLED by top deposition

Motivation

Co2 vs time

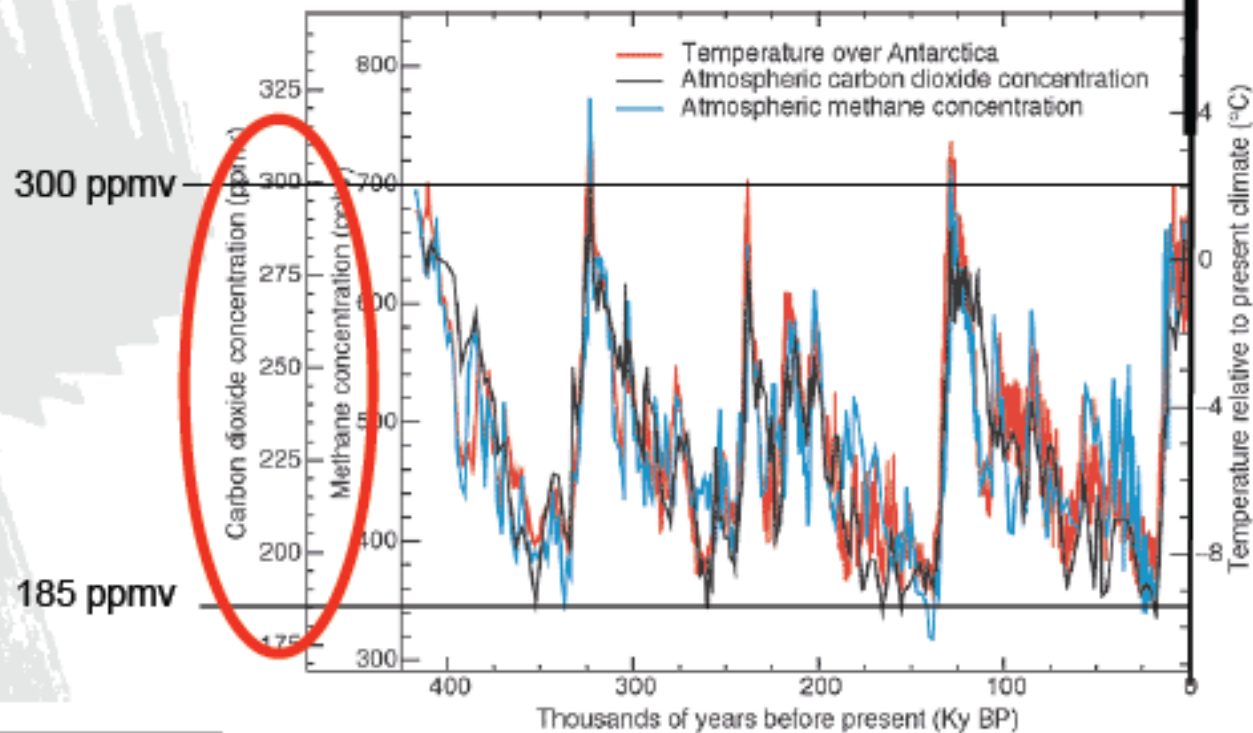
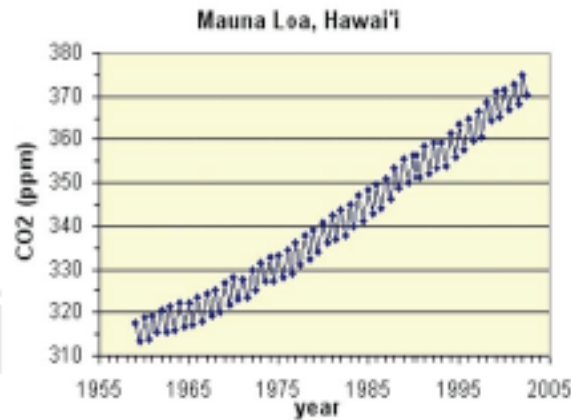
Concentrazione di CO2



6.5.2010

Migliaia di anni

CO₂ and Climate Change



500 ppmv

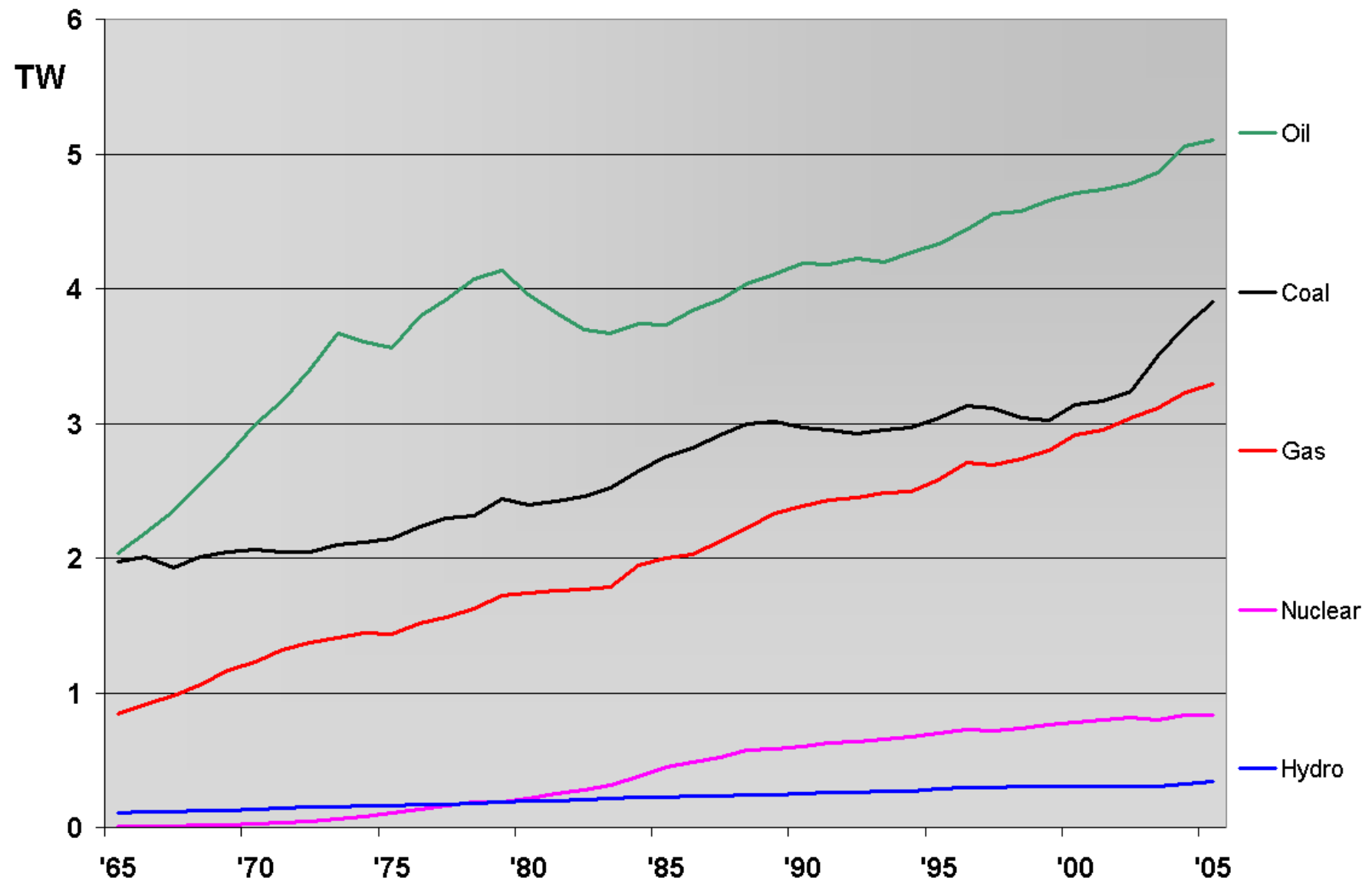
?

400 ppmv

385 ppmv (2008)

How much
CO₂ the
globe can
stand?

15 TW needed for the world



Need for CO₂-free Power

In order to stabilize our
climate we need in 2050
at least

10 TW to 30 TW

of CO₂-free power.

*based on extremely optimistic assumptions
and very conservative calculations*

Alternatives

Solar

Biomass



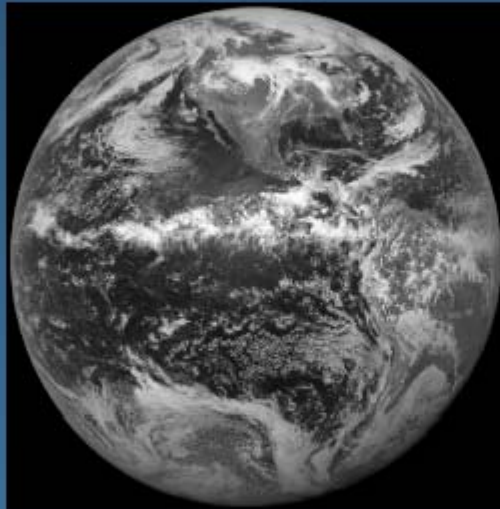
Wind

Hydroelectric

Geothermal

Ref.: Nathan S. Lewis, <http://nsl.caltech.edu/energy>

Hydro 1,6TW



Hydroelectric

Gross: 4.6 TW

Technically Feasible: 1.6 TW

Economic: 0.9 TW

Installed Capacity: 0.6 TW

Ref.: Nathan S. Lewis, <http://nsl.caltech.edu/energy>

Geotherm. 11,6 TW



Geothermal

Mean flux at surface: 0.057 W/m^2

Continental Total Potential: 11.6 TW

Ref.: Nathan S. Lewis, <http://nsl.caltech.edu/energy>

Wind 2 - 3TW

Wind

4% Utilization
Class 3 and
Above
2 - 3 TW



Ref.: Nathan S. Lewis, <http://nsl.caltech.edu/energy>

Biomass 1 - 2TW

Biomass

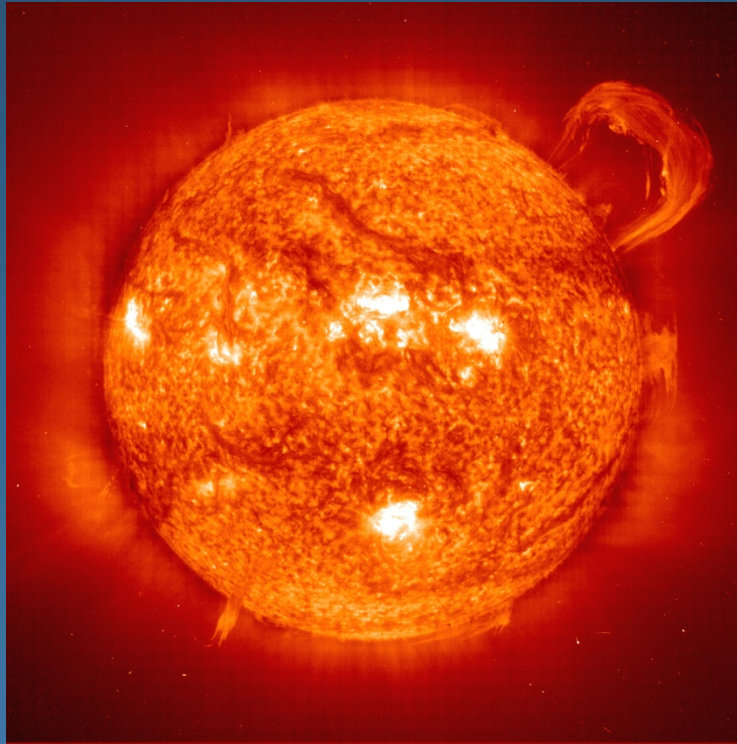


50% of all cultivatable land:
7-10 TW (gross)
1-2 TW (net)

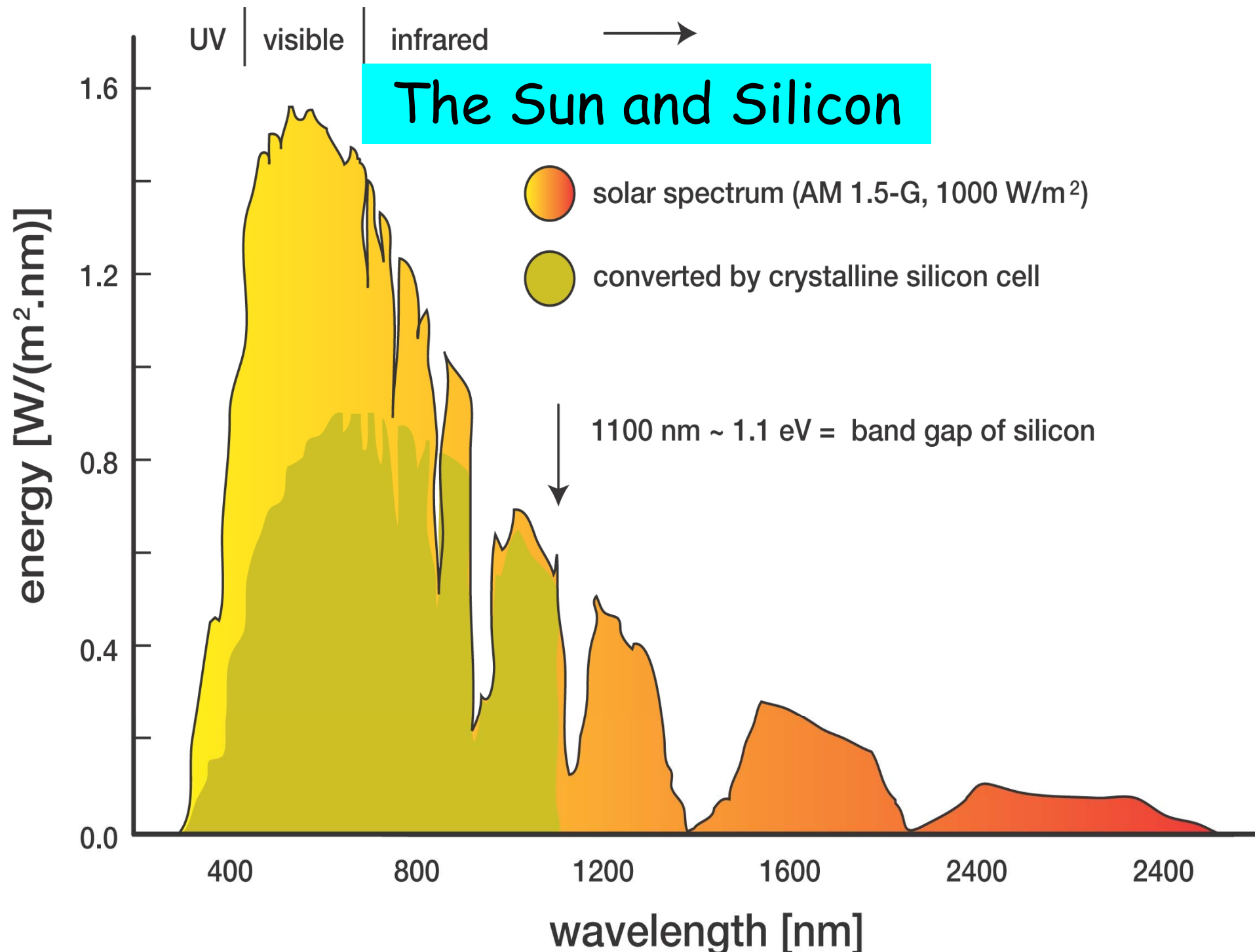
Ref.: Nathan S. Lewis, <http://nsl.caltech.edu/energy>

Solar 600TW

Solar: potential 1.2×10^5 TW; practical > 600 TW

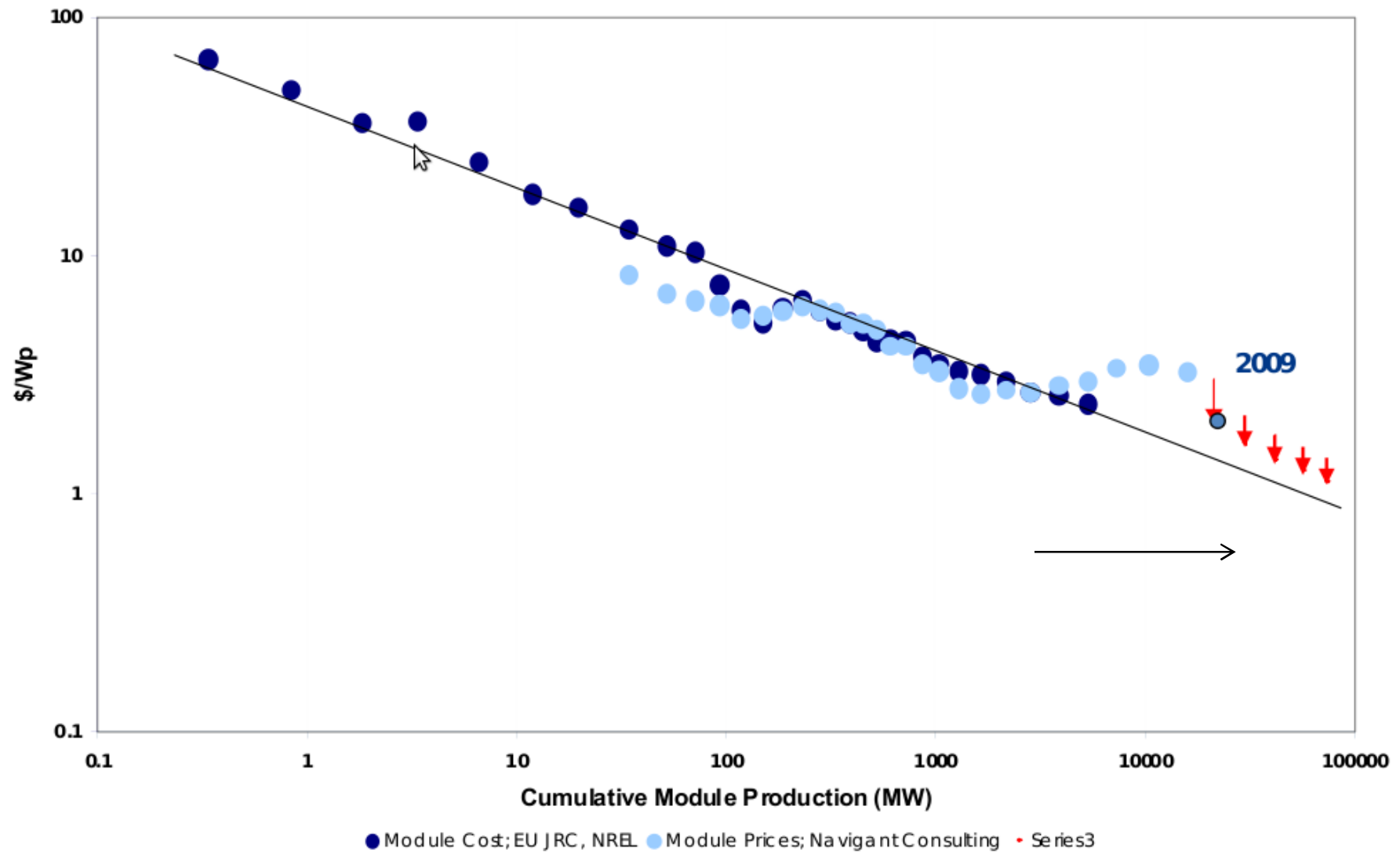


Ref.: Nathan S. Lewis, <http://nsl.caltech.edu/energy>



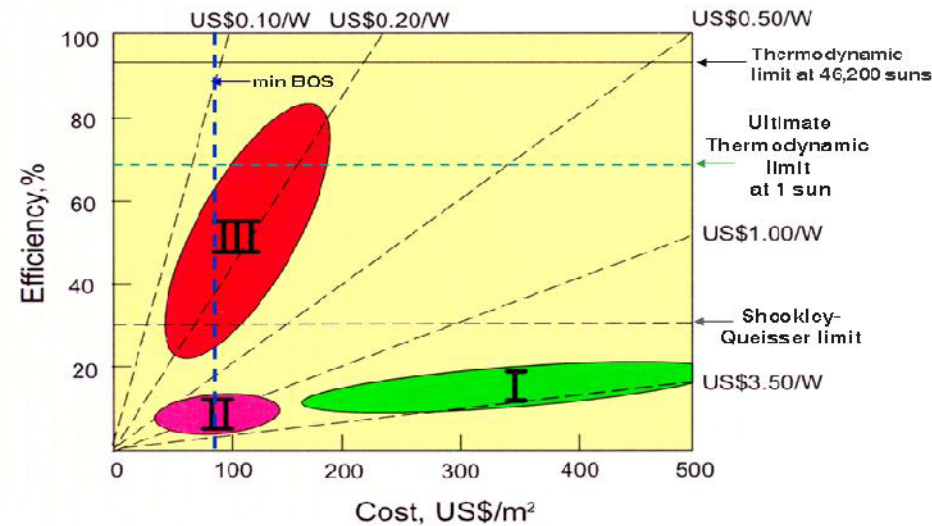
Motivation

PV: learning curve



Development of a novel low cost photovoltaic (PV) technology

- Present cost of PV is unsustainable
- Need to find a low cost (Gen II) PV technology
- Thin films option

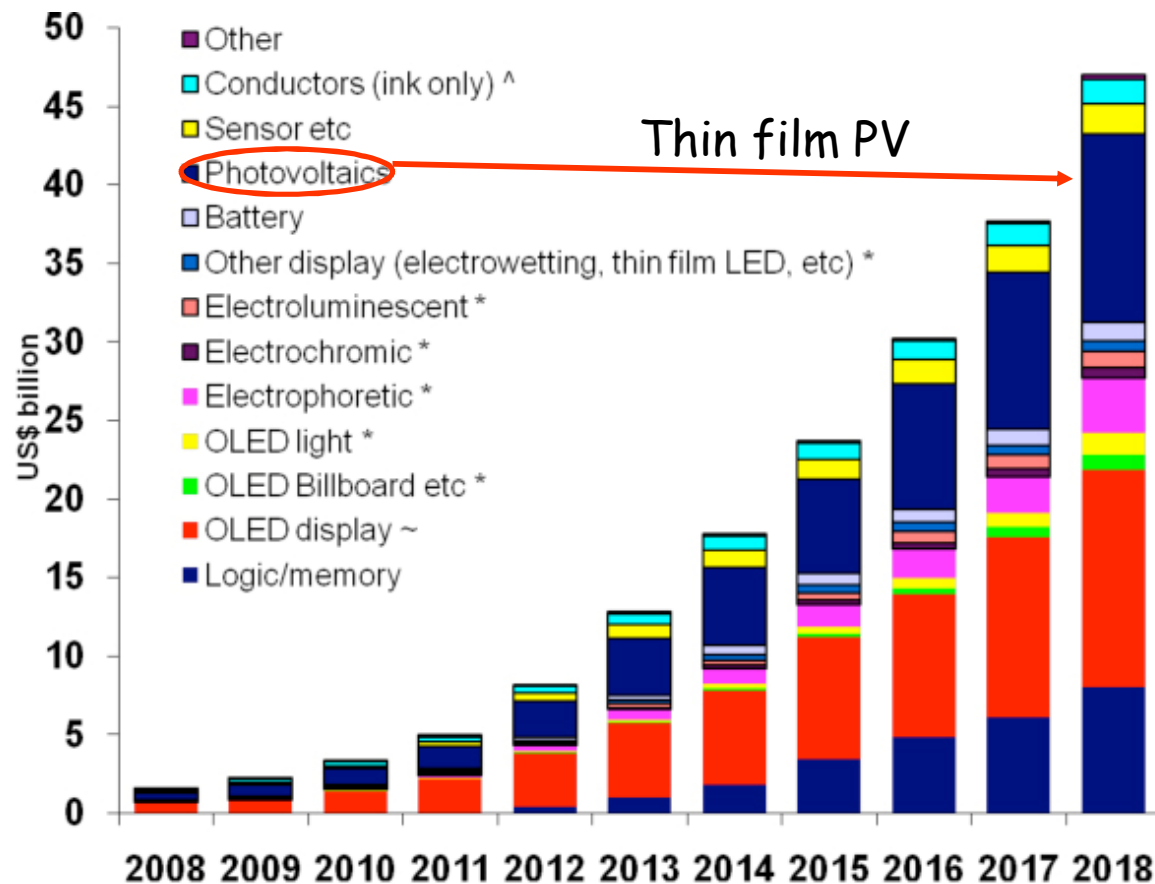


For PV or PEC to provide the full level of C-free energy required for electricity and fuel—solar power cost needs to be ~2 cents/kWh ($\$0.40/W_p$).

Gen II Photovoltaic market perspective

Market size perspective of major new technologies

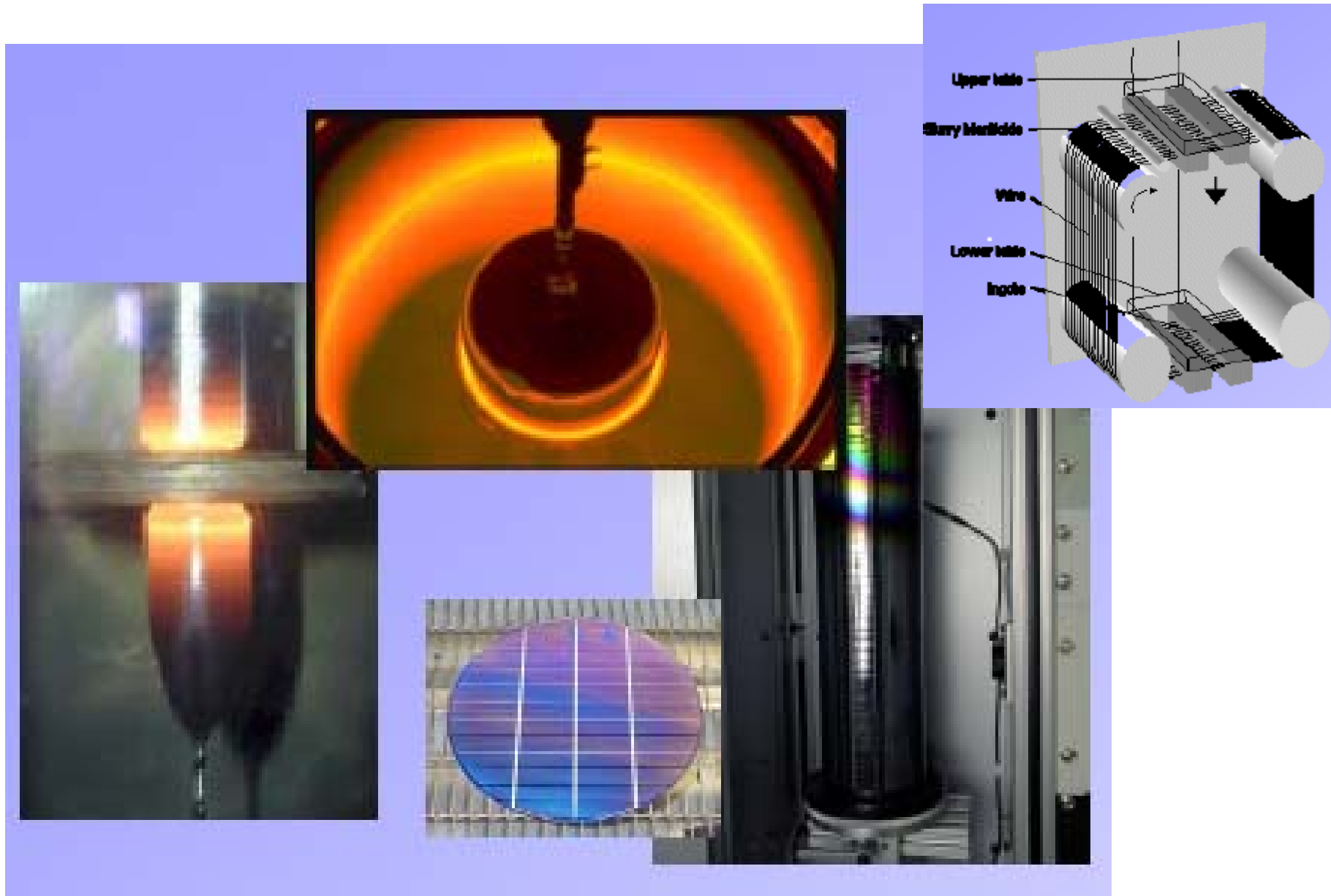
Thin Film Photovoltaic (beyond conventional silicon technology) represents a 12 bil \$ market. (Source IDtechEx)



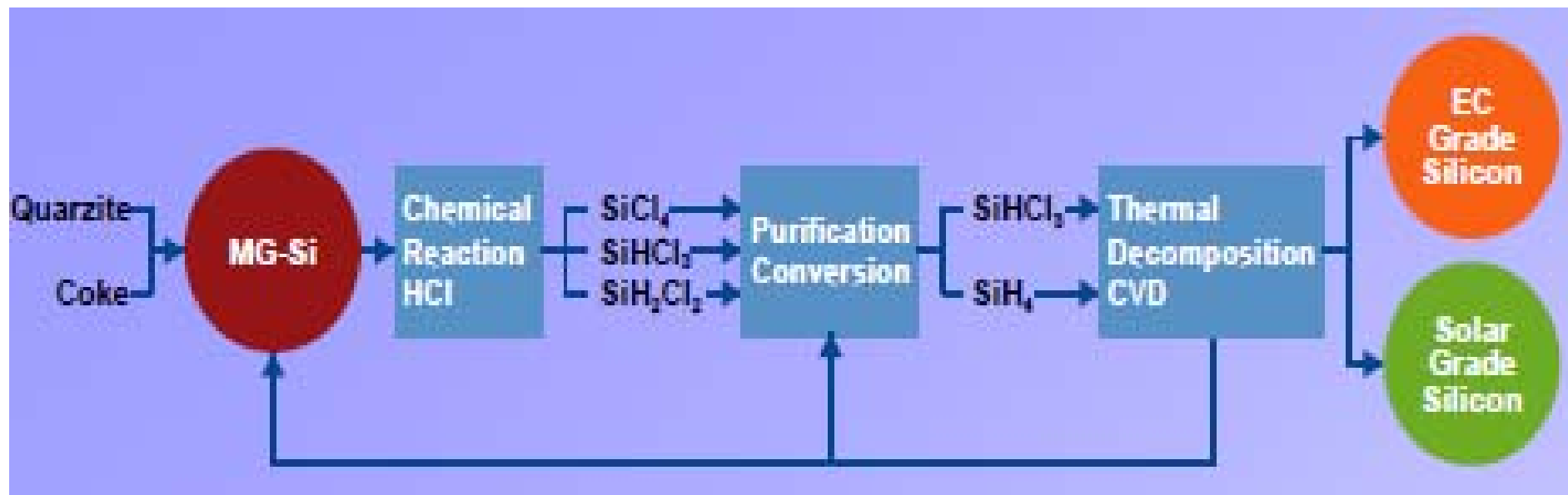
20 billion \$

Silicon is not the material for solar

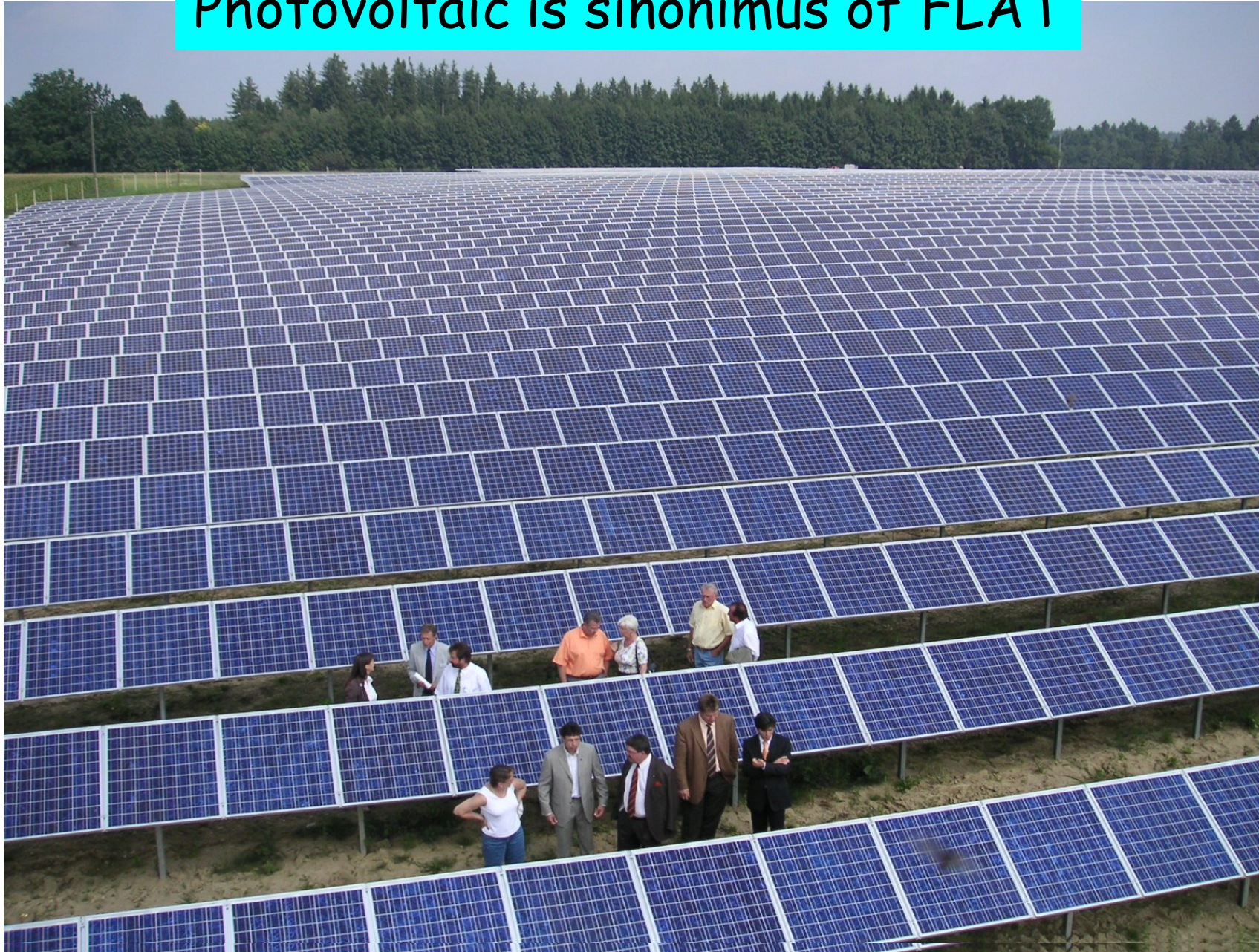
Silicon manufacturing



Silicon manufacturing



Photovoltaic is sinonimus of FLAT



The silicon paradox

Silicon is not suitable for PV since it is a **indirect-gap** semiconductor (small absorption cross section).

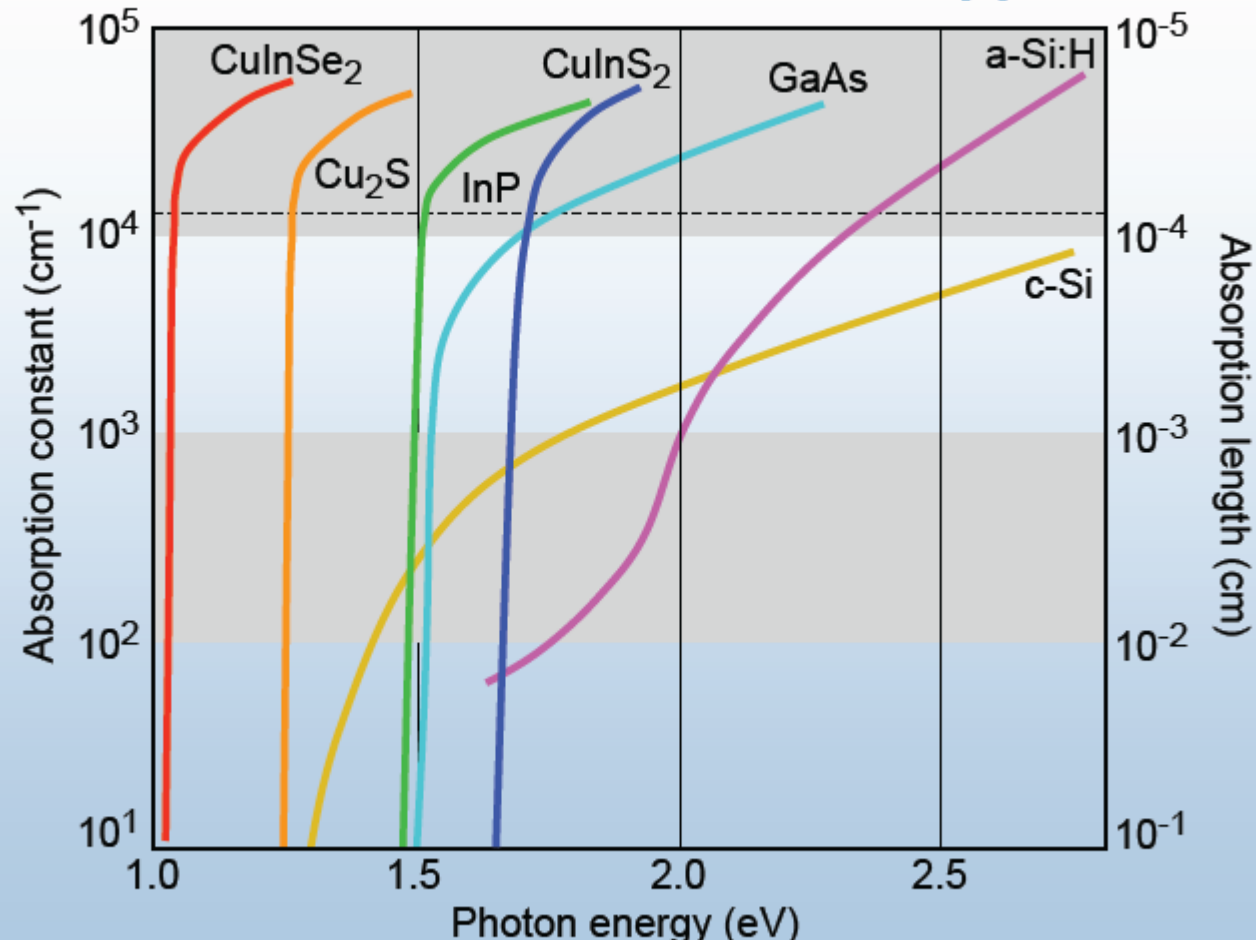
The cost to make it is determined mainly by the **energy** required to purify and treat it.

Whichever is the fossile energy cost (grid cost) silicon will follow it.

There is no hope to achieve **grid parity** with silicon!

Direct vs Indirect Band Gap

Absorption Coefficient of Chalcopyrite Compounds Together with Other Semiconductors Applied in PV



Source: Satyan K. Debb (2005)

Thin Film Solar Cells, N. Hamada, Springer

Why CdTe?

- 1 CdTe is a **direct gap** semiconductor (i.e. absorbs efficiently sunlight).
one micron thickness is sufficient

CdTe

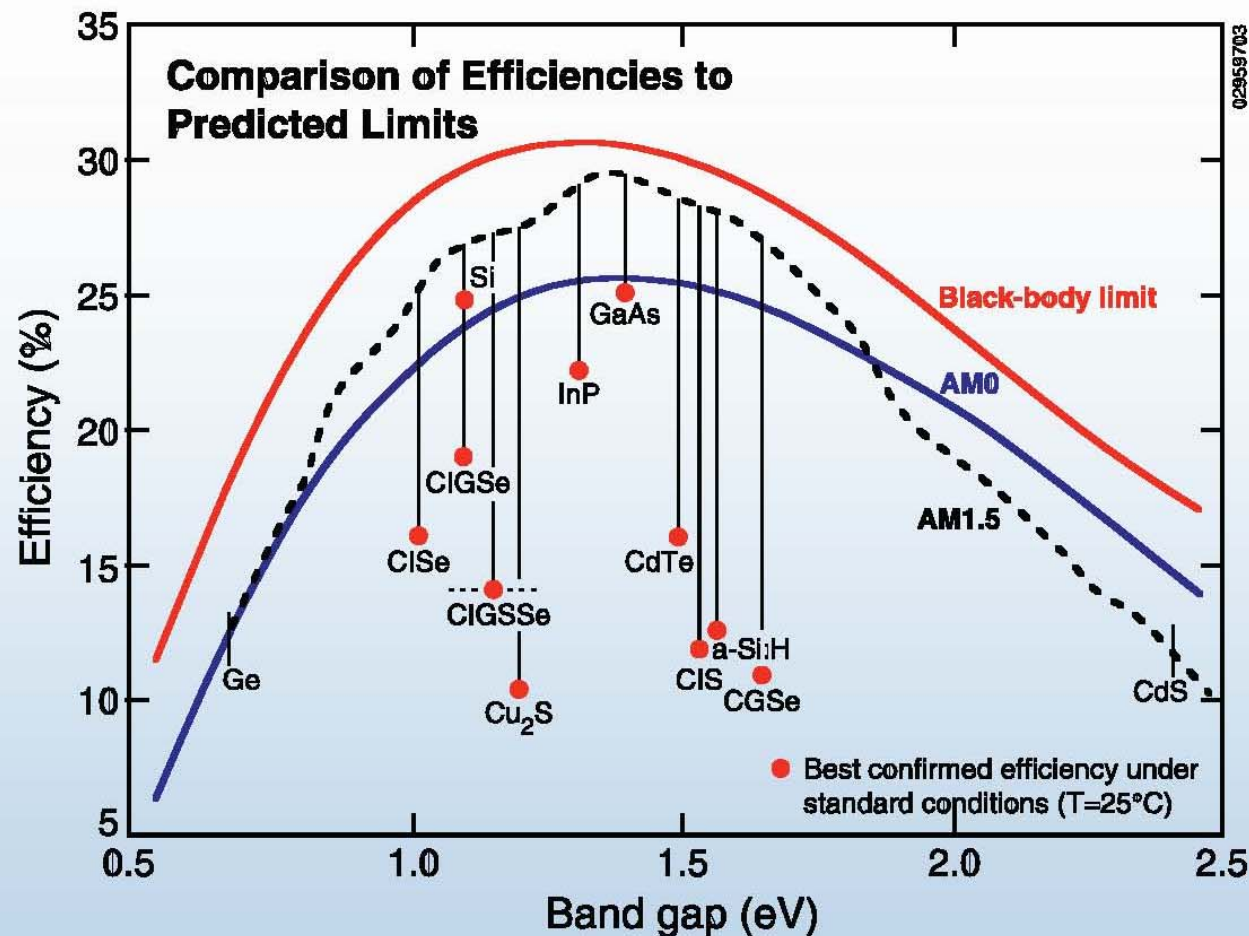


Silicon

Thickness

The silicon paradox: is a poor absorber because it is an **indirect gap** semiconductor.

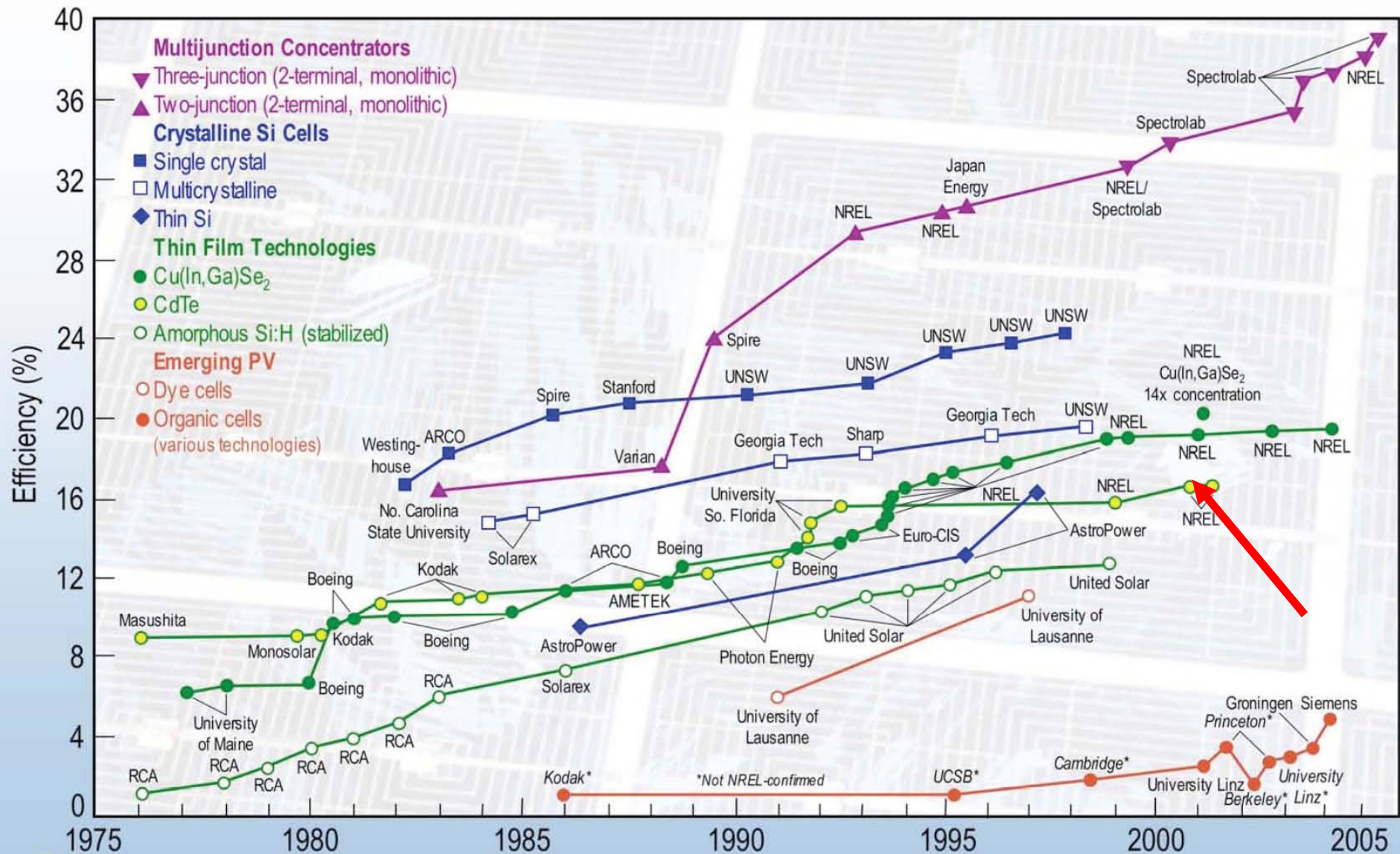
- 2 In theory the efficiency is in excess of **30%**



Calculated AM1.5 efficiencies (dashed line) and AM0 efficiencies (solid line), comparing achieved cell efficiencies (laboratory-best, confirmed) for various technologies

Source: Satyen. K. Debb (2005)

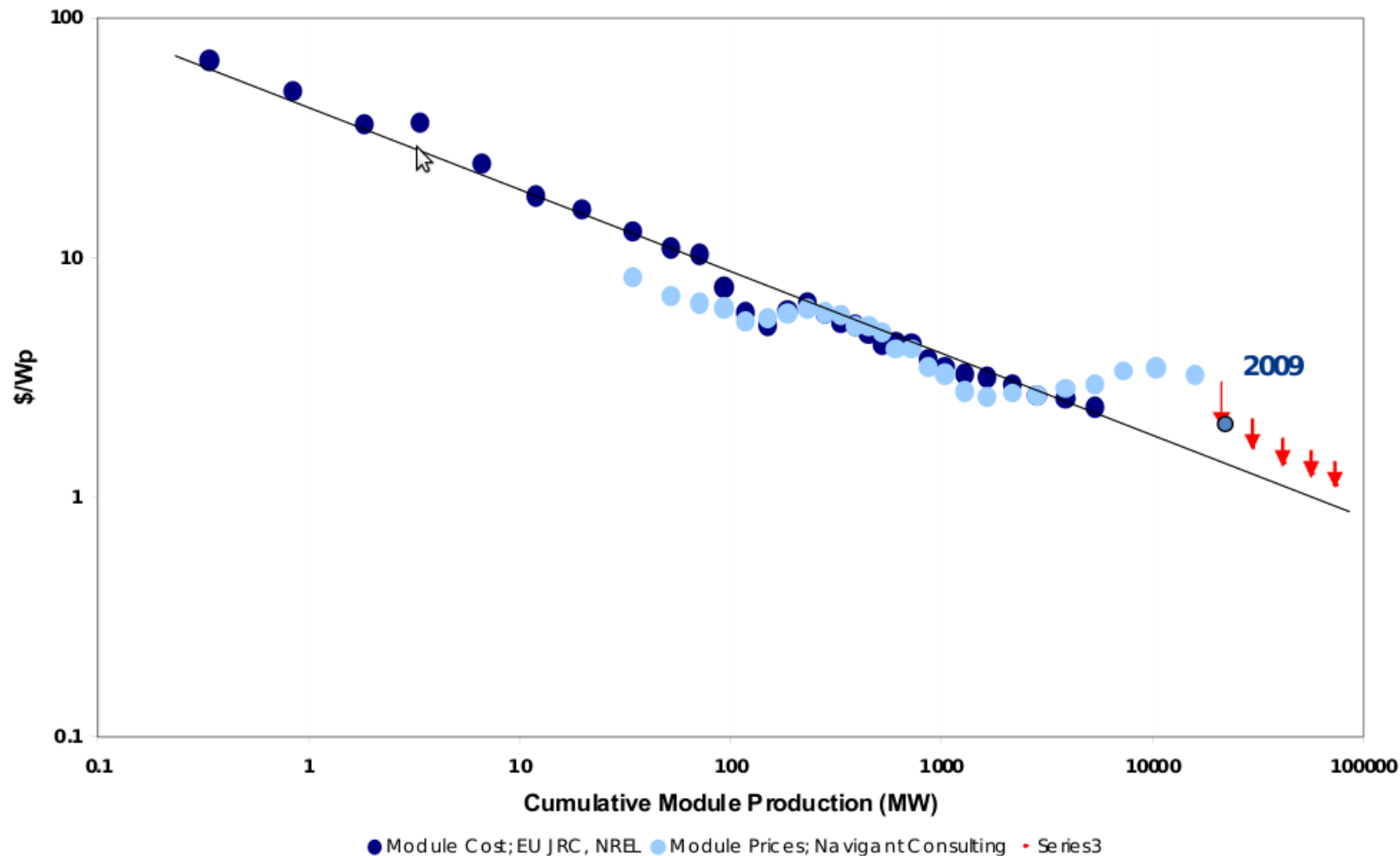
Best Research-Cell Efficiencies



Source: Satyen. K. Debb (2005)

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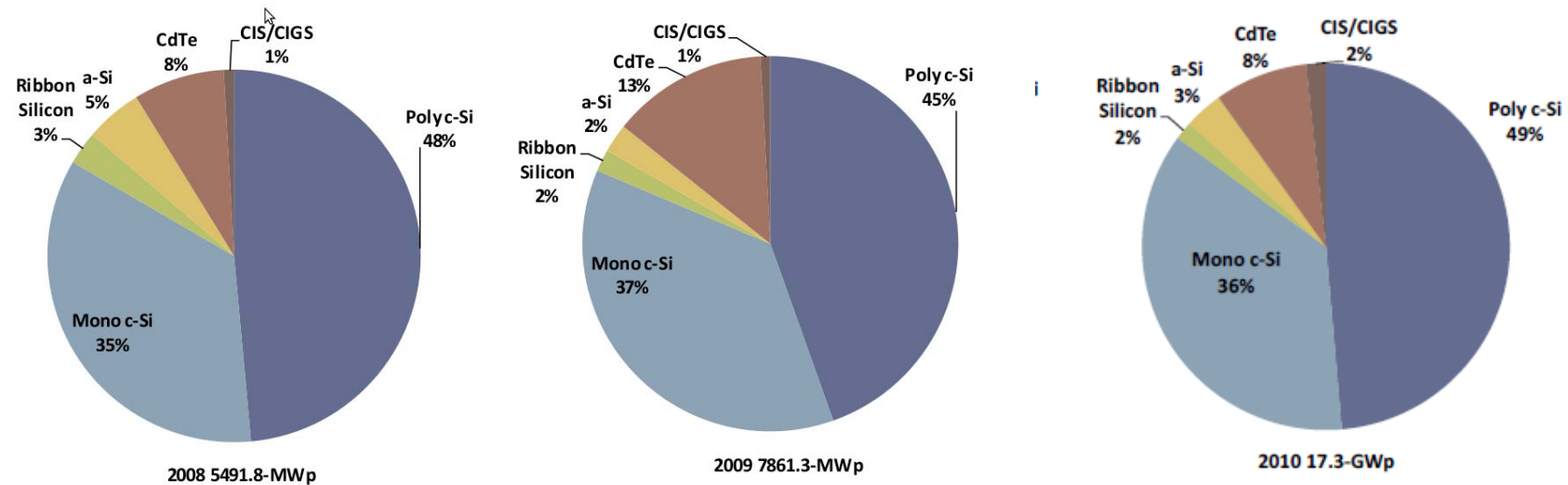
PV: Cost learning curve



Production costs and sales prices vs time. See the umbrella effect in 2008 due to over-demand determined by the subsidies determining the entrance of unsustainable technologies.
Source: Navigant Consulting

Technology Market Shares, 2009 and 2010

Thin films held a 17% share of the market for all PV technologies in 2009, and a 13% share of the market in 2010. In 2010, thin film shipments grew by 72% over 2009, with c-Si growing by 129% over 2009.



CdTe : 430 (2008) - 1021 (2009) - 1384 (2010) MW/yr

Thin film PV

Fotovoltaico di seconda generazione

Film sottile

- Poco materiale
- Poca energia, basse temperature..
- Nanotecnologie

Silicio amorfo

CdTe (Tellururo di Cadmio)

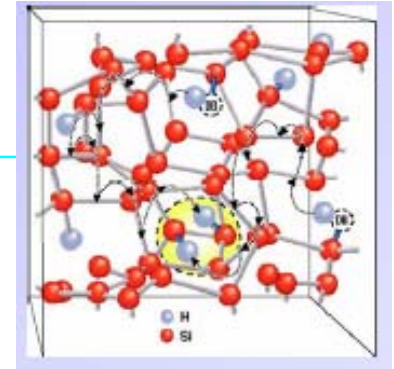
CIGS

Fotovoltaico di seconda generazione

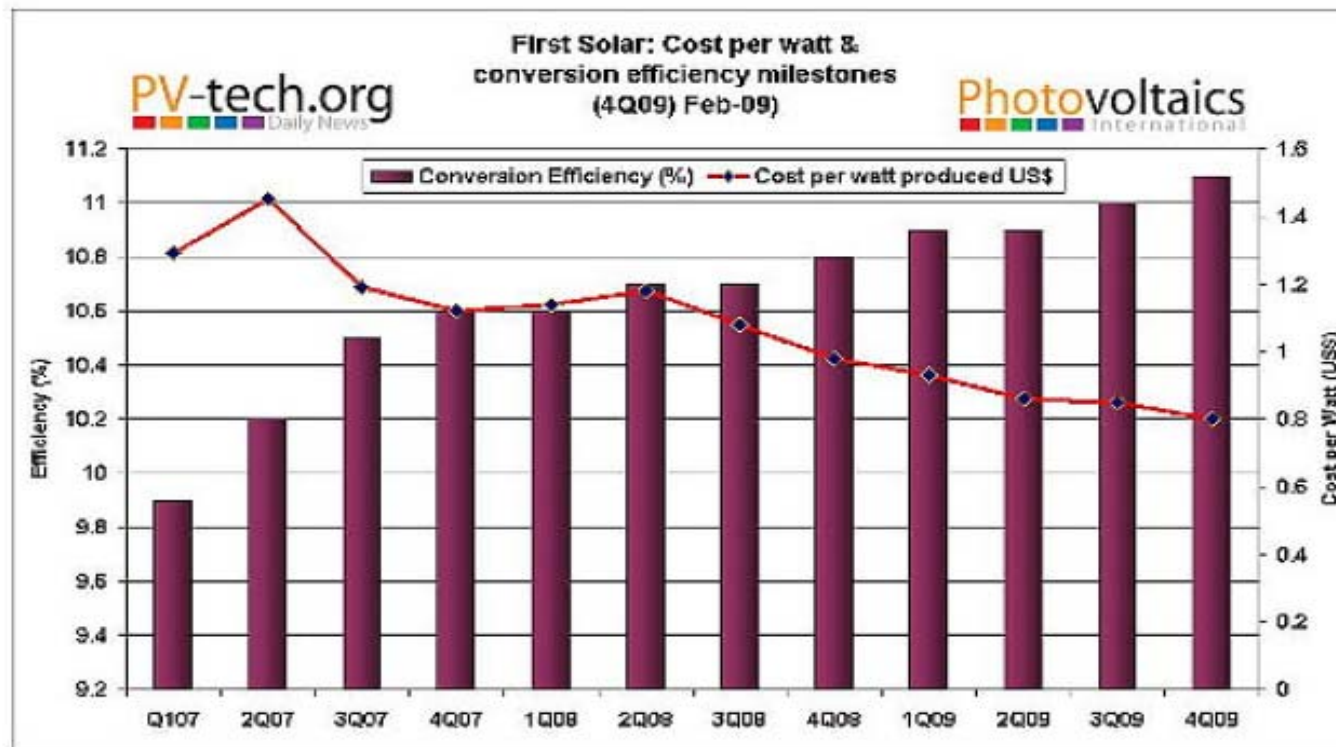
Silicio amorfo : basso rendimento e alti costi

Tellururo di Cadmio: basso costo e crescita impetuosa

CIGS: ancora a livello di sviluppo

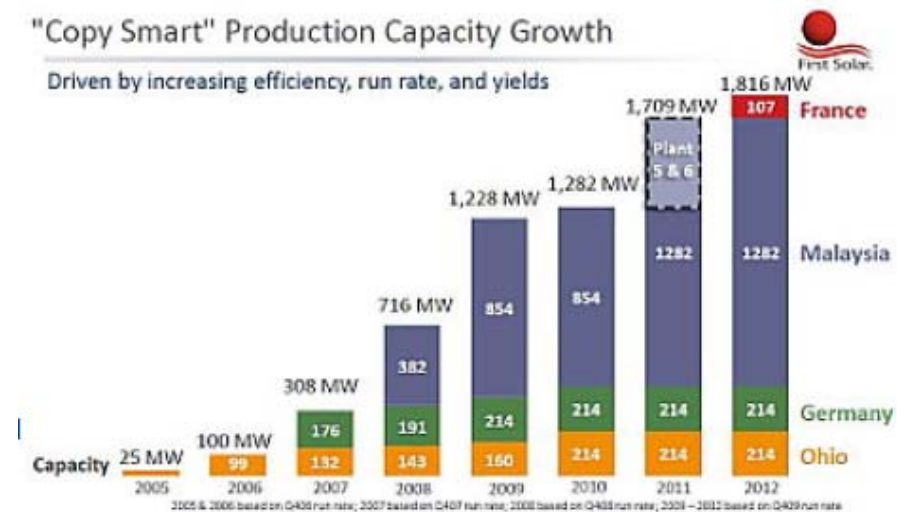


The Champion First Solar Case



"Copy Smart" Production Capacity Growth

Driven by increasing efficiency, run rate, and yields



Our approach

OS and 2SN have developed a new thin film deposition technology characterized by:

- **Proprietary** IP CdTe process and fabrication
- **Low** material cost and consumption
- **Low** installation, maintenance and running costs
- **Safe** (contained low P) fabrication method
- **Shortening** time to market by integrating the module into existing CdTe lines
- Suitable for **Roll to Roll** on metal and plastic foils
- **Conformable** PV (flexible, building integrated)



Material usage and availability

Table 2 Are There Enough Materials for Energy-significant PV Production?

Technology	Material	World Production (MT/yr) ^a	Materials Required (MT) ^{a,b}	% of Current Production	Annual Growth Needed (%)
Crystalline silicon	Purified silicon	25,000 ^b	130,000	520	3.7 ^c
	Silver (grids, cell pads)	20,000	6,000	30	0.53
Thin-film Cu (In, Ga)Se ₂ alloys	Indium	250 (by-product)	400	160	2.0 ^d
	Selenium	2,200	800	36	0.6 ^e
	Gallium	150	70	47	0.9 ^f
Thin-film CdTe	Tellurium	450 (2,000 unused by-product)	933	38 (of total, including unused)	2.2
	Cadmium	26,000 (by-product)	8	3	0.06
Thin-film silicon	Germanium	270 (3,200 unused by-product)	40	1 (of total, including unused)	0.7

^a Necessary production for each type of PV technology to produce 20 GW/yr by 2050

^b Metric tons

^c Elemental silicon is not constrained by supply; current production is low because of low demand.

^d Indium is a by-product of zinc, which has been growing at 3%/yr for 50 years. Indium growth will probably exceed demand because of growth in zinc.

^e Selenium is a by-product of copper; an increase of only 0.16% per year would keep pace with demand.

^f Gallium is not constrained by supply; current production is low because of low demand.

The PPD Thin Film Deposition Technology

Pulsed Plasma Deposition: a key enabling technology for thin film fabrication

Carlo Taliani
ISMN e
Organic Spintronics SrL

Presentation to IIT Milan _ june 2011

Outlook

Organic Spintronics and the PPD technology

PPD source improvements and evolution

Applications:

Transparent conducting oxides (TCO)

TCO at low T on PET and org. semicon.

Indium free TCO at low T

Hard coating

Oxides on HDPE for implants

Diamond Like Carbon (DLC)

Photovoltaics

CdTe/CdS , CIGS,

Buffer layers

CeOx, YSZ, ZrOx, TiOx,...

Ultra high k (barium strontium titanate - BST)

Carbides WC, SiC



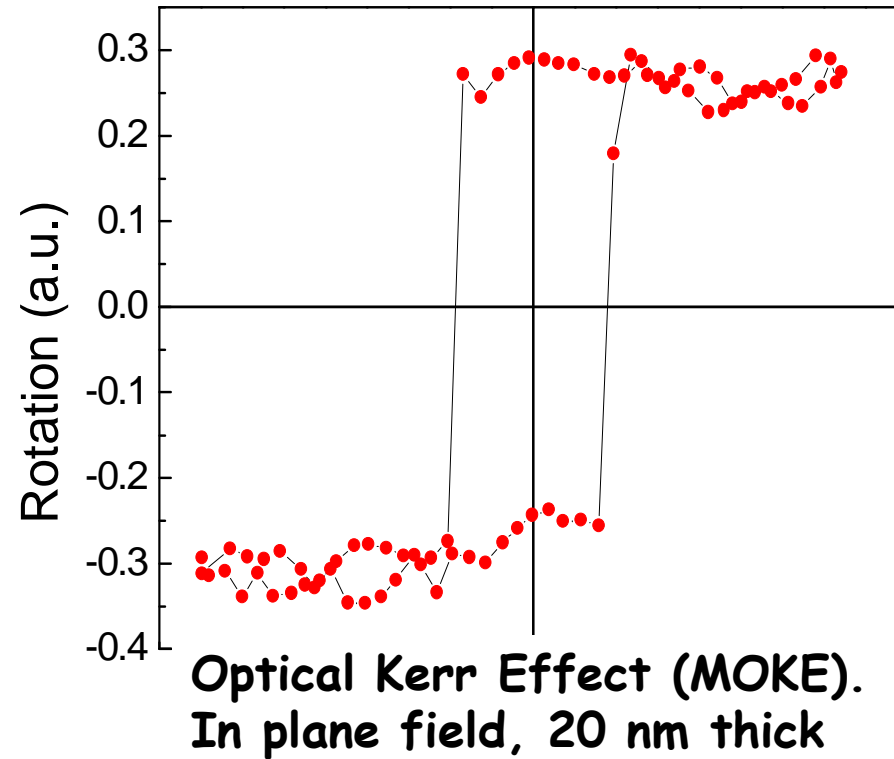
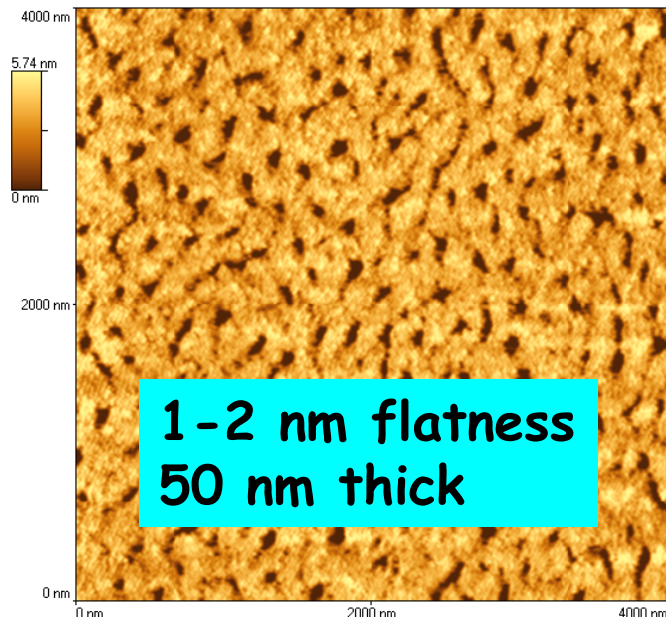
PPD: towards an industrial tool



2003: the origins

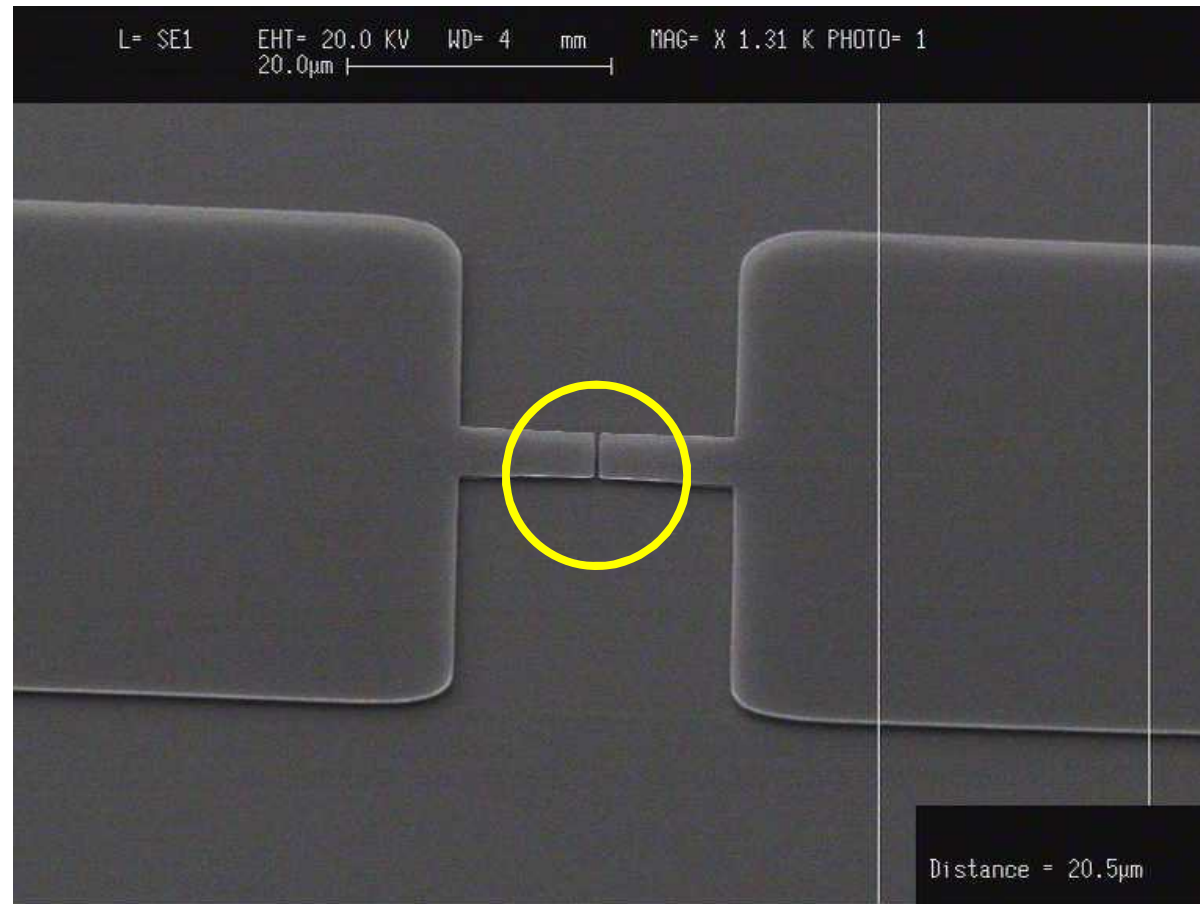
from research to business

$\text{La}_x \text{Sr}_{1-x} \text{MnO}_3$ films by PPD deposition on STO



V.A. Dediu, et. 2002

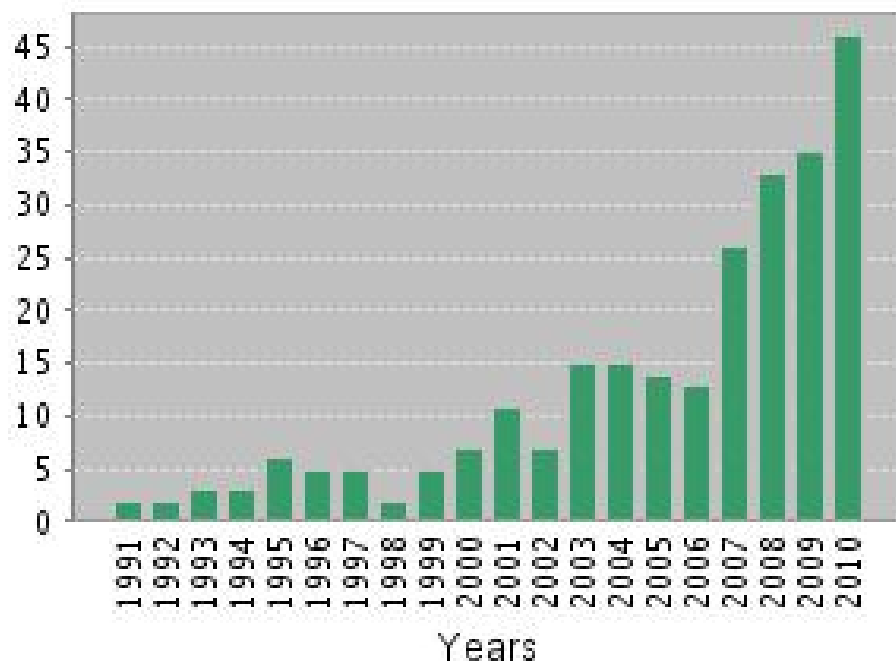
The first organic spin-valve



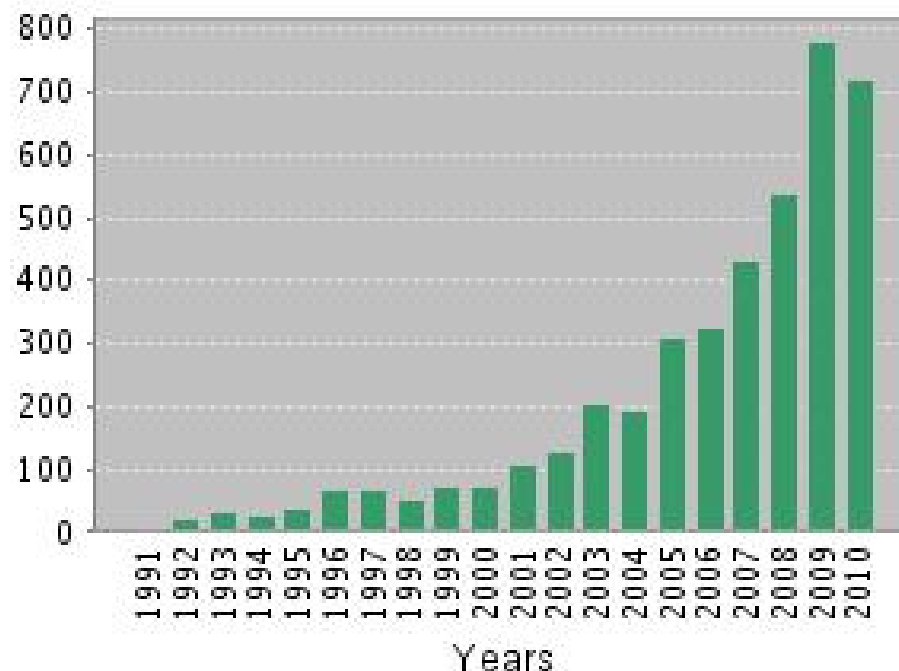
A new field emerged from this paper

Organic Spintronics: a new rapidly expanding scientific area

Published Items in Each Year



Citations in Each Year



SpinOS 2007

Workshop on Spintronic Effects in Organic Semiconductors
Bologna Italy 9 September - 11 September 2007

We are pleased to inform you of the Workshop on Spintronic Effects in Organic Semiconductors (**SpinOS 2007**) that will be held at the CNR Campus in Bologna from 9 to 11 September 2007.

The main scope of the **SpinOS 2007** Workshop is to bring together for the first time the international community of scientists working in Organic Spintronics.

The organizers hope to start an intense dialog in the community and to lay the foundations for future regular meetings in the field of both basic research and applications of spin injection and transport in organic semiconductors.

The Conference will include presentations on recent experimental and theoretical results on various spintronic effects in organic semiconductors.

For more details, please visit our website at <http://www.spinOS.org>

Conference chairman

C. Taliani, ISMN-CNR, Bologna

Scientific Advisory Committee (confirmed)

Martin Aeschlimann, Univ. Kaiserslautern
Sasha Alexandrov, Loughborough University
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Xin Sun, Fudan University
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Markus Wohlgenannt, University of Iowa

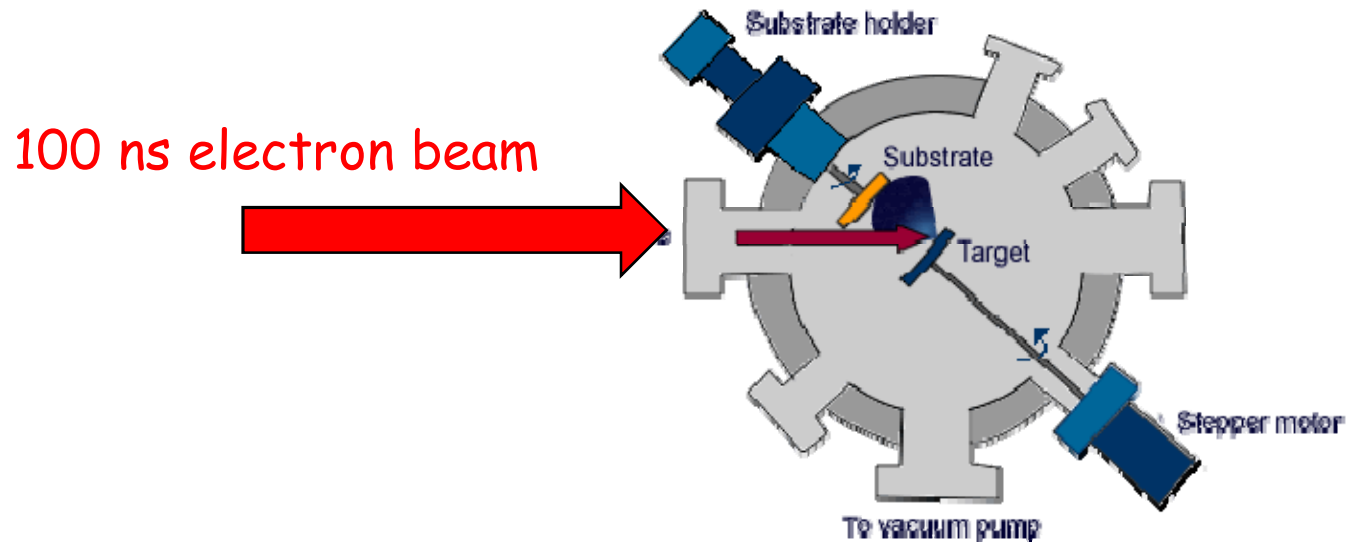
Program committee

V. Alek Dediu, ISMN-CNR, Bologna
Georg Schmidt, University of Würzburg

We look forward to seeing you at the conference



Pulsed Plasma Deposition by Ablation

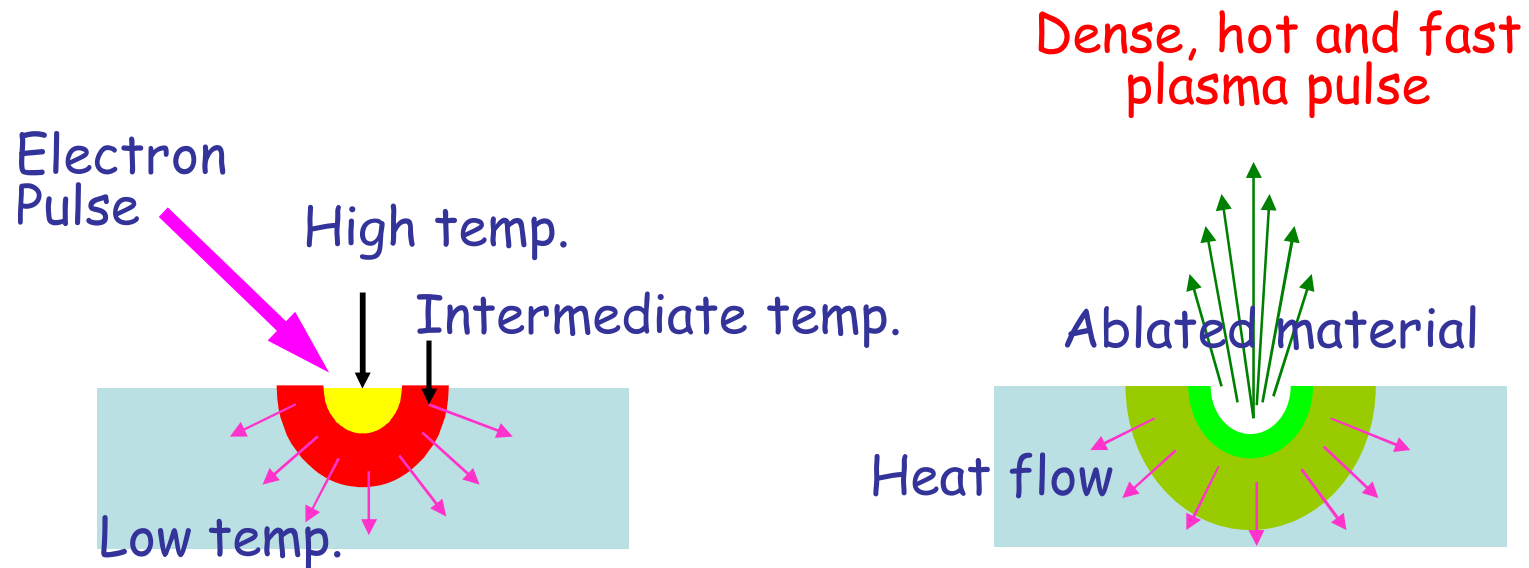


Deposition characteristics:

- Good **composition transfer**
- **Smooth** surface

The ablation process

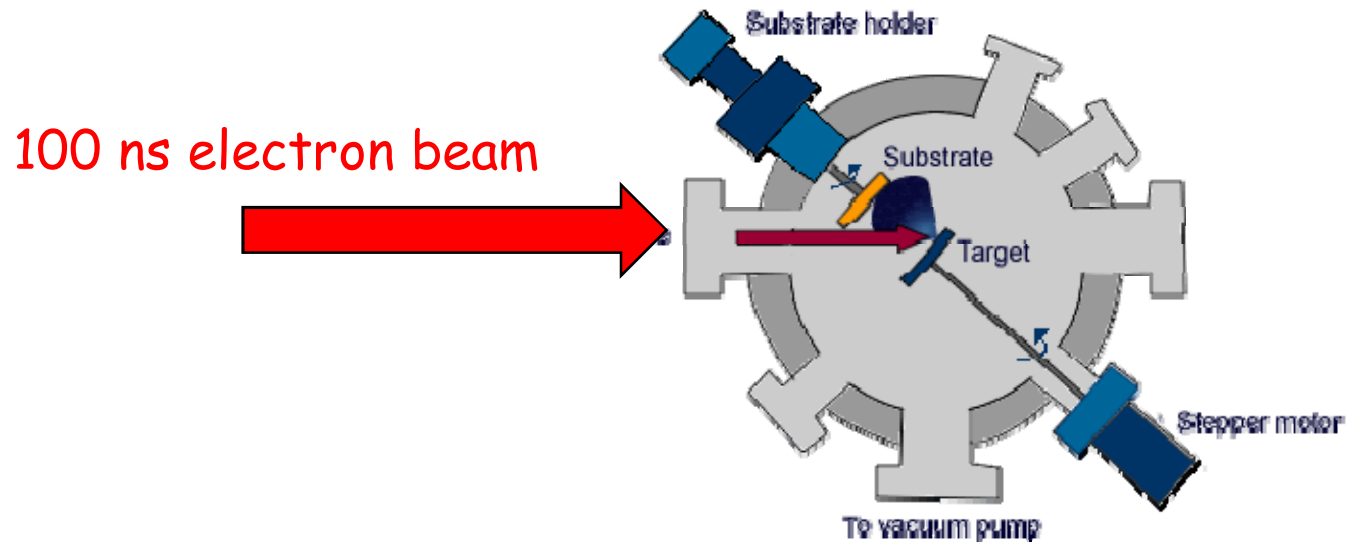
Ablation below the target surface ejects a fast, dense and fully ionized plasma normal to the surface forming a film on a substrate.



Composition of the substrate is **the same** of the target

Is a **scalable** process suitable for industrialization (contrary to Pulsed Laser Deposition)

Pulsed Plasma Deposition by Ablation



Deposition characteristics:

- Good **composition transfer**
- **Smooth** surface
- Good homogeneity
- As in the case of PLD

Advantages:

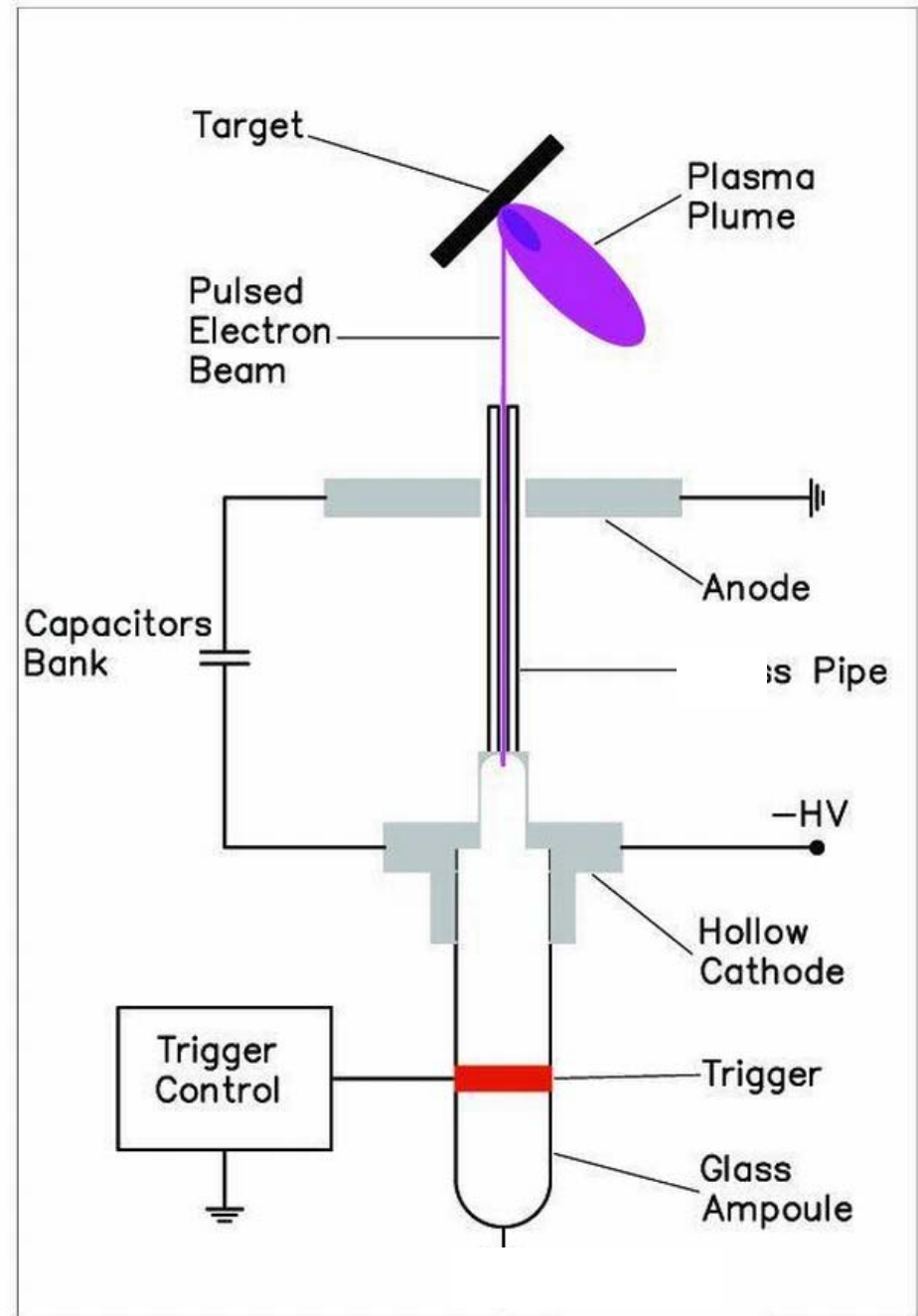
- **Low** equipment **cost**
- **Low** running **cost**
- **Scalable** for large area
- Suitable for **industrial** application

PPD ablation principle

Triggered discharge and acceleration from the hollow cathode to the anode generates a **focussed electron beam** that interacts with the target.

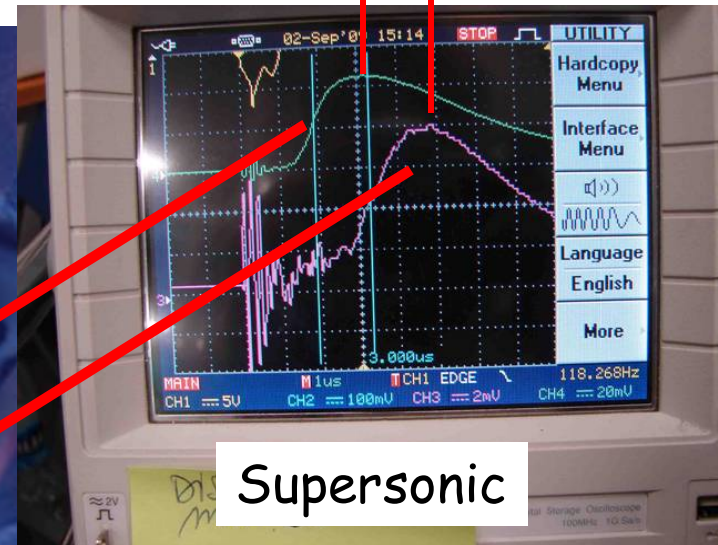
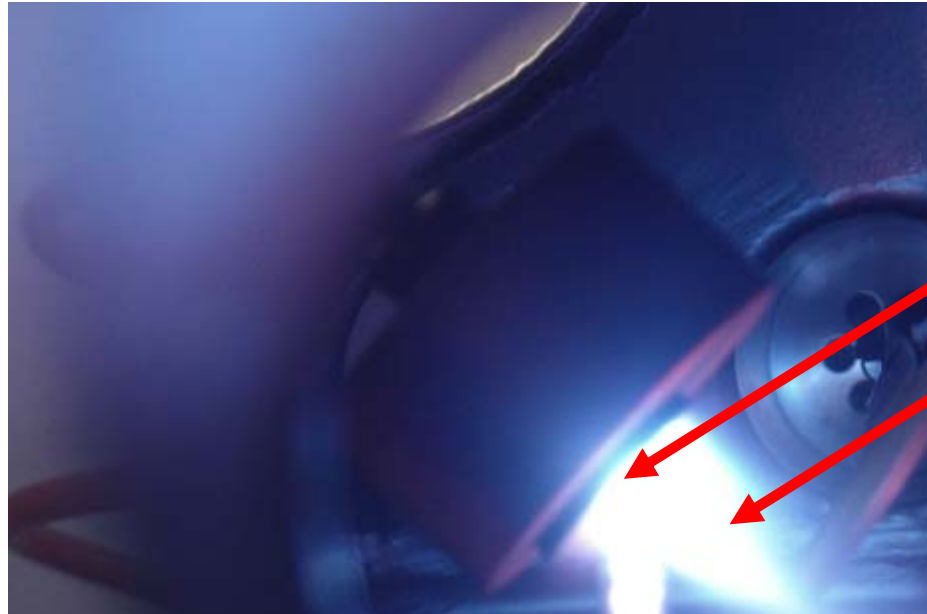
Target material explodes and is ejected forming a supersonic and dense plasma.

- Duration: 100 ns
- Max. energy: > 4J
- Beam size at target: 3 mm²
(and less by plasma focussing)

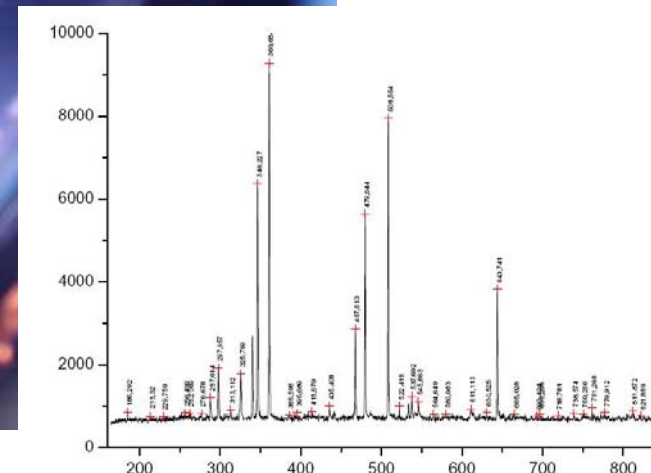
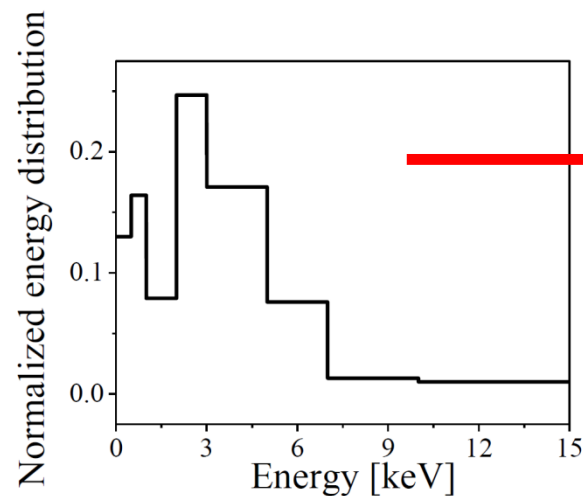


PPD keeps the target composition

25 mm = 5 Km/s



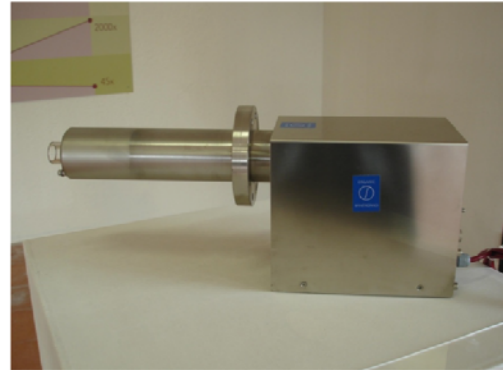
Supersonic



Dense Plasma

Electron Energy (J.A.P.,106,73301,(2009))

Evolution of PPD Guns: from GenI to Gen III



30 Hz, 2007

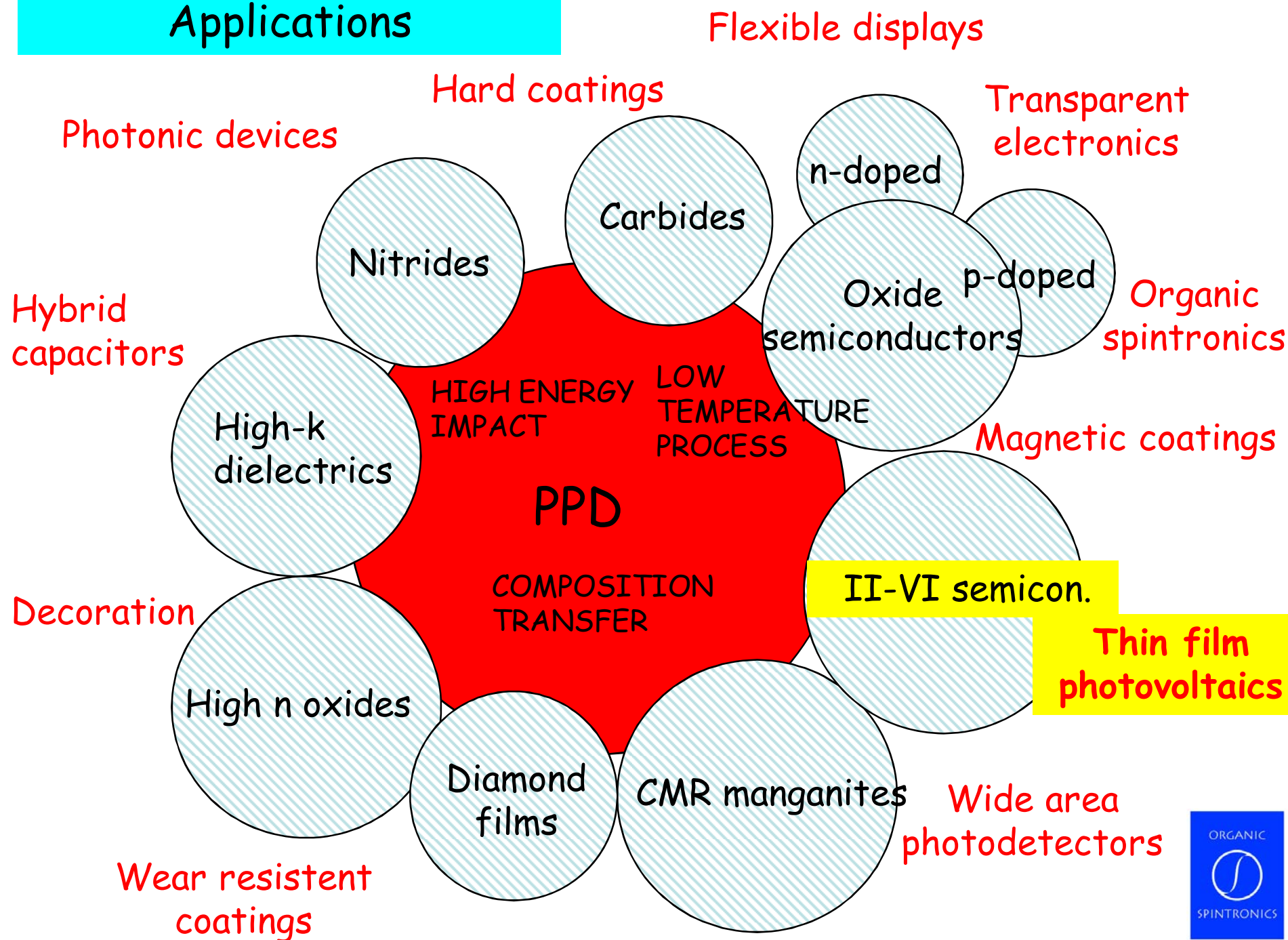


10 Hz, 2005



2 Hz, 2004

Applications



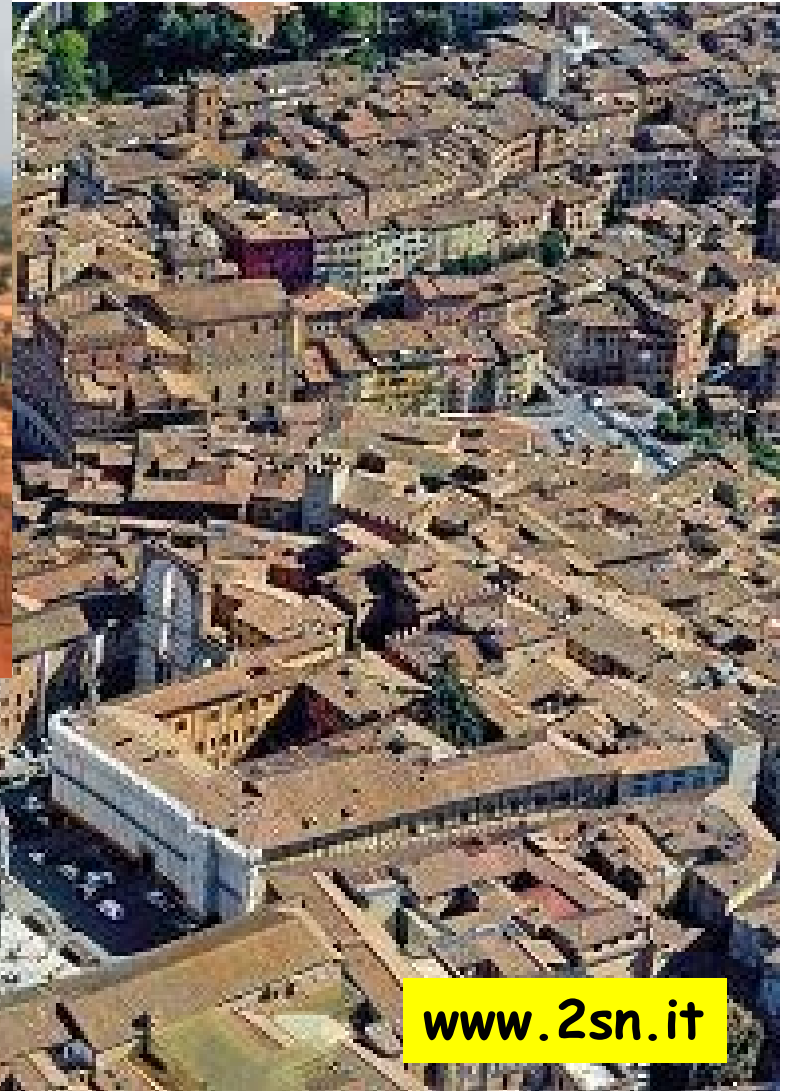
Chalcogenides
by the
PPD

2sn

**SIENA
SOLAR
NANOTECH**

A new deposition technology for
CdTe, CdS thin film PV

Carlo Taliani, President



www.2sn.it

2SN in brief

Siena Solar Nanotech (2SN) was born in 2007 as a **spin-off of Organic Spintronics**, a spin-off of the National Research Council of Italy (CNR). **2SN possesses the IP** of the process and the PPD technology for II-VI semiconductors

Vision: **getting grid parity** by depositing CdTe, CdS and TCO by a **new** thin film deposition technology.

Business:

- commercialize thin film deposition PPD equipments for CdTe, CdS and TCO
- integrate our PPD technology in traditional flat glass lines
- develop R2R thin film deposition equipments for flexible substrates

2SN SpA is undergoing to a second round of investment for the development of the 30 cm web pilot equipment

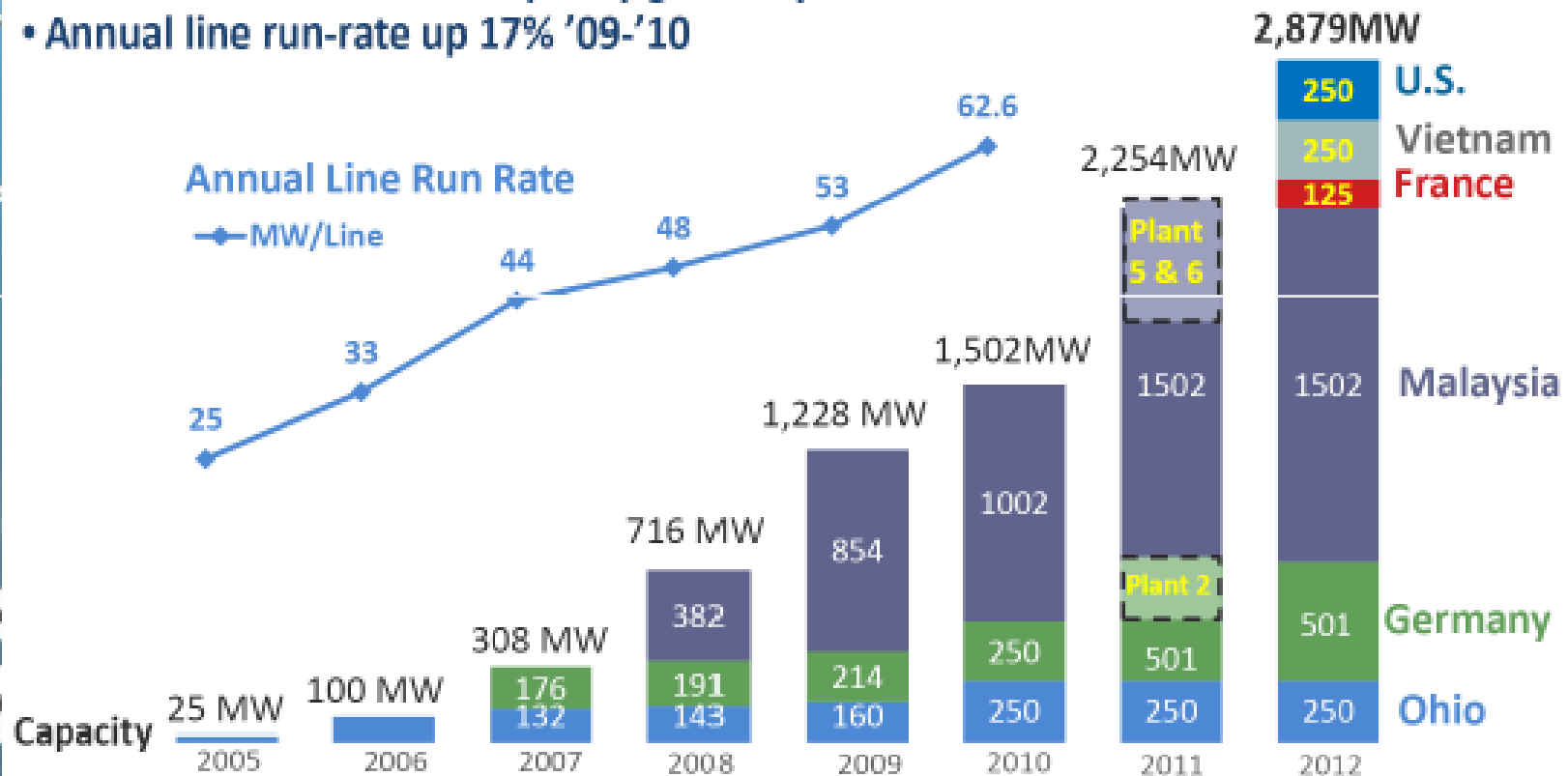


The CdTe champion

Production Capacity Growth (year-end)

New sites in U.S and Vietnam add 500 MWs

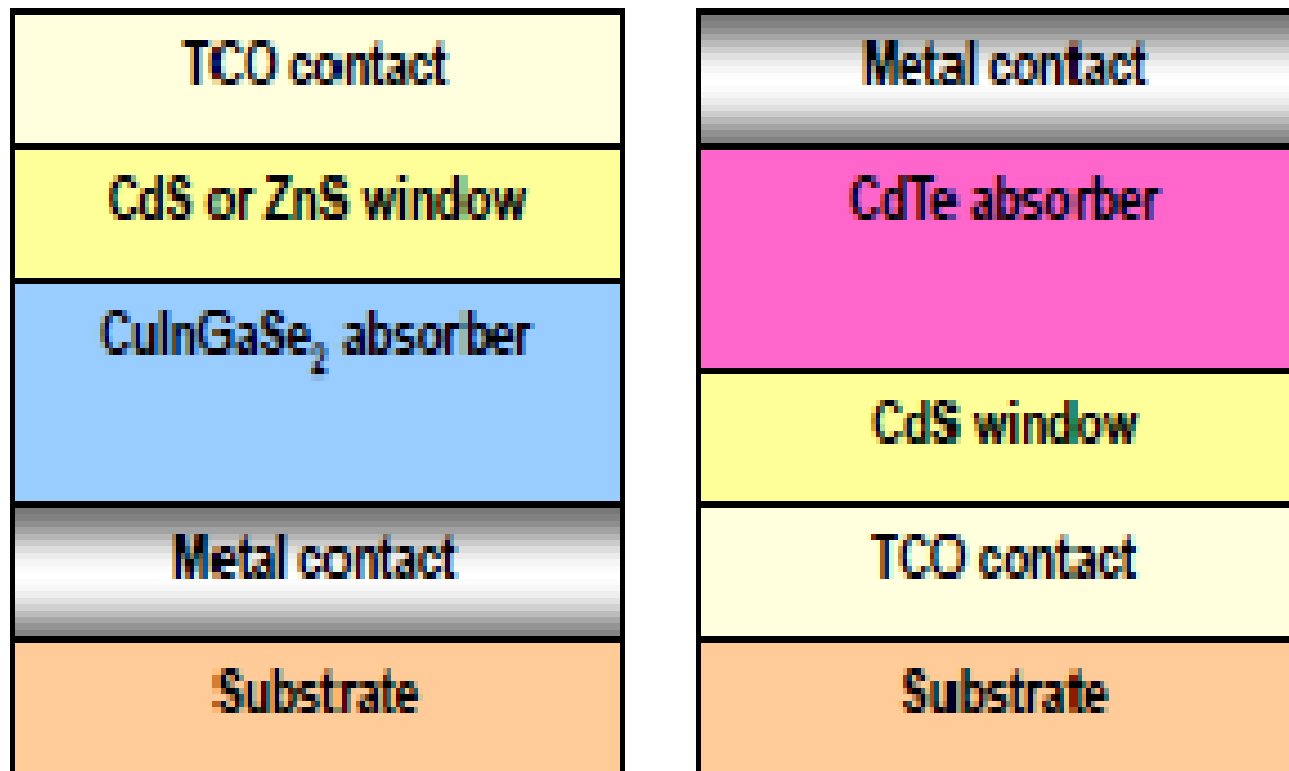
- Current and announced capacity grows by 1.4 GW or 92% to 2.9 GW
- Annual line run-rate up 17% '09-'10



© Copyright 2010, First Solar, Inc.

Representation of year-end capacity. 2005 & 2006 based on Q406 run rate; 2007 based on Q407 run rate; 2008 based on Q408 run rate; 2009 based on Q409 run rate, 2010-2012 based on Q4 2010 run-rate

CdTe vs CIS now Flat vs Flex



Cost reduction factors by the PPD

The PPD technology enables the achievement of grid parity by :

- Reducing material usage
- Increasing deposition rate
- Reducing the thermal budget
- Introducing a safe and sustainable fabrication process
- Improving efficiency
- Implementing a wide area scalable deposition system
- Implementing a Roll to Roll web deposition

Cost reduction parameters

The PPD technology enables the achievement of grid parity by :

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Thin film fabrication technologies

•Thermal

- Flash evaporation
- Vapour transport sublimation
- Electron gun evaporation
- Molecular beam epitaxy

•Sputtering

- DC sputtering (for metals)
- RF sputtering (for semiconductors)
- Reactive sputtering (for oxides,...)

•CVD

- mw, thermal, rf activated ...
- Plasma enhanced CVD
- etc

•PLD

- Nd YAG (IR), excimers lasers (UV)

•Species generated Energy (E)

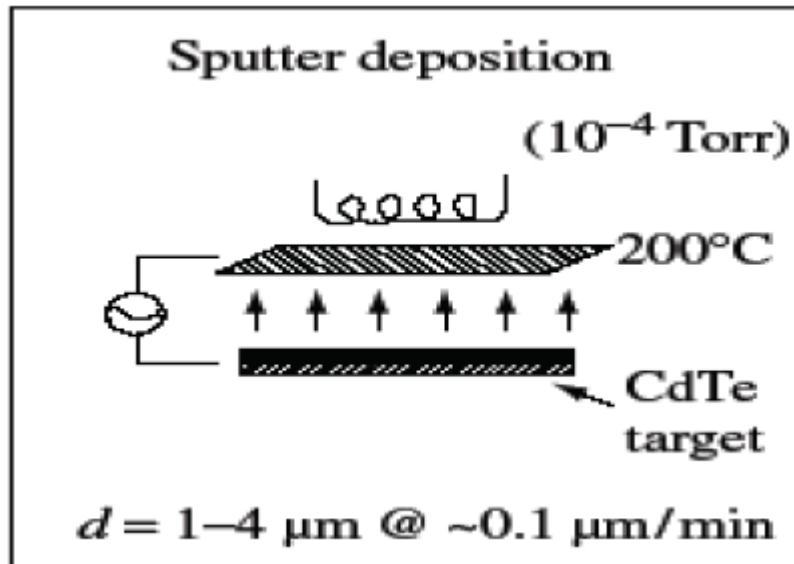
- neutral atoms
 - molecules
- Kinetic E at kT

- neutral atoms
 - ions
- Plus low electronic E (few eV)

- molecular fragments
 - ions
- Plus low electronic E (few eV)

- neutral atoms
 - ions
 - clusters
- Supersonic kin. E and large electronic E

CdTe Thin Film Growth Technologies: 2

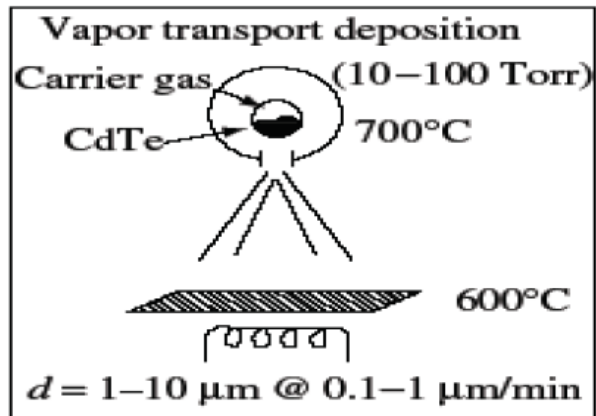


RF sputtering U. of Toledo

Problems:

- Slow
- Homogeneity (thickness)
- No industrial application

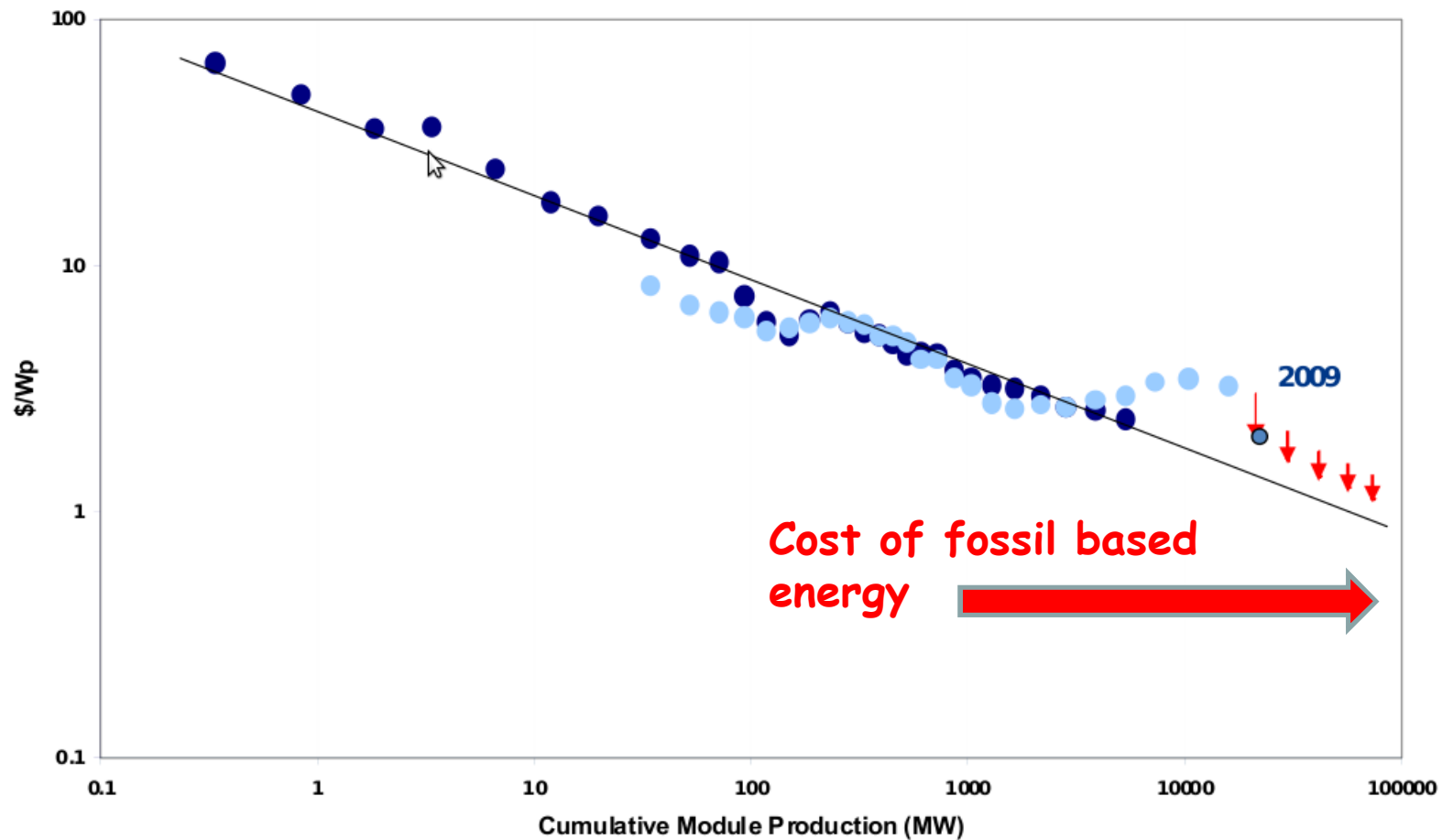
Present CdTe deposition technology by First Solar



- High roughness (thick)
- Hot gases (risky)
- High T (costly)

Source: Satyen. K. Debb (2005)

Our goal: grid parity by chalcogenide thin film photovoltaics



Photovoltaic production costs and sales prices vs time.
Source: Navigant Consulting

We aim at total costs lower than 0.5 €/Wp

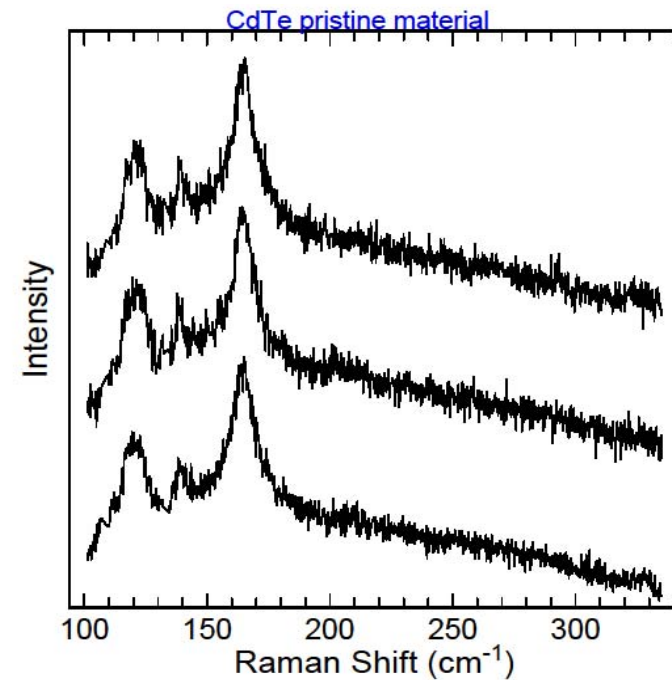
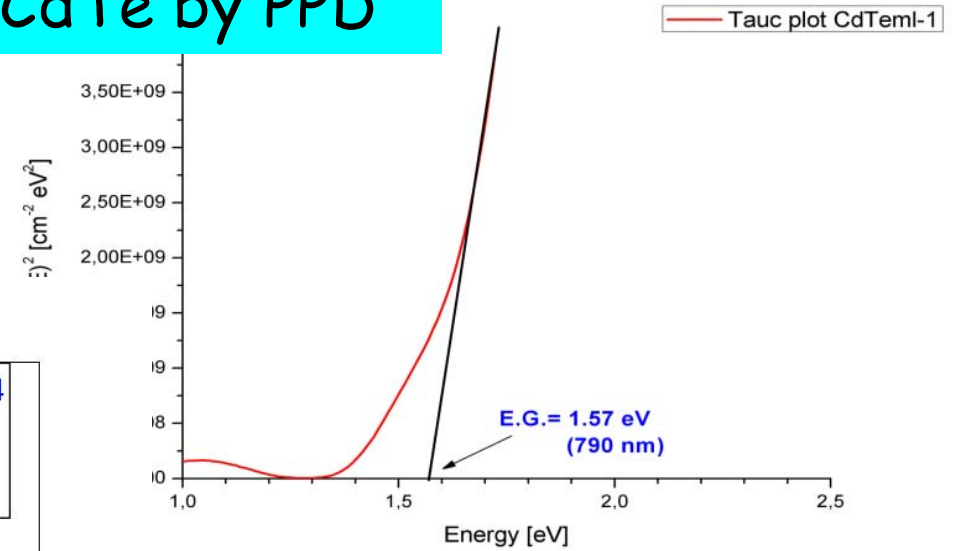
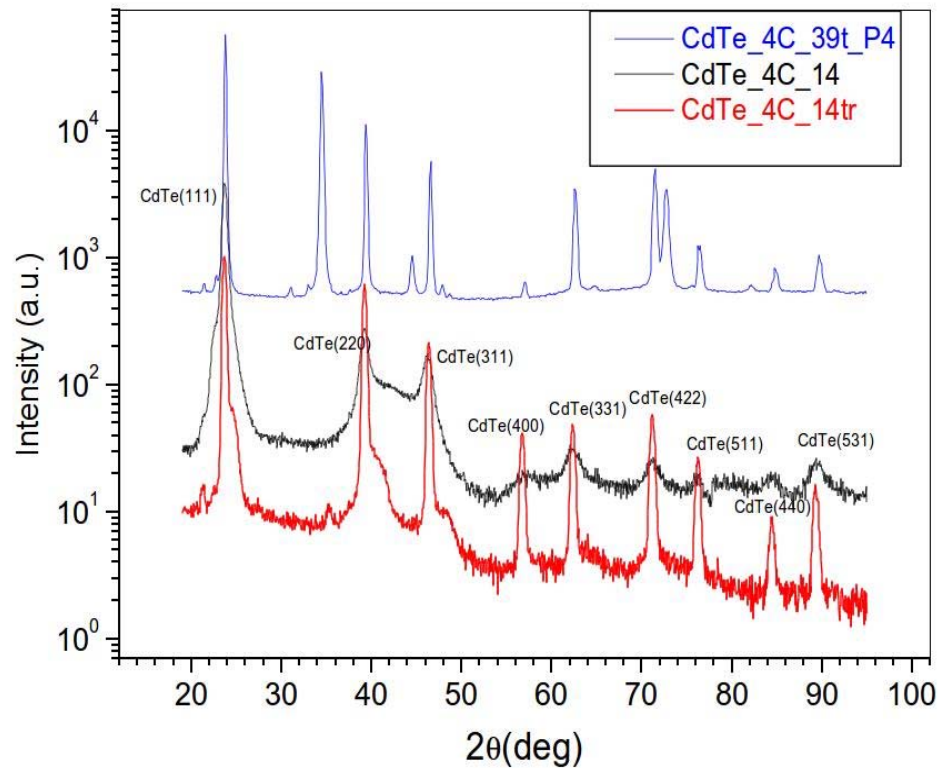
The nature of the challenge!

Technology is the **challenge**
Relevant issues are: **cost & cost**

- Reduce material (**reduce cost**)
- Increase deposition rate (**reduce cost**)
- Reduce thermal budget (**reduce cost**)
- Introduce a safer process (**reduce cost**)
- Improve efficiency (**reduce cost/W**)
- Implement in line productivity (**reduce cost**)
- Implement Roll 2 Roll (**reduce cost**)

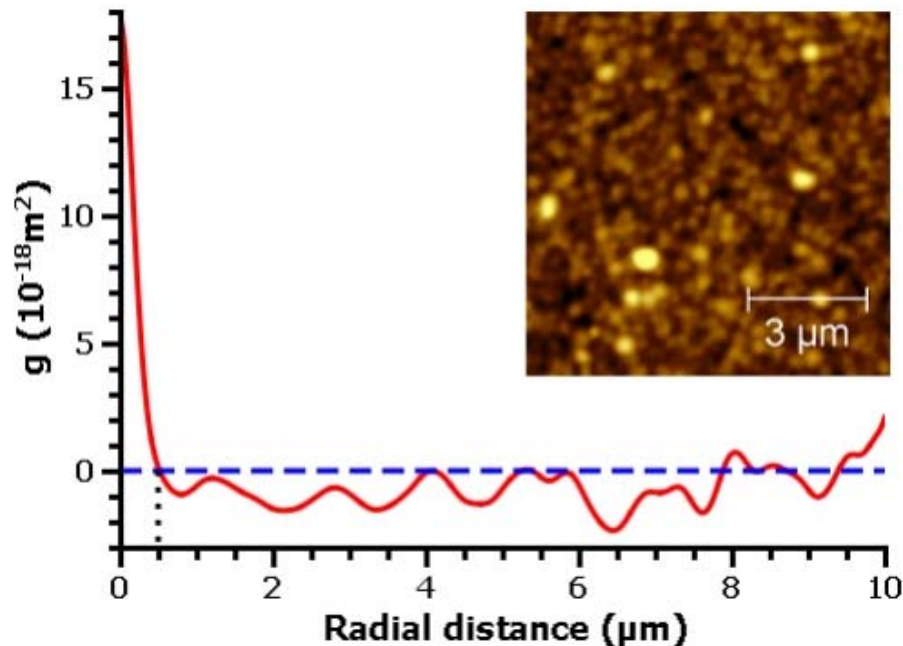
Pristine CdTe by PPD

optic geometry: PSA(θ , 2θ) for sample 39, GID for sample 14

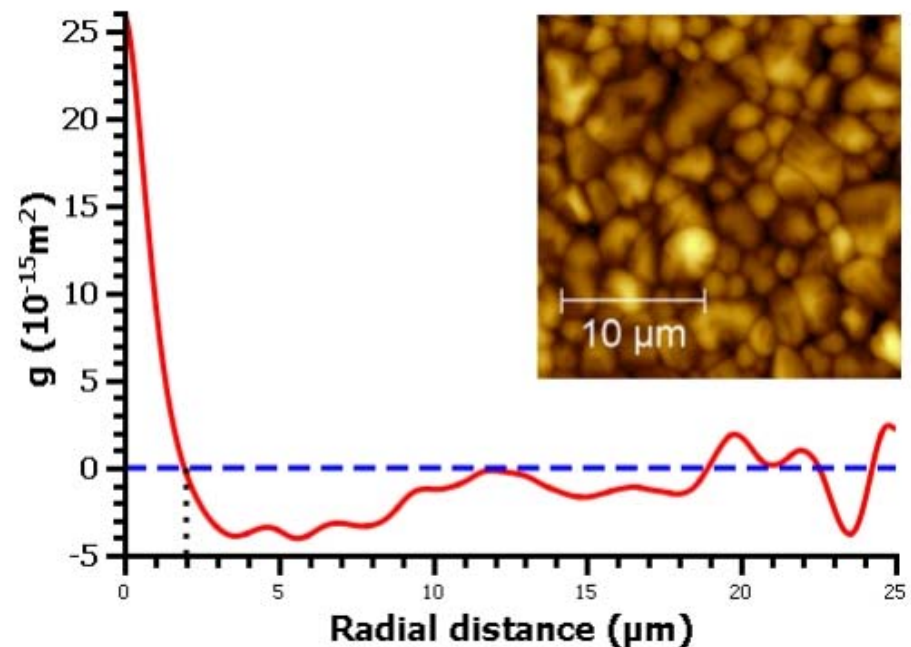


Reducing material usage

The PPD technology enables to make **very smooth** layers reducing the need to deposit **6-8 μm** as in the case of the present CSS and VTD technologies. **One μm is sufficient. 8 times less material**

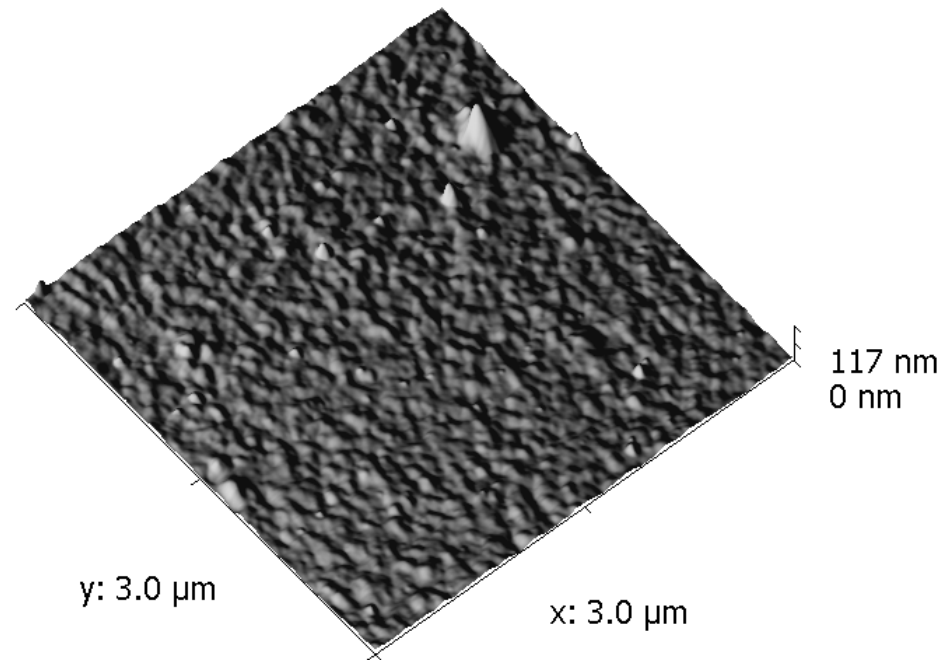
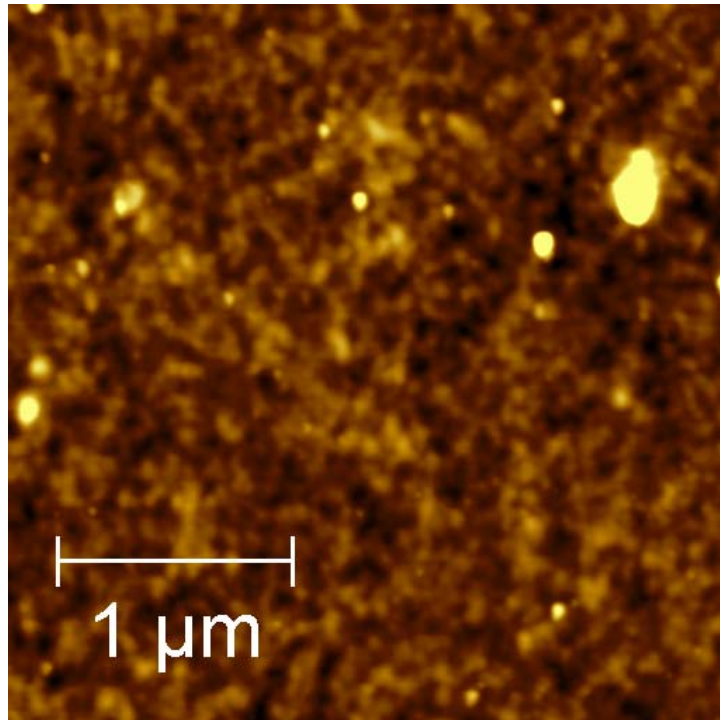


CdTe deposited at room temperature
Roughness **4 nm r.m.s** (AFM image).



CdTe treated with CdCl_2 at 420°C
Roughness 152 nm r.m.s
AFM image.

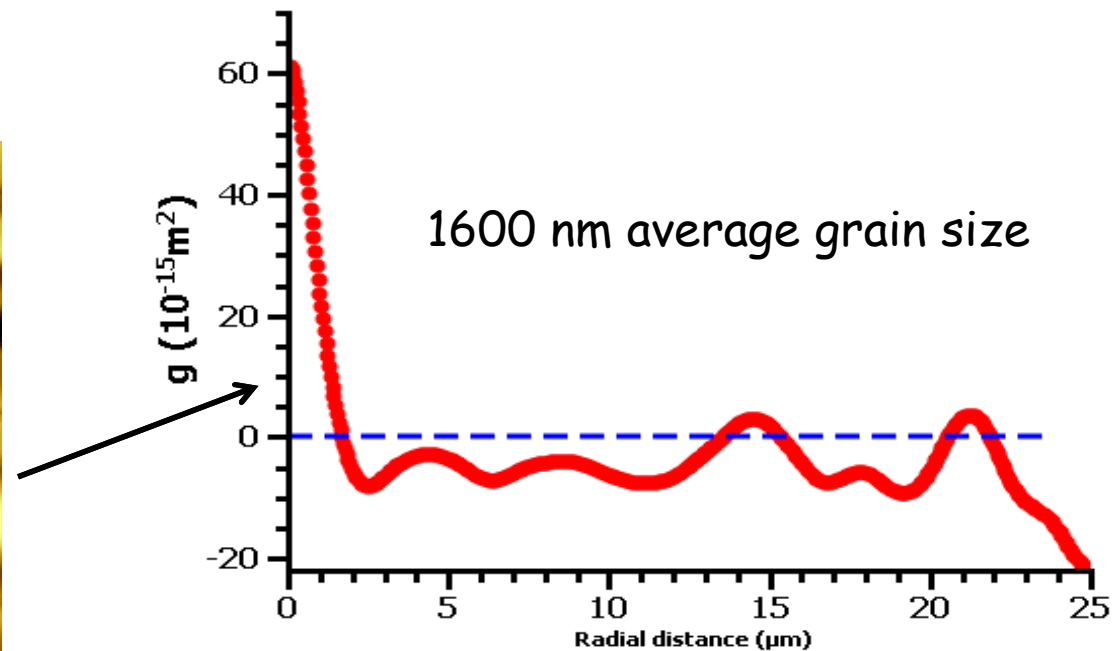
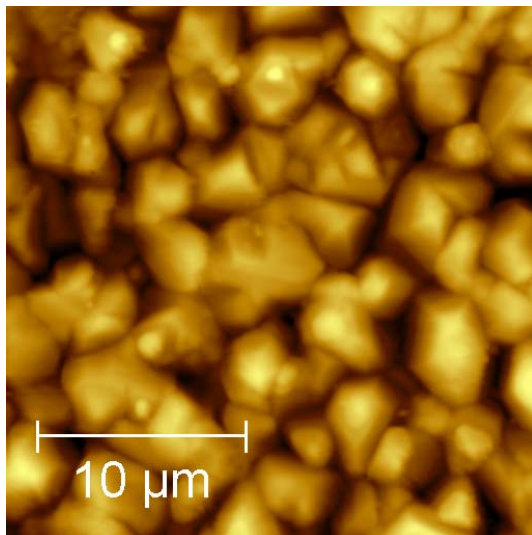
Reducing material usage



Cd S is also deposited at room temperature :
Roughness 4 nm r.m.s . AFM images

Reducing material usage: comparison with CSS

CdTe made by
traditional CSS

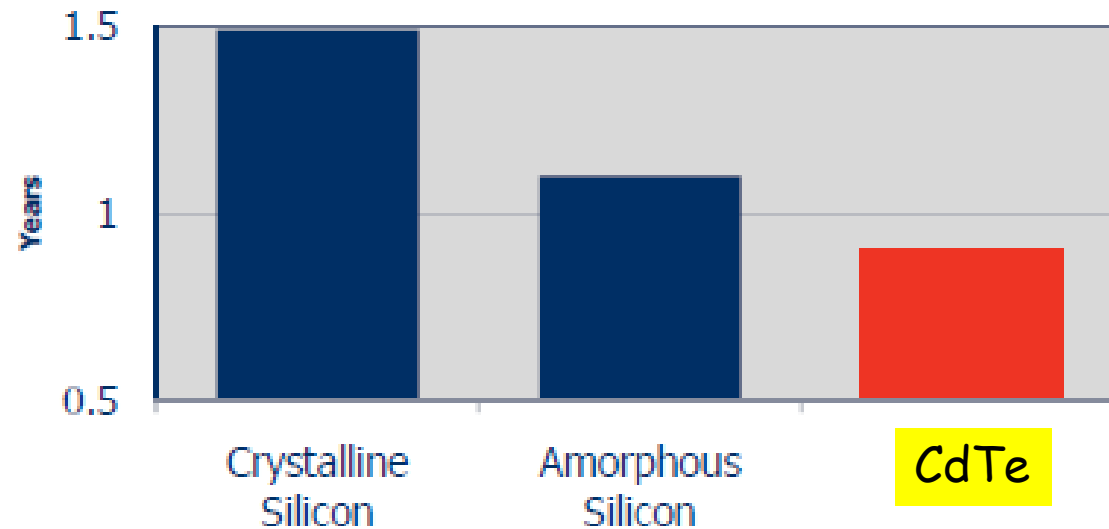


Roughness: 1093 ± 44 nm

PPD use less material and does not use gases

Reducing thermal budget

Energy Payback Time

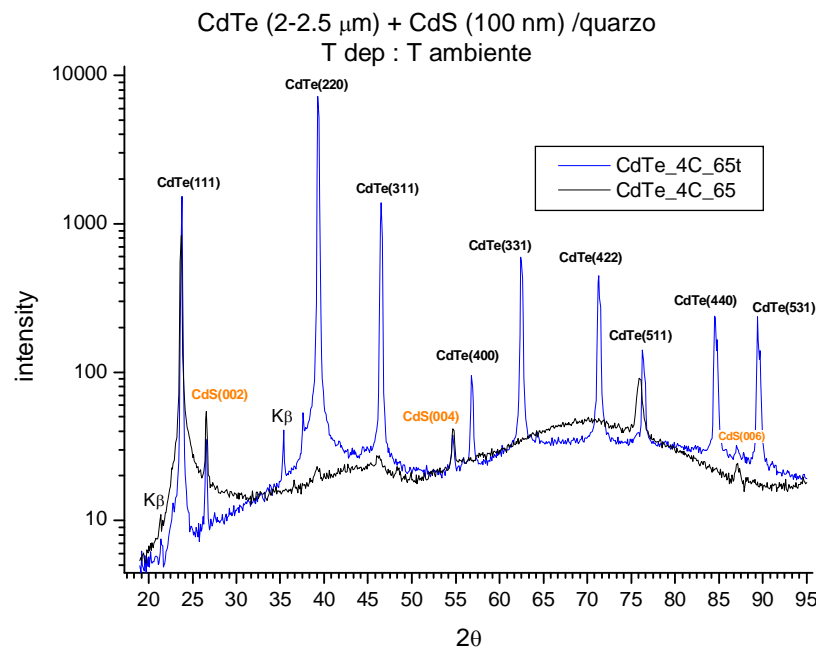


- Energy Payback Time (EPT): the time required for a module to generate the amount of energy spent in its production

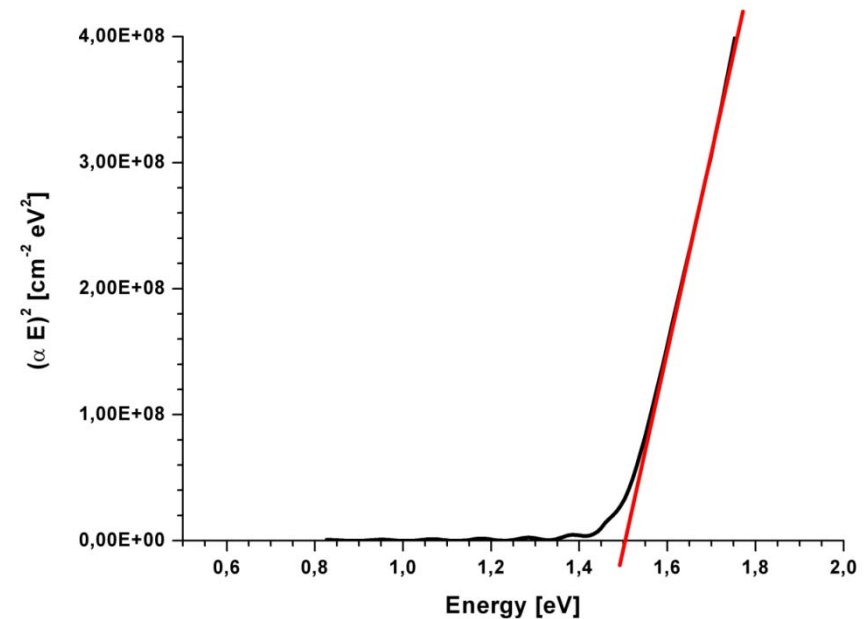
CdTe modules have a faster EPT than conventional silicon

Reducing thermal budget

The PPD technology enables the deposition of excellent quality and cristalline CdTe **at room temperature**



CdTe and CdS : X ray structures at Room temperature



CdTe energy gap

Increasing deposition rate

The PPD technology allow to reach dep. rates of 300- 400 nm/min. for CdS and 500 - 700 nm/min for CdTe.

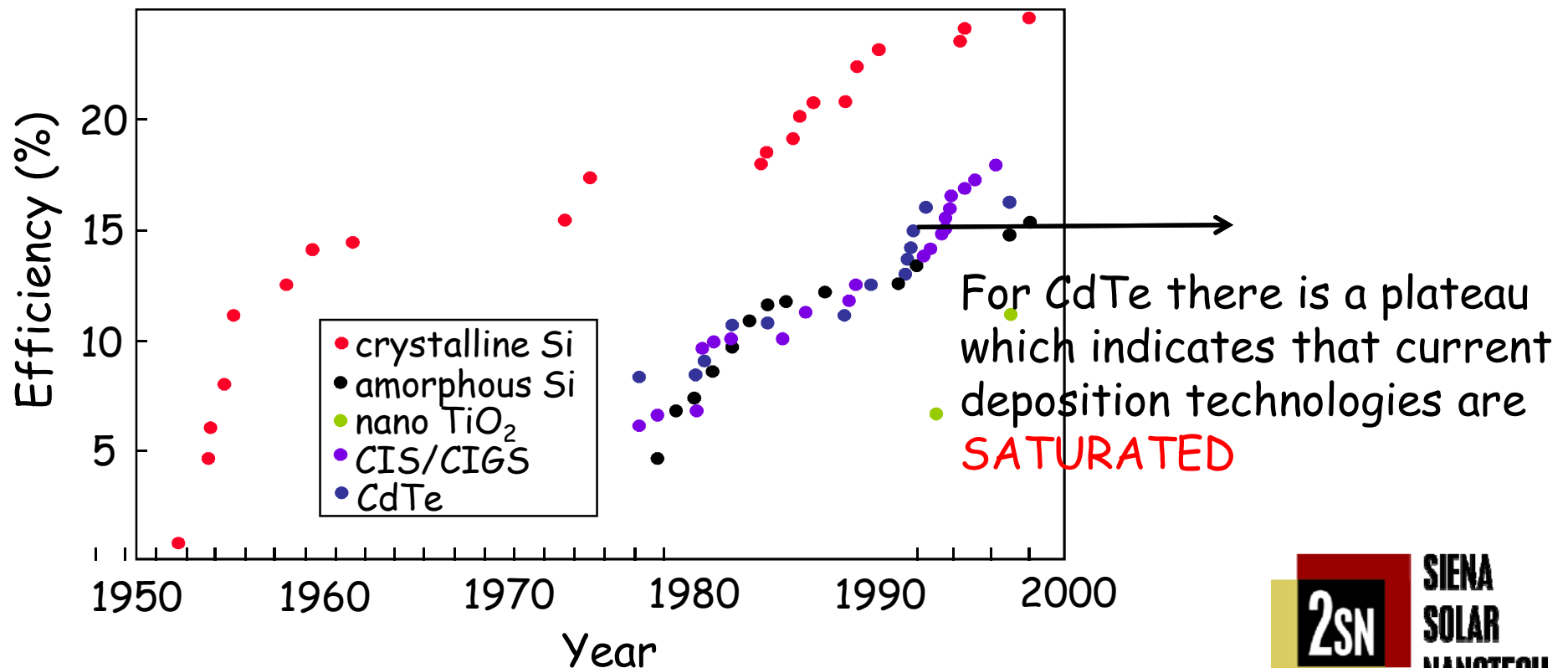
CdS	PPD	Sputtering	CBD	CSS
Deposition rate (nm/min)	300-400	50	3	100
Average grain size (nm)	20	50	12-15	5-80
Roughness (nm r.m.s.)	3		5 -120	
Temperature (°C)	RT	200	60 - 85	
Reference	Acharya 2007	Romeo 1998	Choi 98	Ferekides 1998

Ten times faster than conventional CBD and better smoothness

Improving efficiency

The **learning curve** concept involves the improvement of the quality of materials, processes etc.

Better CdTe and CdS, better interfaces, lower absorption losses, allow to follow the learning curve.

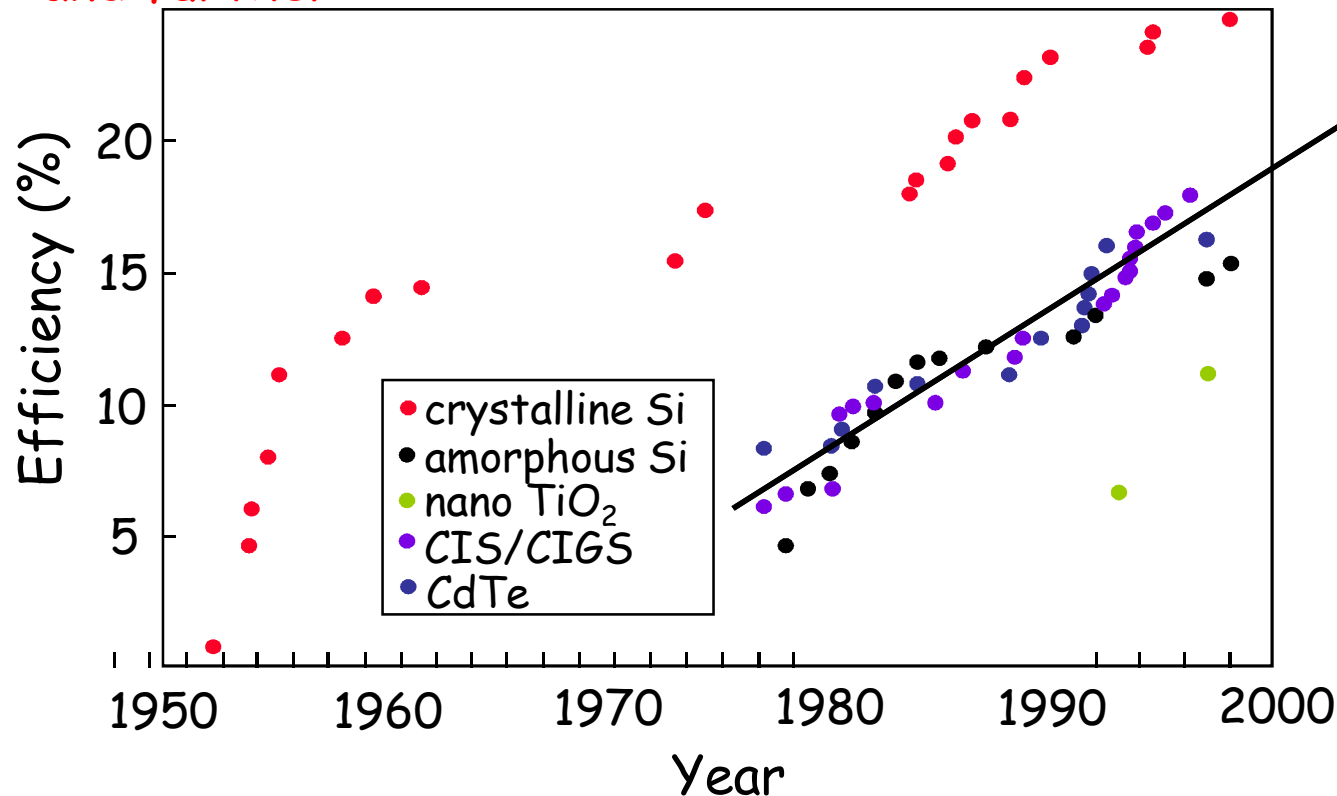


Improving efficiency

The **learning curve** concept involves the improvement of the quality of materials, processes etc.

Better CdTe and CdS, better interfaces, lower absorption losses, allow to follow the learning curve.

The PPD technology enables to explore the learning curve further and further



Safe processing

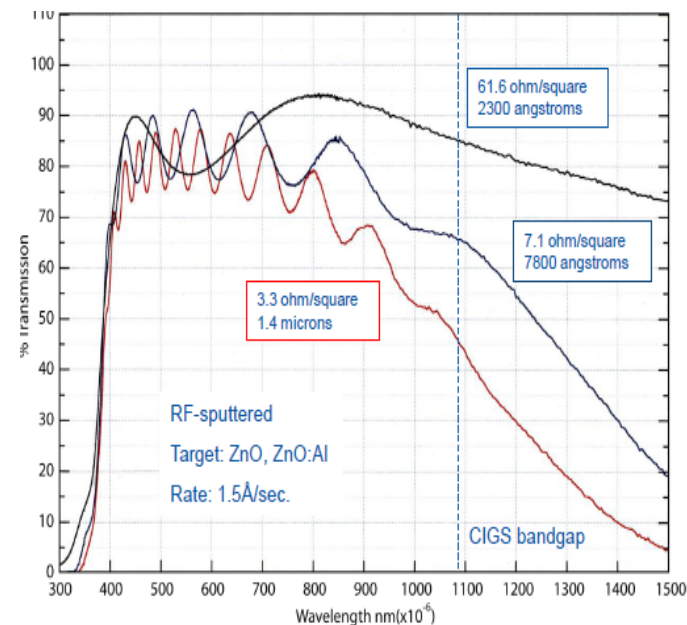
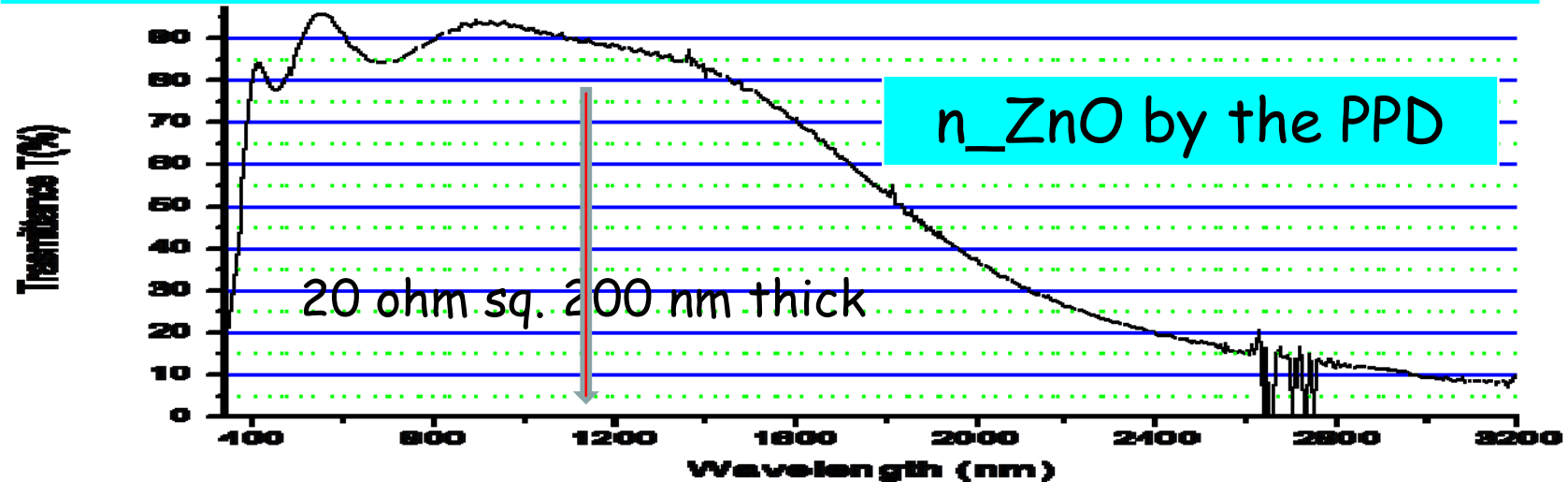
Insoluble high melting point CdTe is transferred to the substrate in vacuum.

- No exposure to Cd vapour
- No processing gases
- Low temperature process
- Confined environment in vacuum

Transparent Conducting Oxides by the PPD

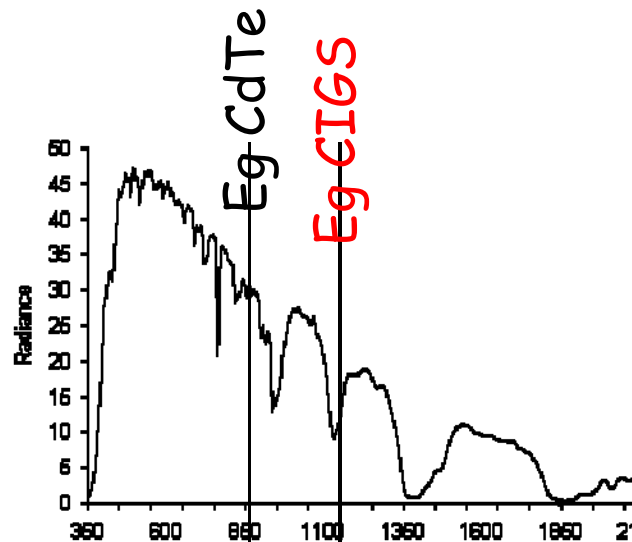
Improving efficiency

Excellent near IR T% at Eg CdTe and CIGS

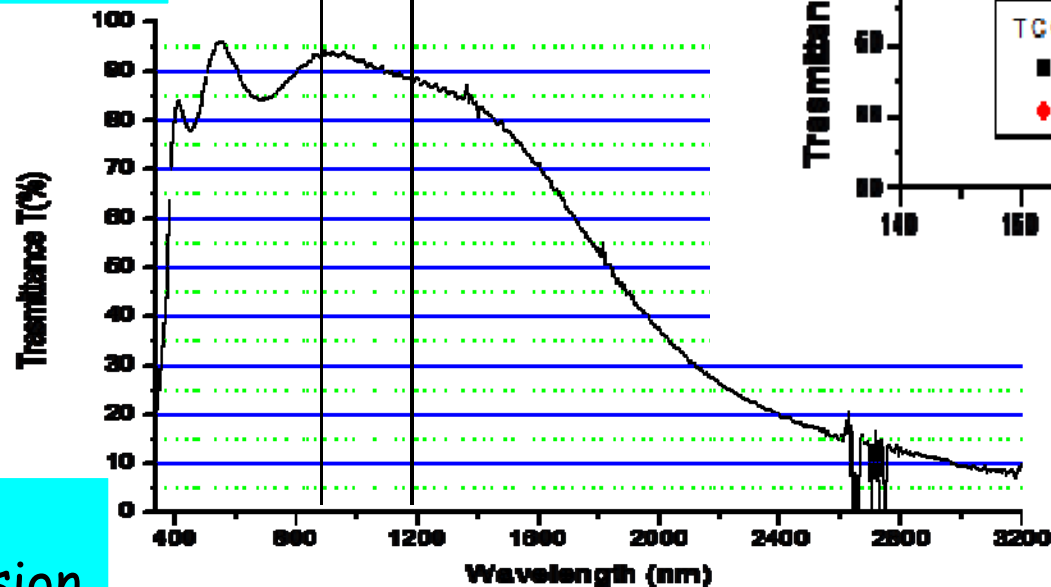


Al_ZnO by sputtering
(commercial)

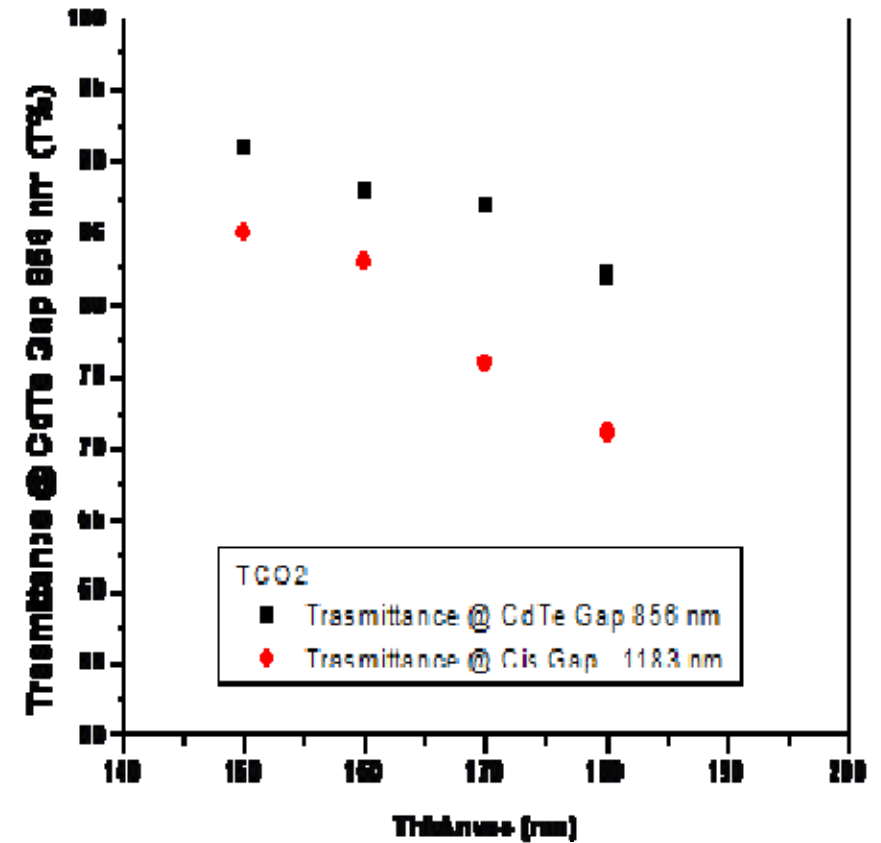
Improving efficiency: lower abs. loses



Solar emission



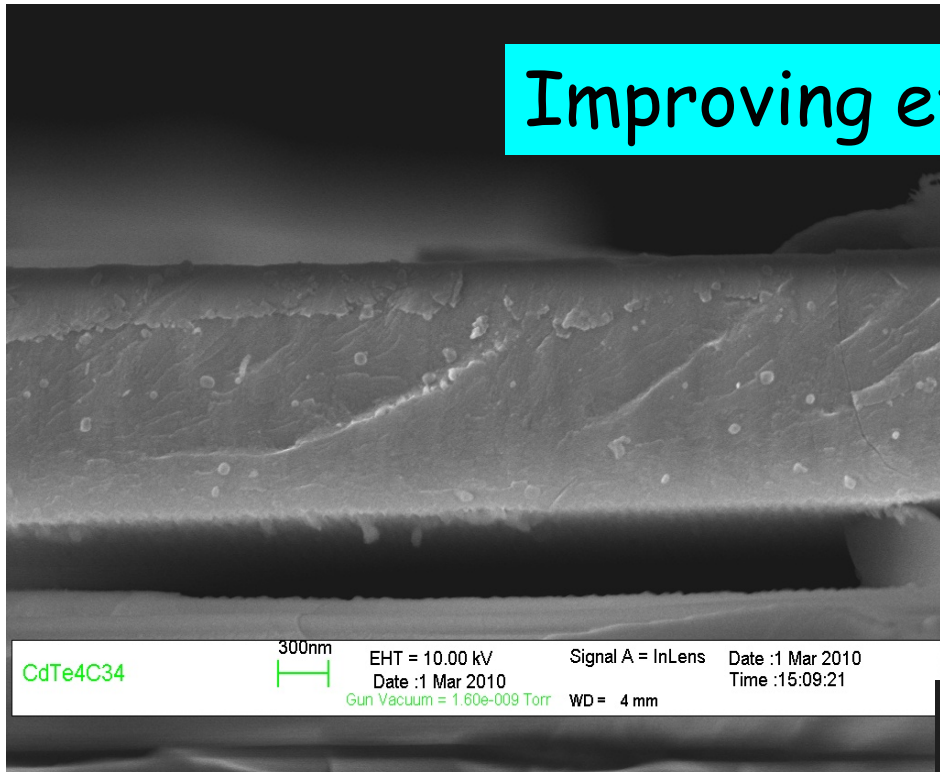
TCO2
transmission



Improving efficiency

Compact high density
pristine CdTe (density equal
to crystalline bulk)

CdTe4C34



300nm

EHT = 10.00 kV
Date :1 Mar 2010
Gun Vacuum = 1.60e-009 Torr

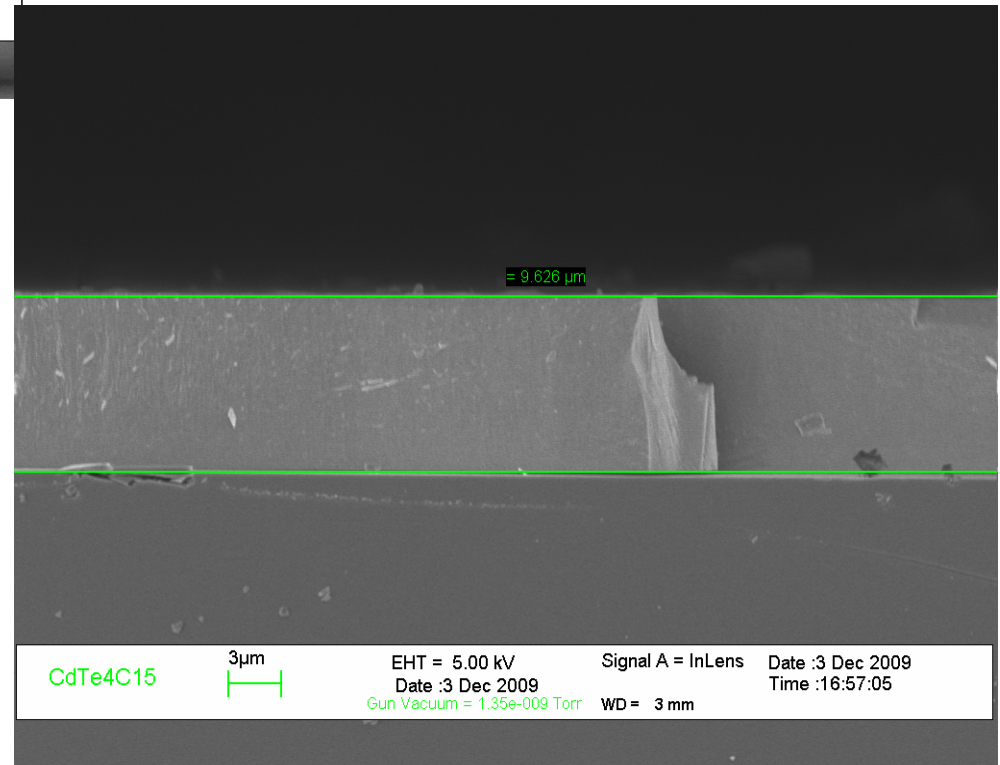
Signal A = InLens
WD = 4 mm
Date :1 Mar 2010
Time :15:09:21

This SEM image shows a cross-section of a CdTe4C34 film. The film appears as a dark, textured layer on a lighter substrate. A scale bar indicates 300 nm.

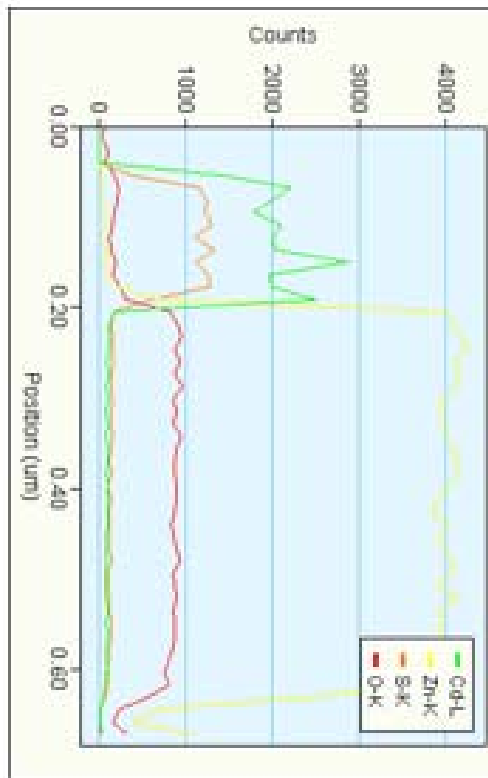
Equally possible to deposit
on glass or metal (flexible)
substrates

i.e.

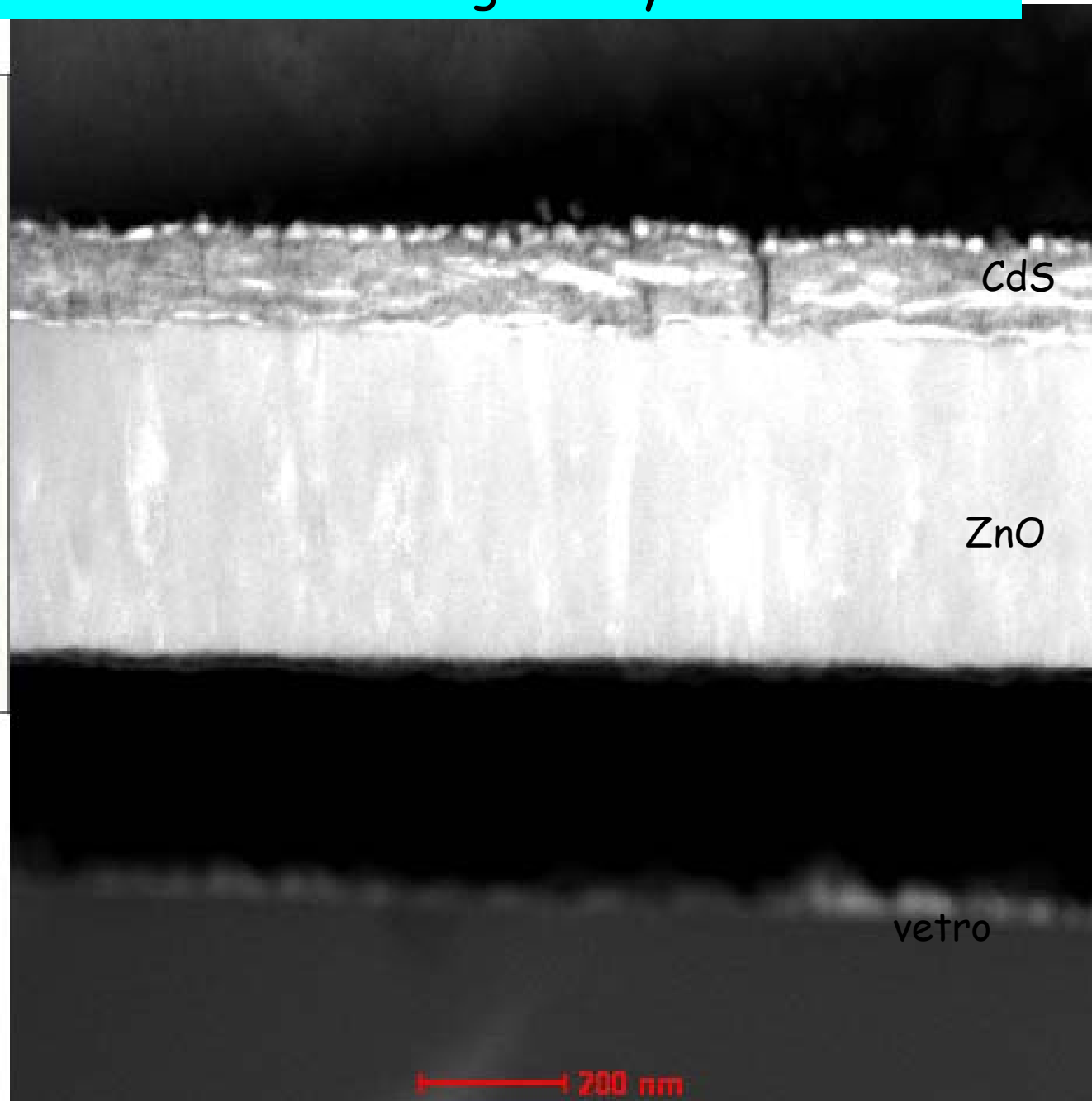
substrate or superstrate



TEM Pristine CdS on ZnO/glass by the PPD



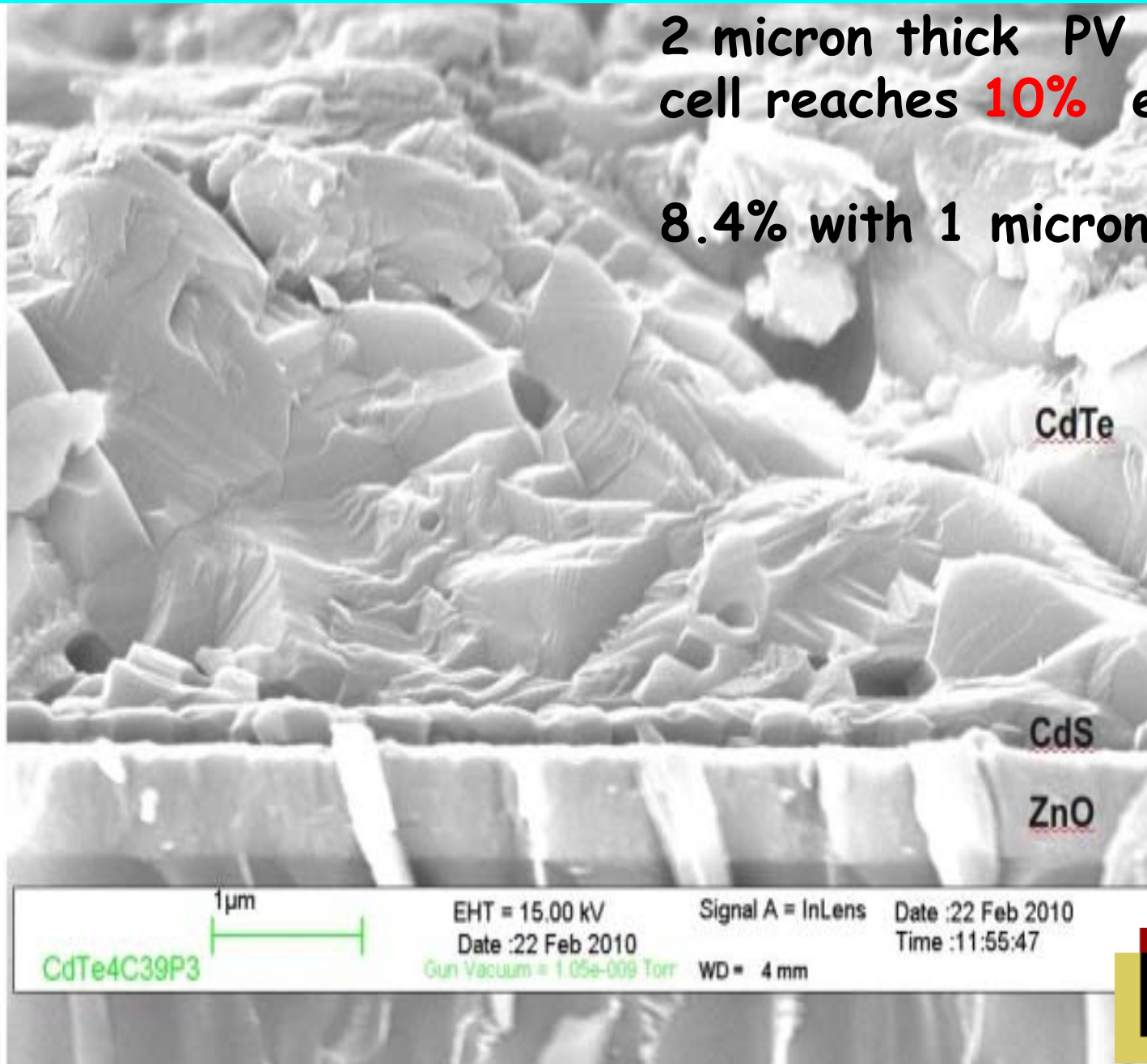
No intermixing of
ZnO and CdS



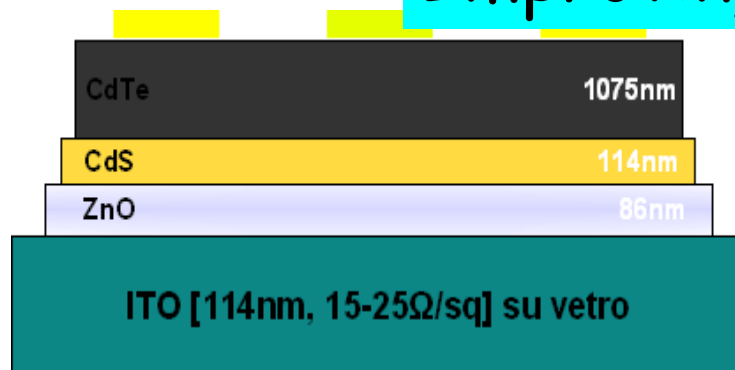
n-ZnO / CdS / CdTe for thin film photovoltaics: fully PPD

2 micron thick PV
cell reaches **10%** efficiency

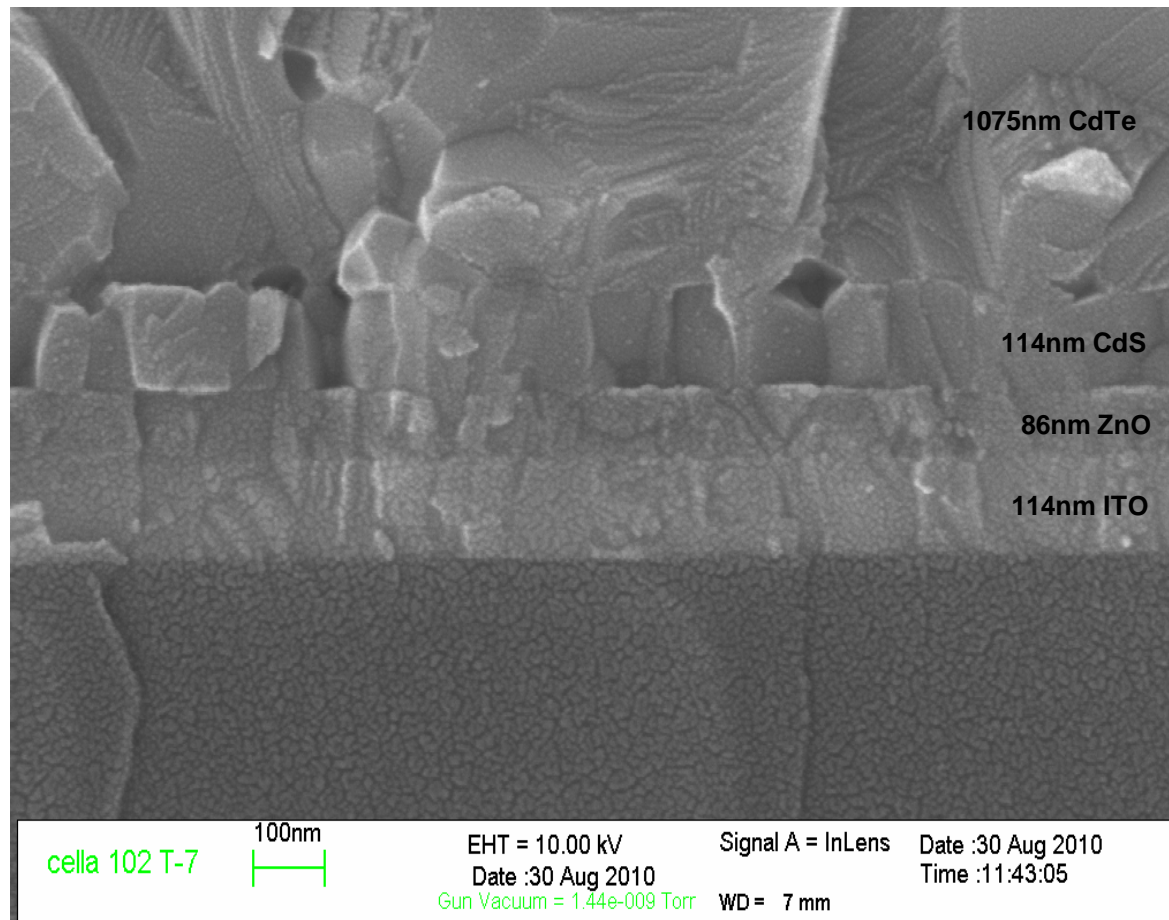
8.4% with 1 micron thick.



Improving efficiency



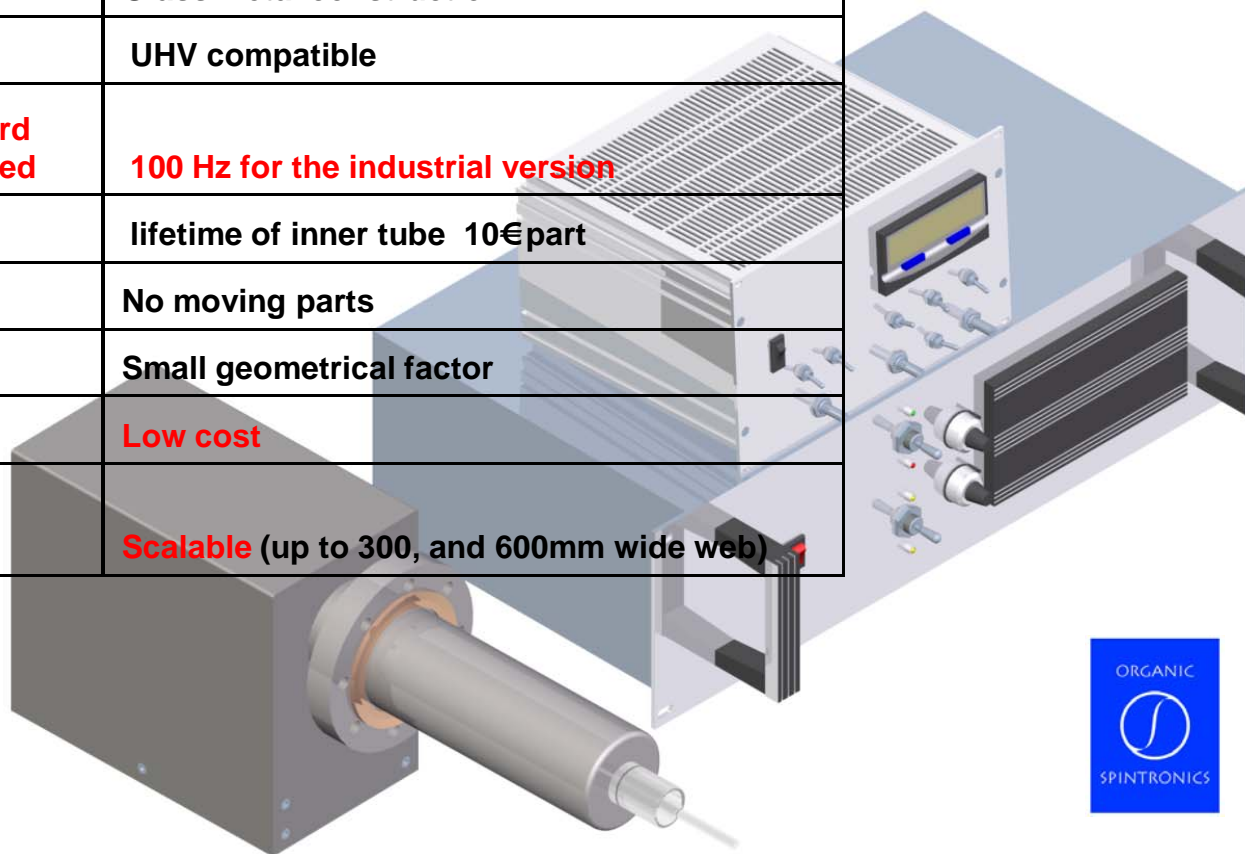
1 micron thick rudimentary PV cell reaches 8.4% efficiency.



PPD technology at OS

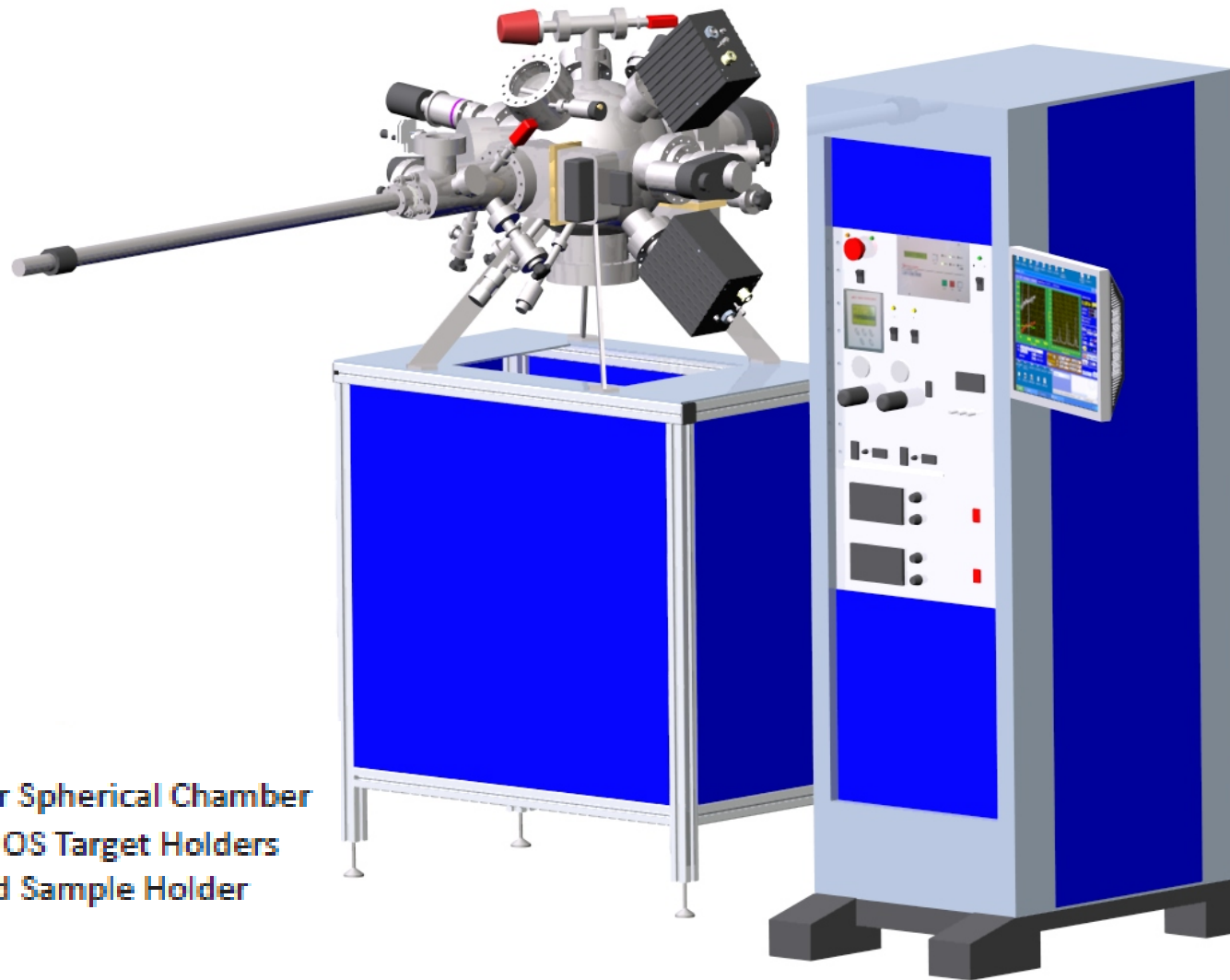
PPD Gen III Gun

Characteristics		Remarks
Deposition rate	50 – 700 nm/min	- depending on target material - one to two orders of magnitude higher than sputtering
Efficiency	> 30%	Power transferred from discharge to electrons
Bakeable	200°C	Glass metal construction
Mounting	CF 63 UHV	UHV compatible
Repetition rate	15 Hz standard 30 Hz advanced	100 Hz for the industrial version
Lifetime	>10 ⁹ shots	lifetime of inner tube 10€part
Rugged		No moving parts
Compact		Small geometrical factor
maintenance		Low cost
suitable to arrange in a serie		Scalable (up to 300, and 600mm wide web)



PPD Gen III Twin Spark System

PPD systems



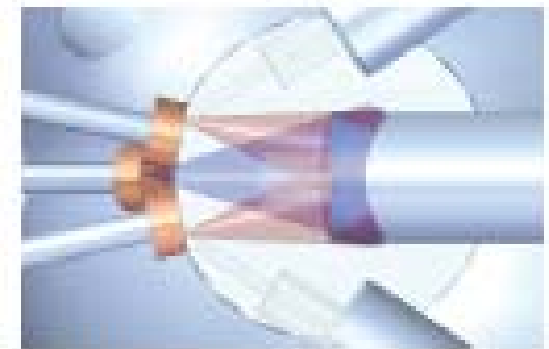
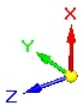
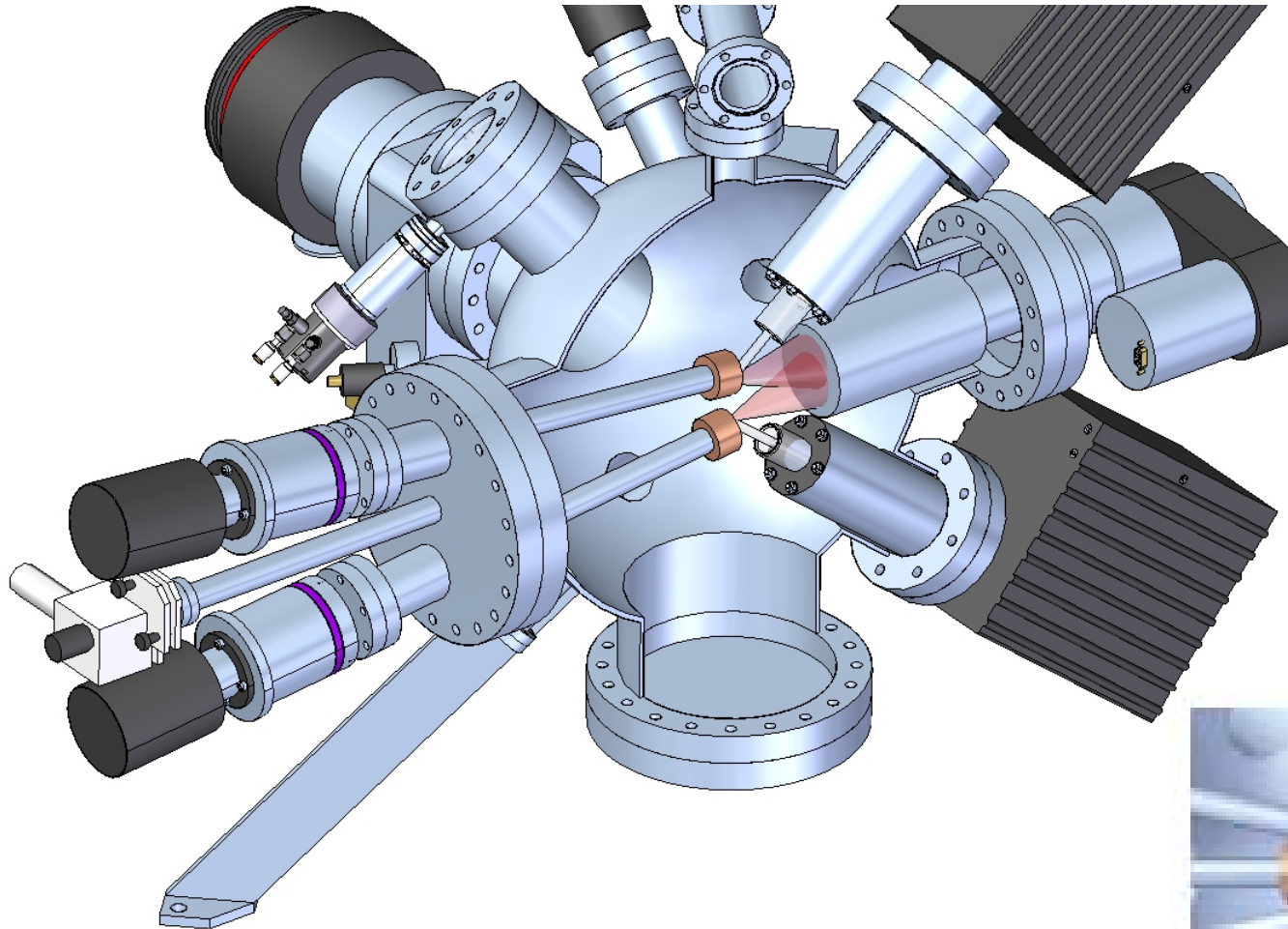
System including:

- UHV 350 mm diameter Spherical Chamber
- Up to 3 PPD Guns and OS Target Holders
- 2" diameter OS Heated Sample Holder
- Control Unit

Next: computer controlled growth (thickness and plasma composition)

Adding plumes to achieve wider areas

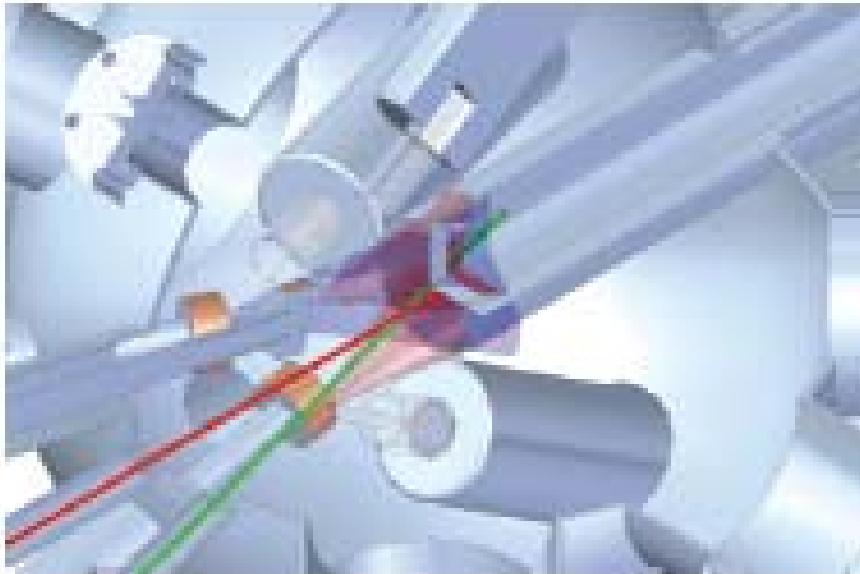
PPD systems



Wide area deposition
configuration

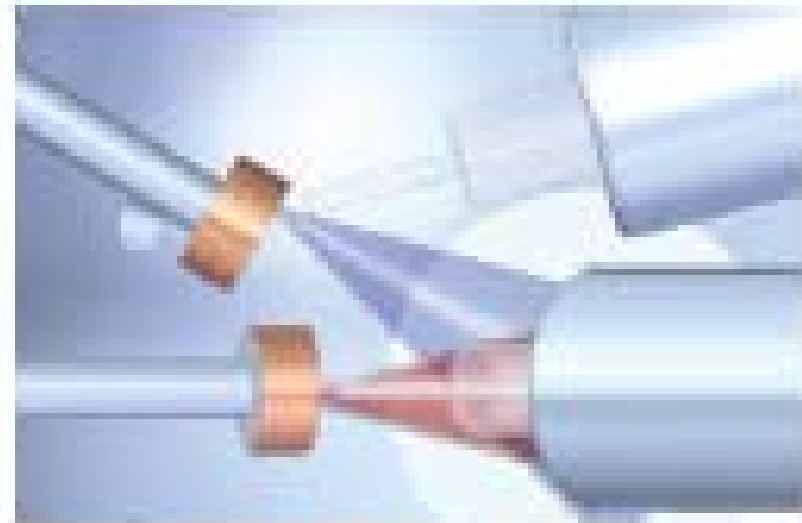
Mixing plumes: towards unconventional doping

PPD systems



Three PPD Gun III guns mounted for:

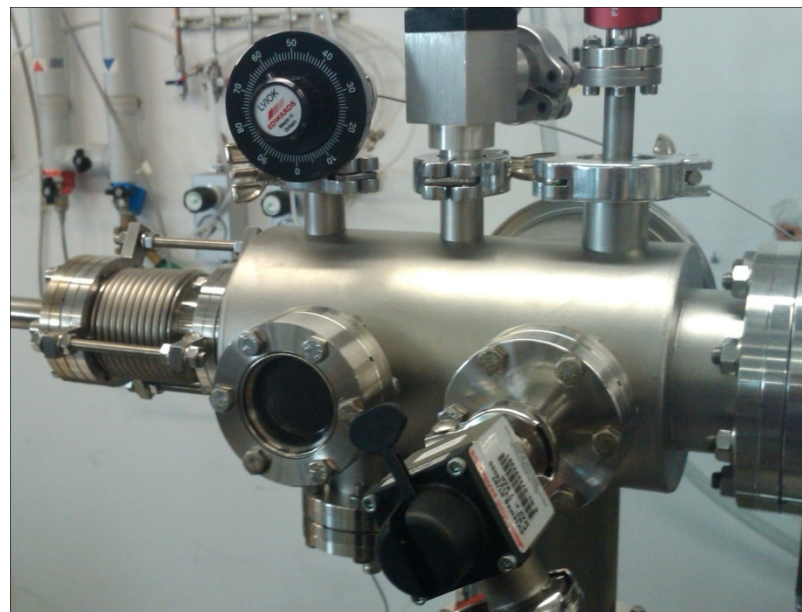
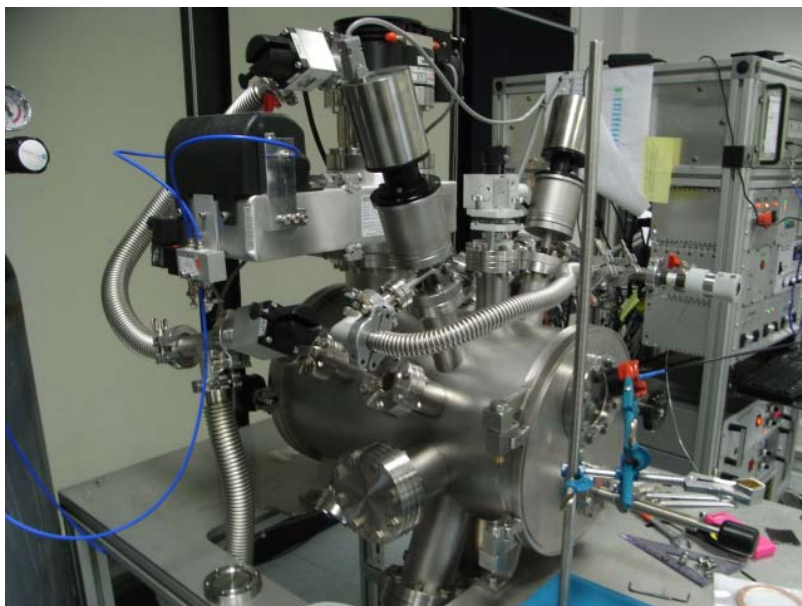
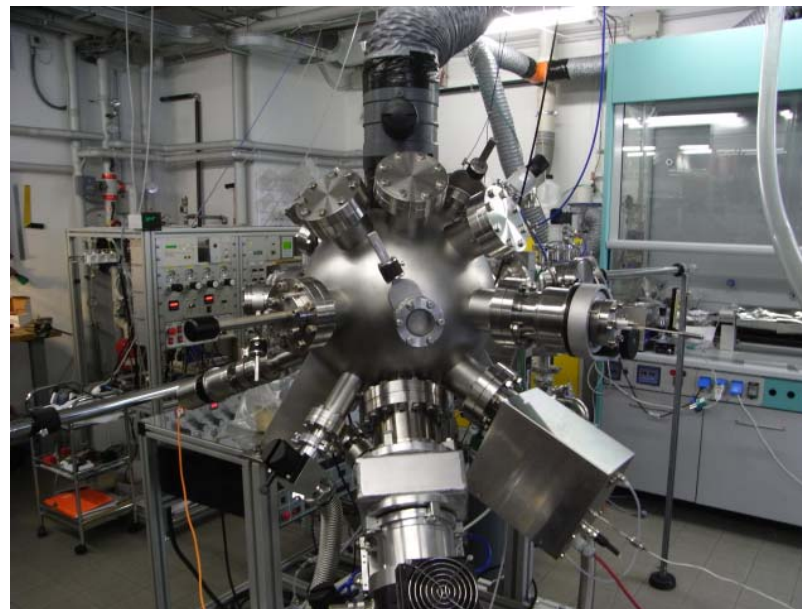
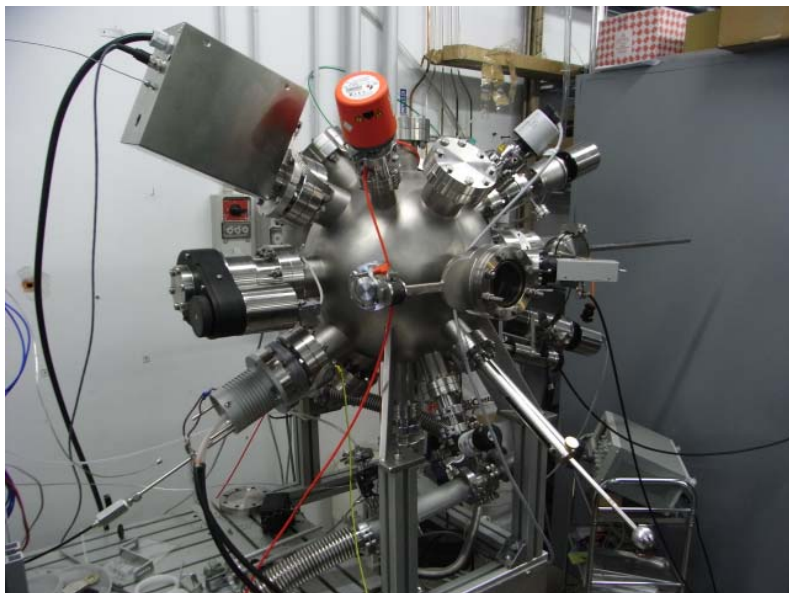
- Wide area
- NEW 30° plasma's intersection for innovative *in situ* doping



Mixing plumes
deposition configuration

PPD systems (Gen II, III and IV) at OS

PPD systems



2" heated sample holder 1.2" rot. target holder

Accessories

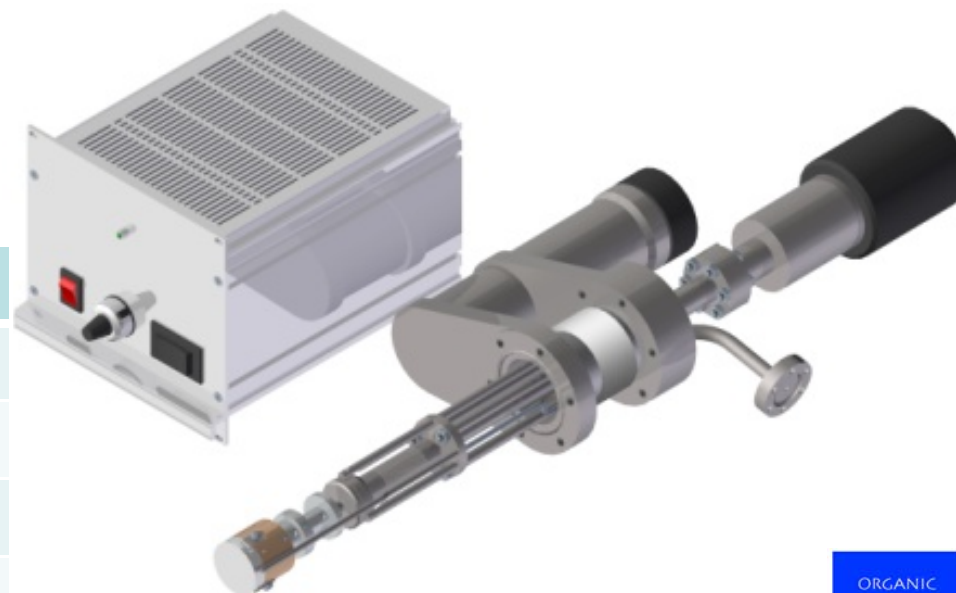


Sample holder

Sample diameter	up to 2 inches
Max. temperature of sample	900 °C
Magnetic rotation	up to 1 Hz
UHV Mounting (z adjustable)	CF 63 50 mm

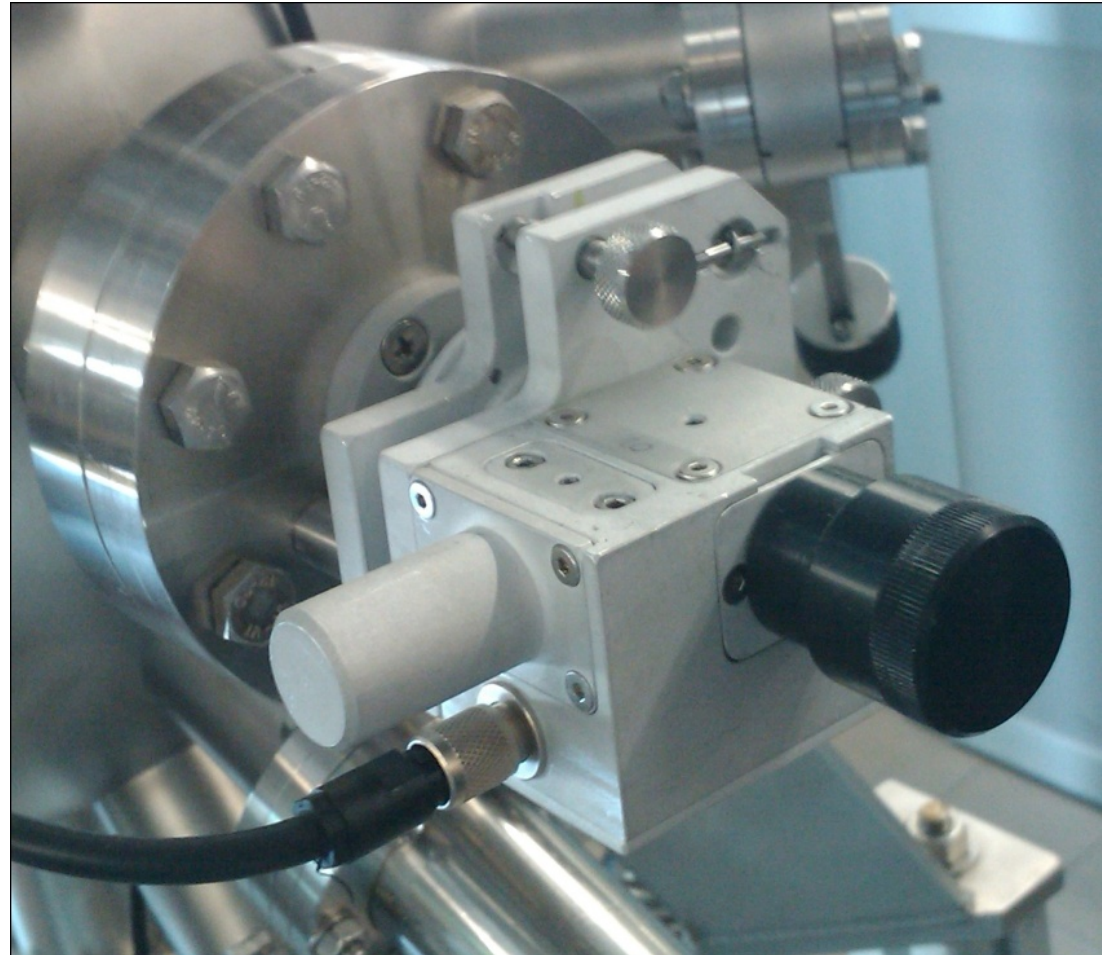
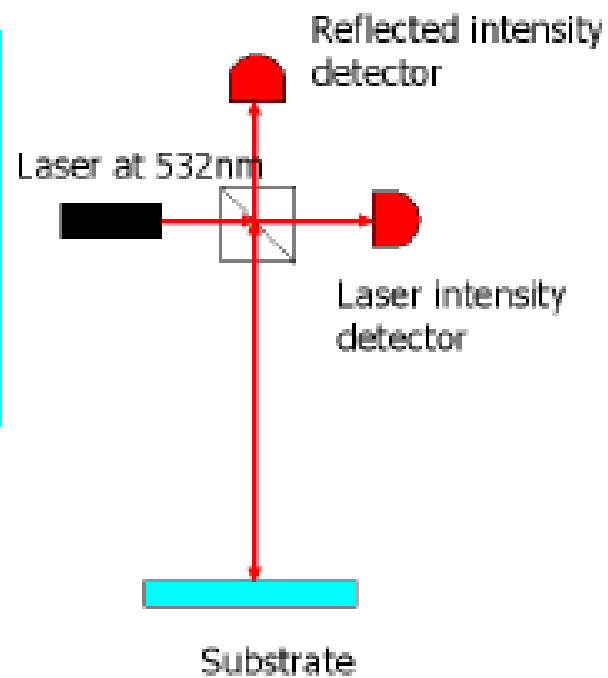
Target holder

Target diameter	Typ. 32 mm
Magnetic rotation	up to 20 Hz
Target tilting (x and y)	up to 5°
UHV mounting (z adjustable)	CF 40 50 mm



in-situ Laser Thickness Monitor (LTM)

Accessories

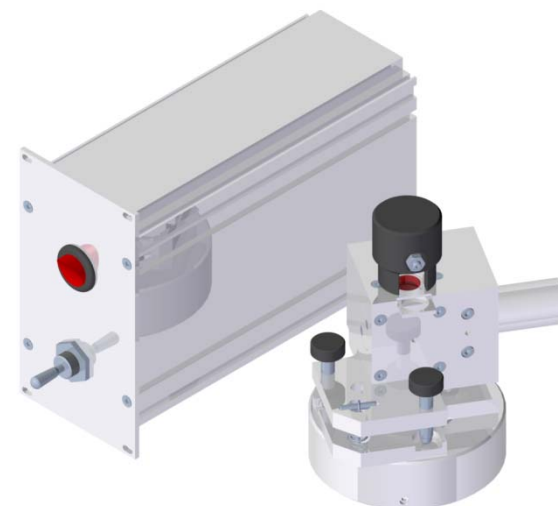


In situ LTM for a wide range of E_g materials

Accessories

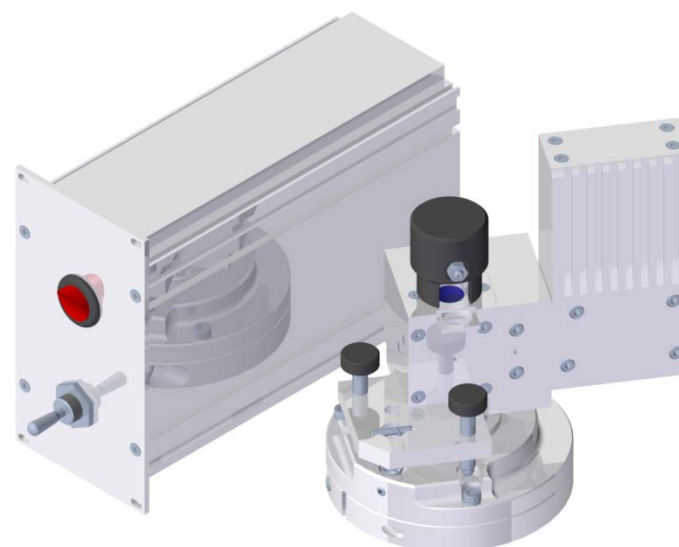
LTM standard specification

Laser frequency	532 nm (or 650, 450 nm)
Laser power	< 5 mW
Thin thickness resolution	Approx. 2 nm



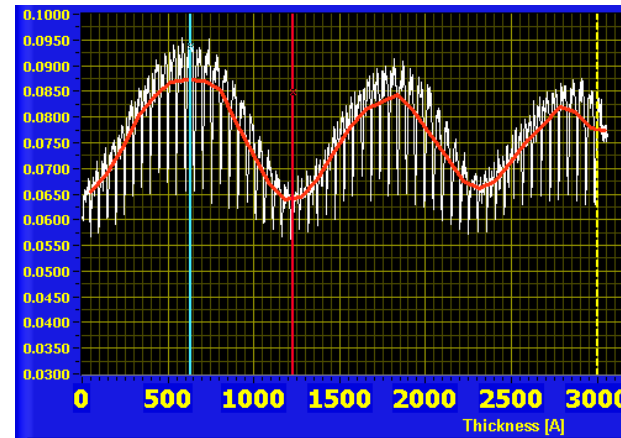
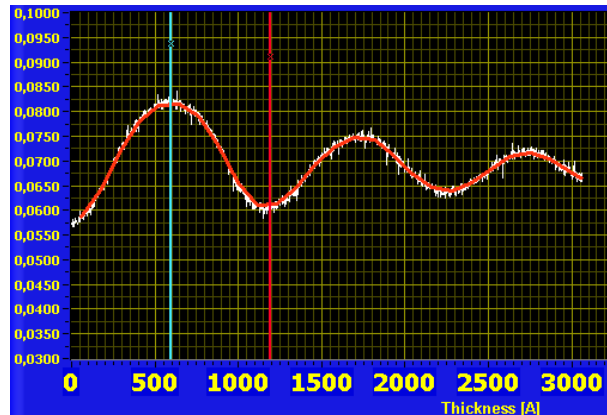
IR (low E_g Materials) LTM specification

Aligning laser	632 nm
Laser power (@ 632 nm)	2 mW
Measuring laser	830 nm
Laser power (@ 830nm)	< 5 mW
Thin thickness resolution	Approx. 2 nm

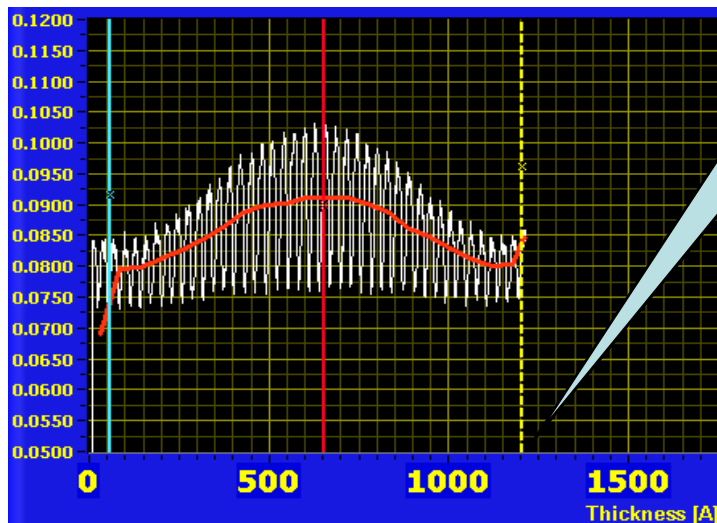


In situ Laser Thickness Monitor (LTM)

Accessories



In situ LTM growth of low E_g material (i.e CdS)

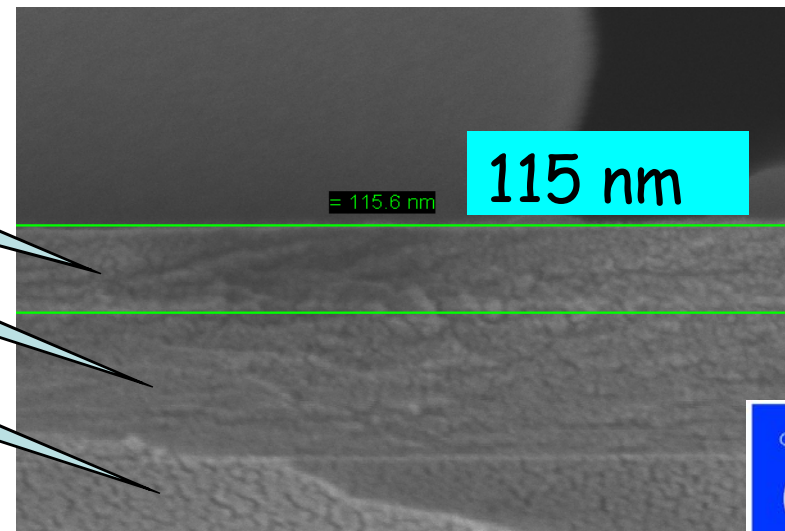


120 nm

CdS

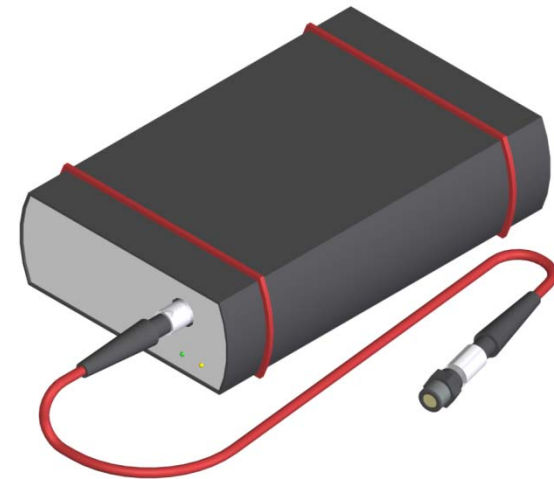
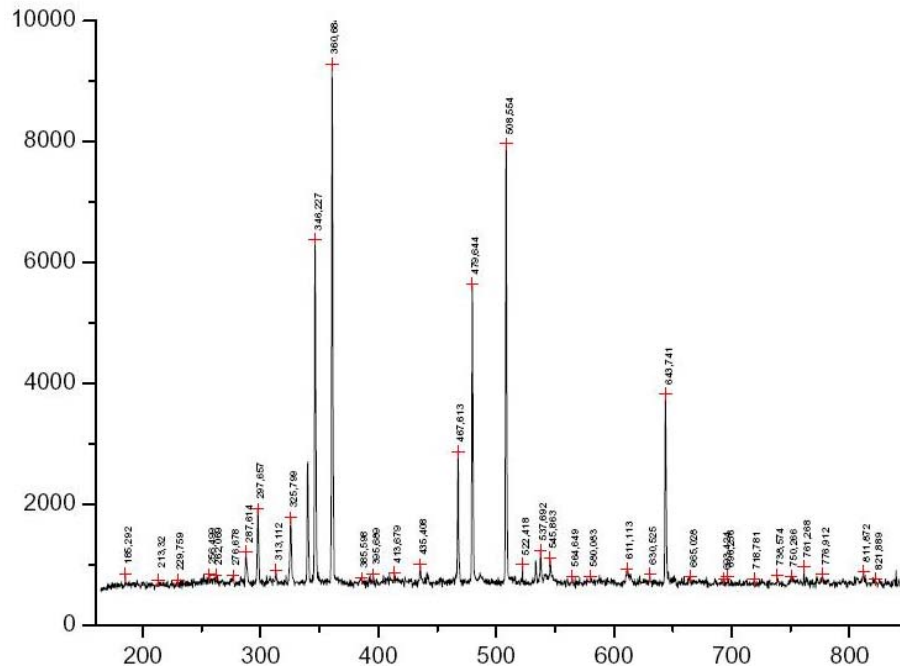
ZnO

vetro



PLSP *in situ* spectrometer for composition growth monitoring

Accessories



Plasma emission spectroscopy (i.e. Zn plasma above fig.)
to identify ionized species in the plume and
to measure the plasma temperature and therefore
the **deposition conditions during growth**

Fabrication parameters are easily reproducible

Industrial developments

PPD technology conclusions

- Wider area
- Increasing deposition rate
- Lower Capex
- Lower thermal budget
- better film quality = efficiency
- Lower costs



Capex → Capex

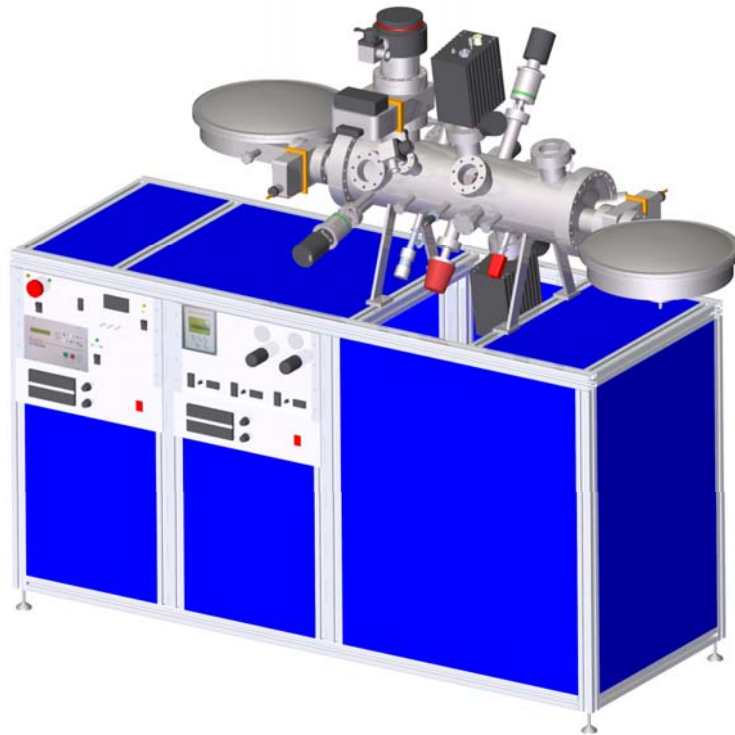
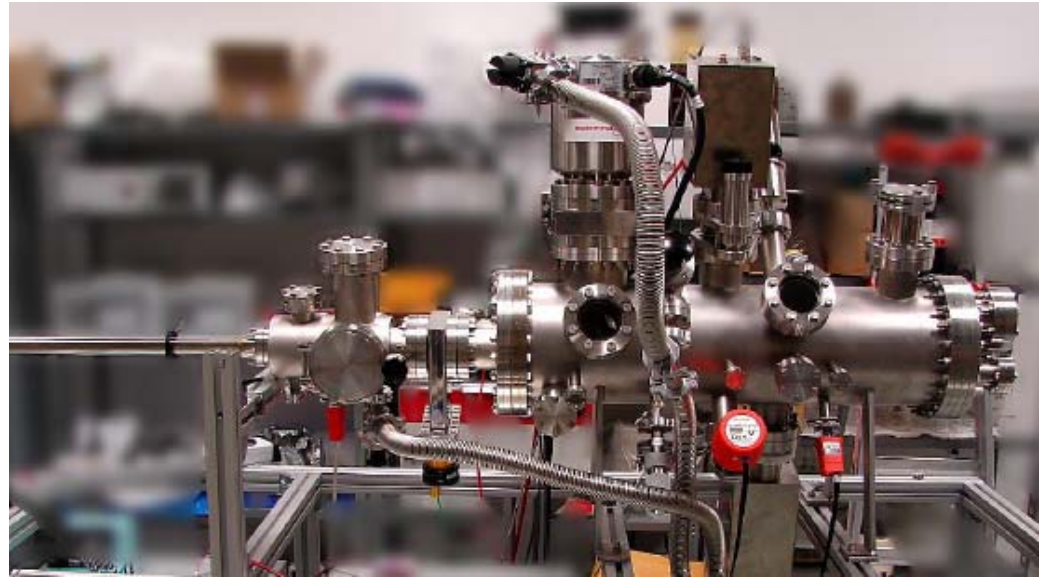


$\$/kWh$ → $\$/kWh$

Linear cw PPD

System information

Base pressure	$< 1 \times 10^{-7}$ mbar
Chamber diameter	DN 200 mm
Chamber length	750 mm
Web size	40 mm
Number of guns	2



A ribbon is fabricated
by a c.w. process
Additive PPD process is proved

Next step is wider web area
deposition by multiple PPD
guns

PPD industrial guns: Gen IV 100Hz



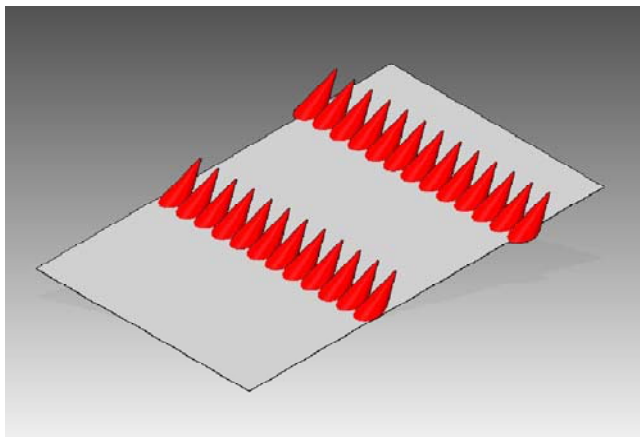
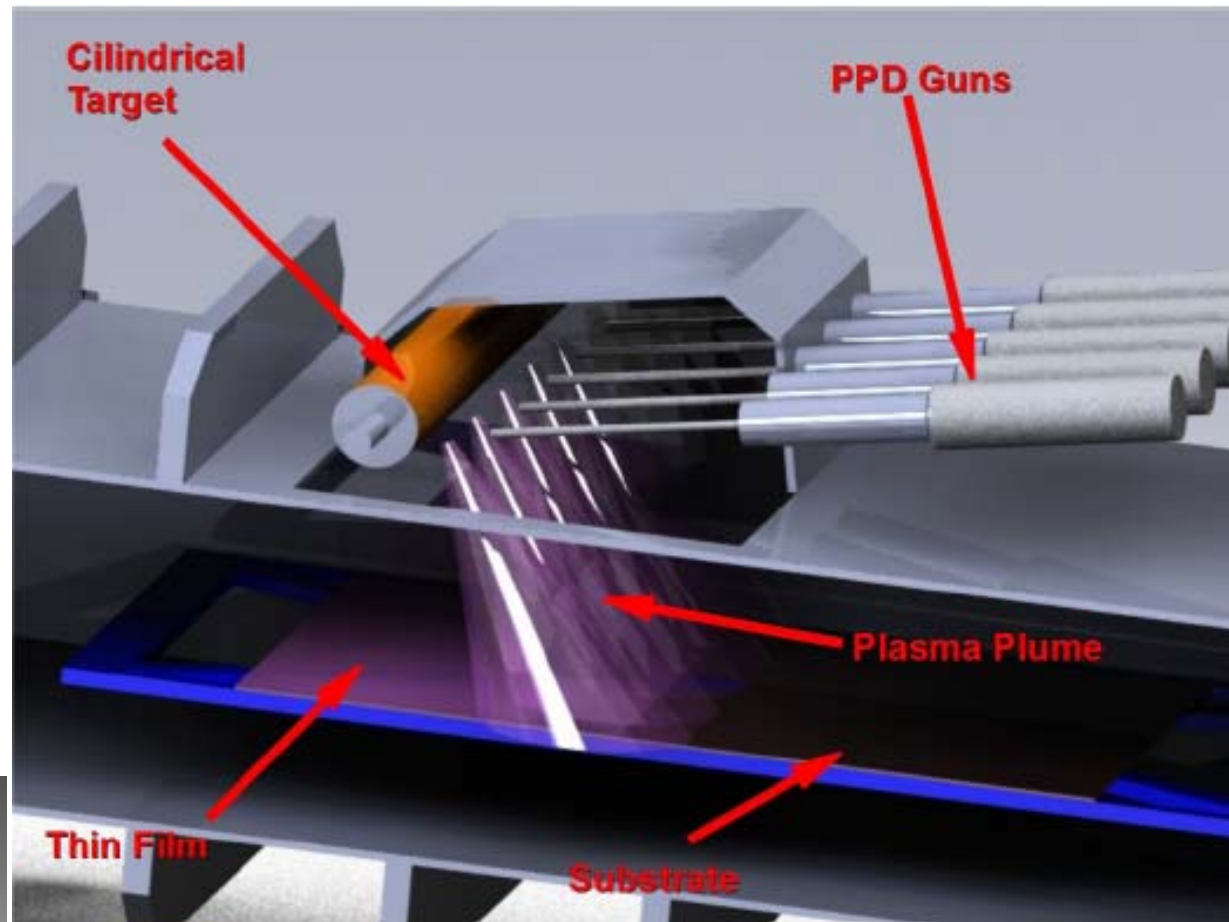
Dep.rate:
up to **700 nm/min**
depending on materials



Gen IV at 100 Hz in operation



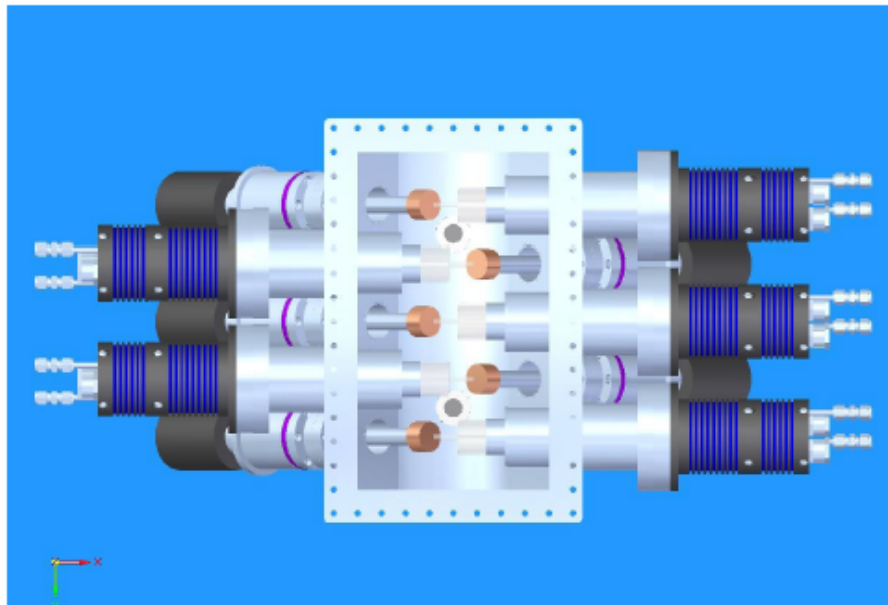
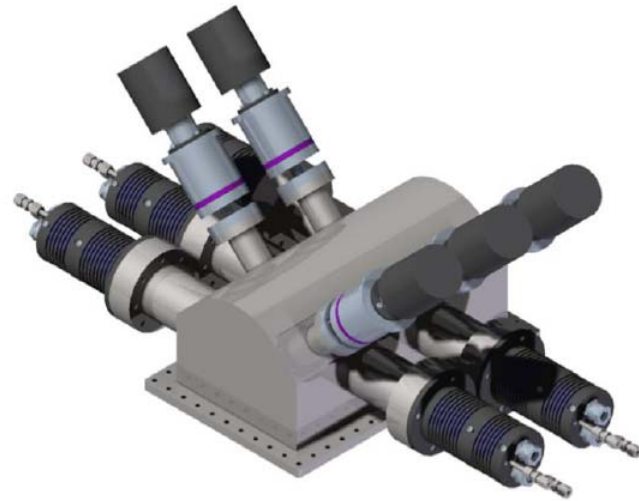
The PPD wide area concept



Wide area R2R PPD

300 mm wide R2R modular system for the pilot production unit

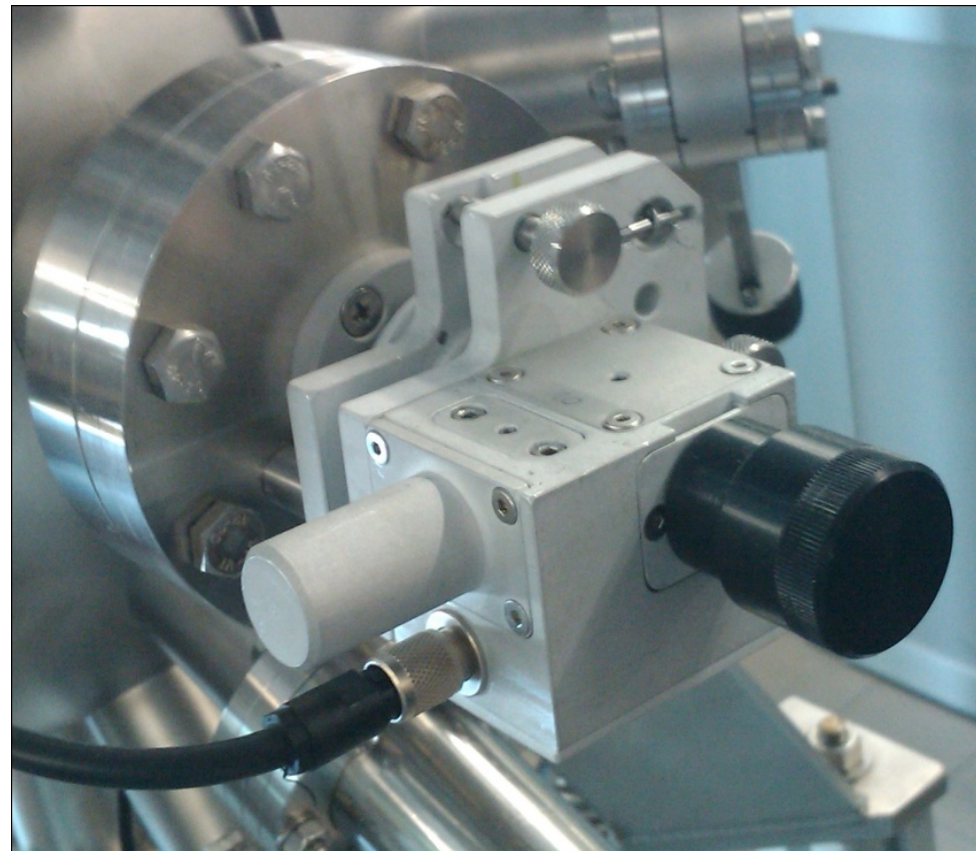
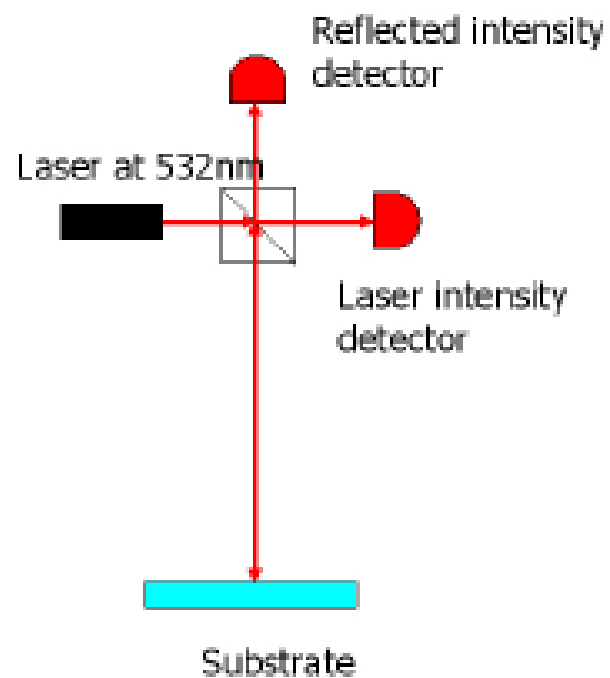
Multiple modules may allow to reach the desired productivity



The plasma surface coverage has a gaussian shape and is therefore suitable for homogeneous coverage on **wider web sizes**

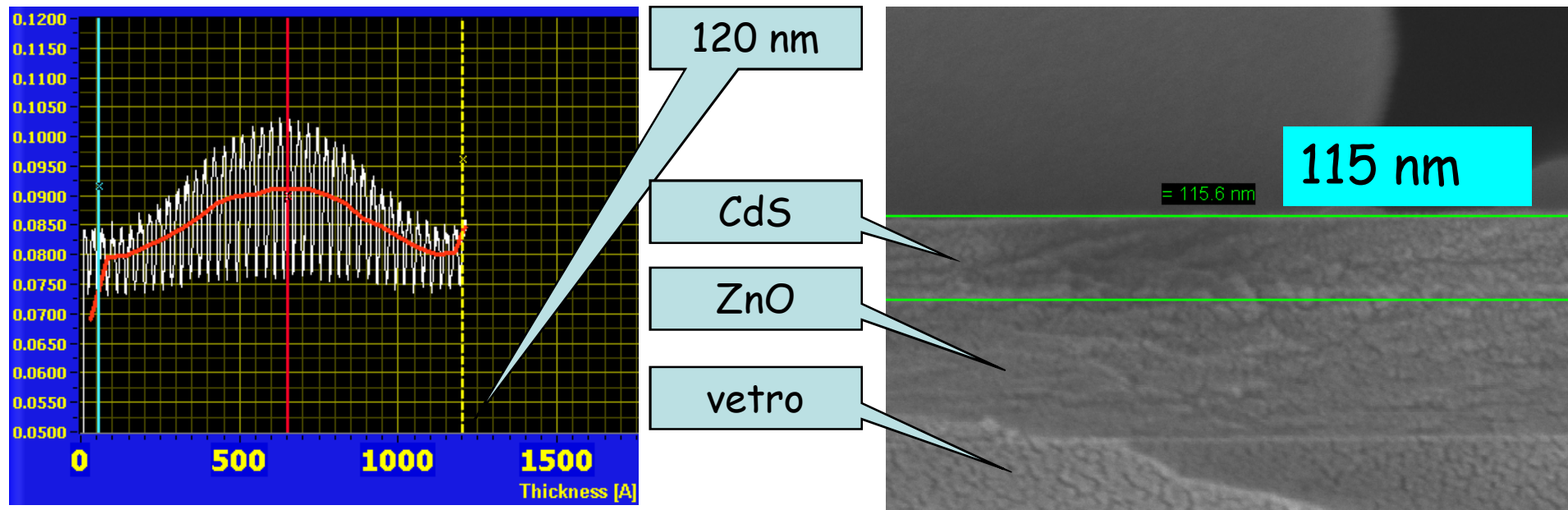
Accessories for the PPD R2R

in-situ Laser Thickness Monitor (LTM)



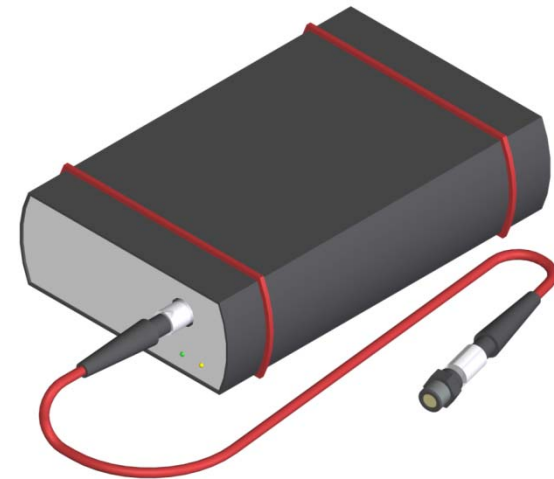
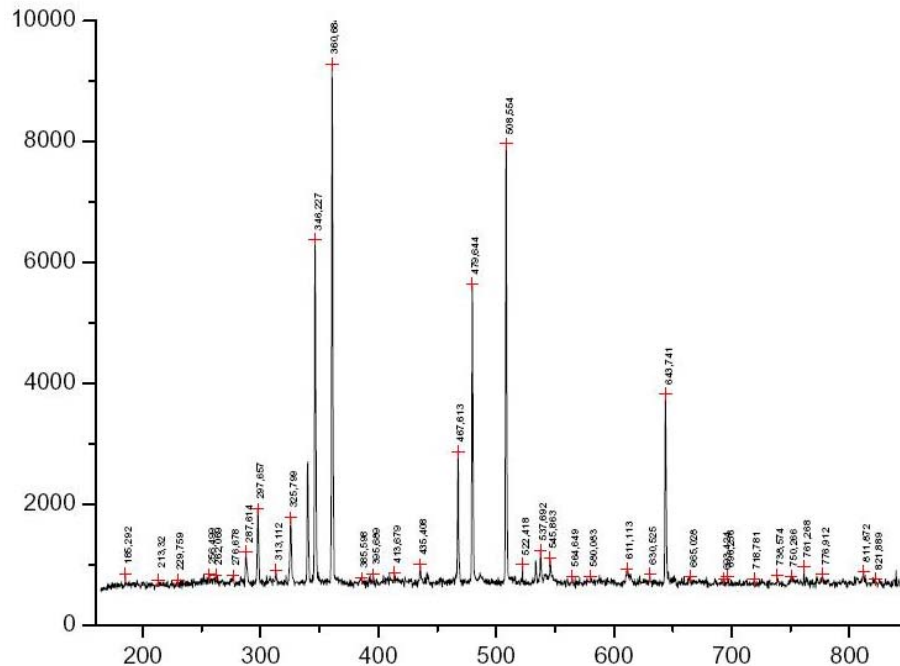
Accessories for the PPD R2R

In situ LTM measurement of a low E_g material (i.e CdS)



Accessories for the PPD R2R

PLSP in situ spectrometer for composition growth monitoring



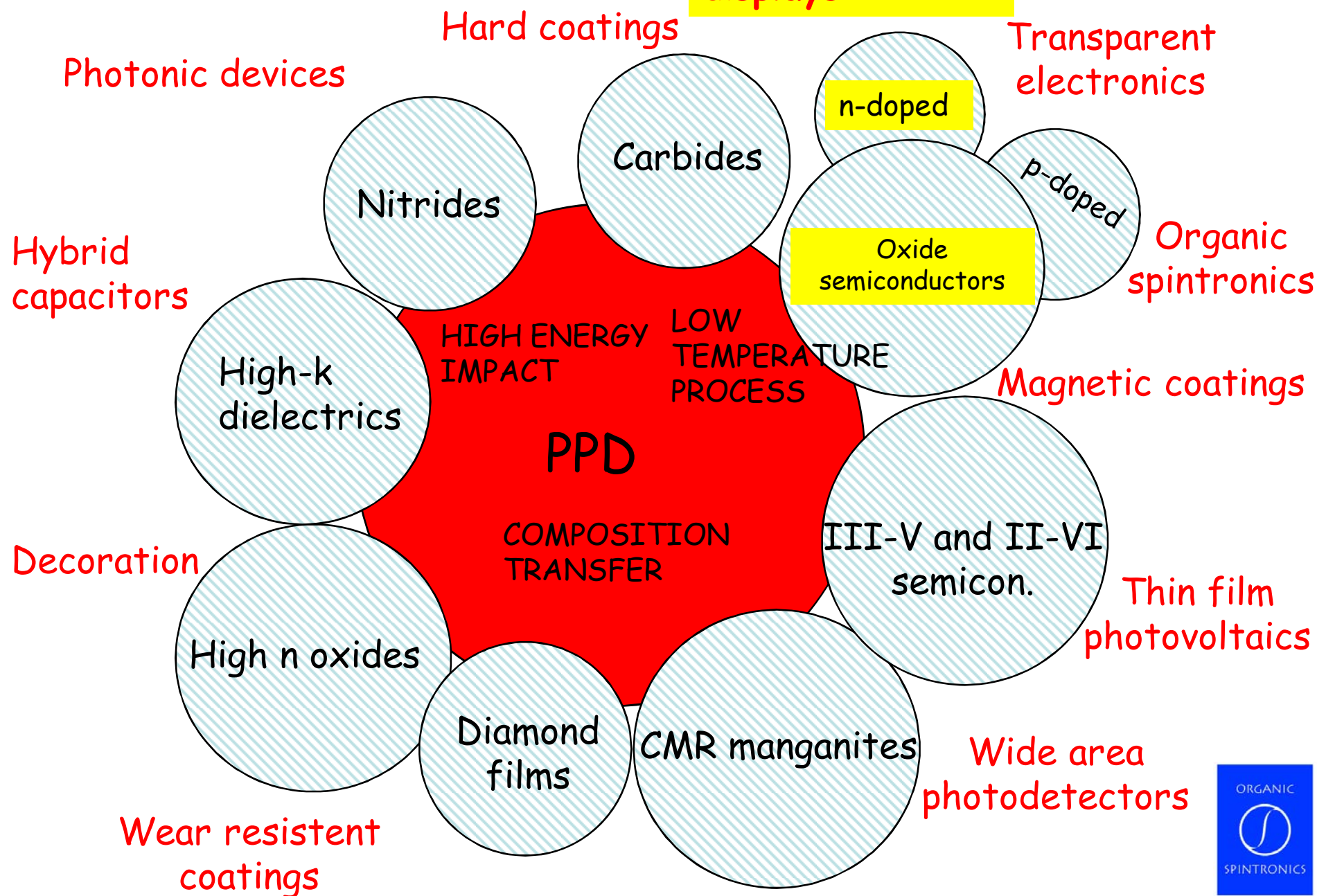
Plasma emission spectroscopy (i.e. Zn plasma above fig.)
to identify ionized species in the plume and
to measure the plasma temperature and therefore
the **deposition conditions during growth**

Fabrication parameters are easily reproducible

TCO on flexible substrates
enabling flexible OPV
**i.e. enabling OPV future
perspectives !!!**

Applications

Flexible PV and displays



Oxygen vacancy n doping of TCO

Doping may be achieved either by:

- Substitution (i.e.: tetravalent vs trivalent ions)
- Removal of oxygen (oxygen vacancies)

Substitution (i.e. Sn vs In in ITO) requires heating post-recrystallization to overcome the **site substitution barrier** as in sputtering.

With the PPD process oxygen **vacancies** are introduced at **room temperature**

Next generation displays



Flexible issues

Applications

Flexible electronics
Flexible displays
Flexible photovoltaics
more..

Active materials

Soft matter:
Organic semiconductors
Polymers

Requirements

TCO at **low temperature**
+ **Barrier** to oxygen and
water

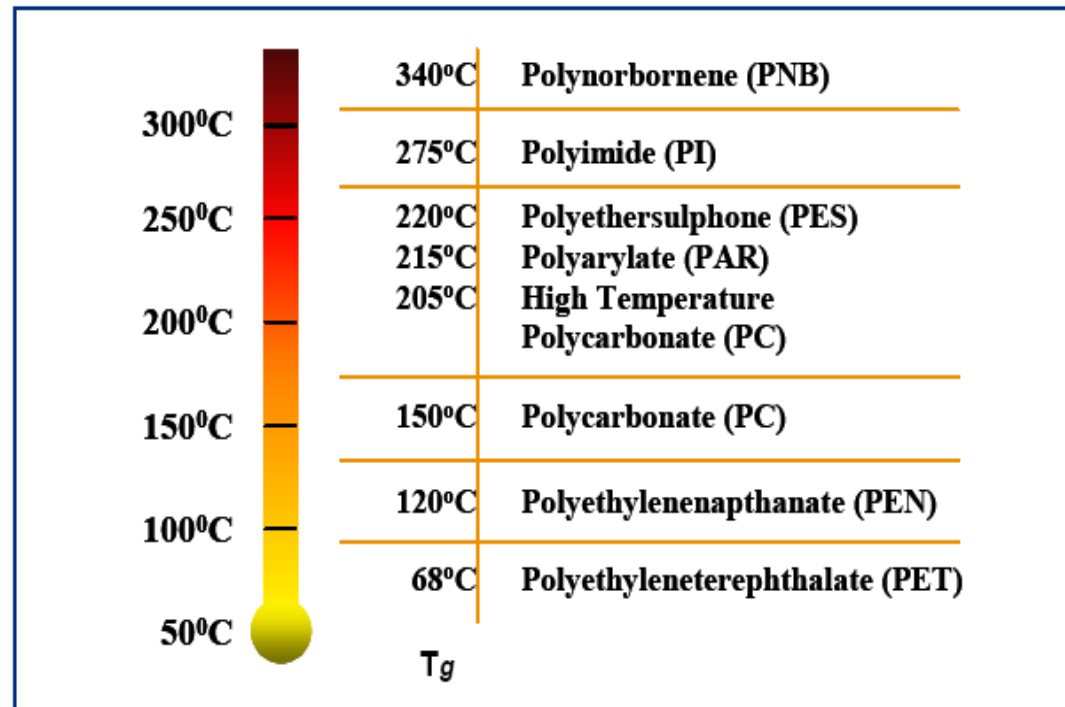
Substrates

Plastic substrates:
Lower cost
Good mech. properties

TCO: the temperature factor vs substrate

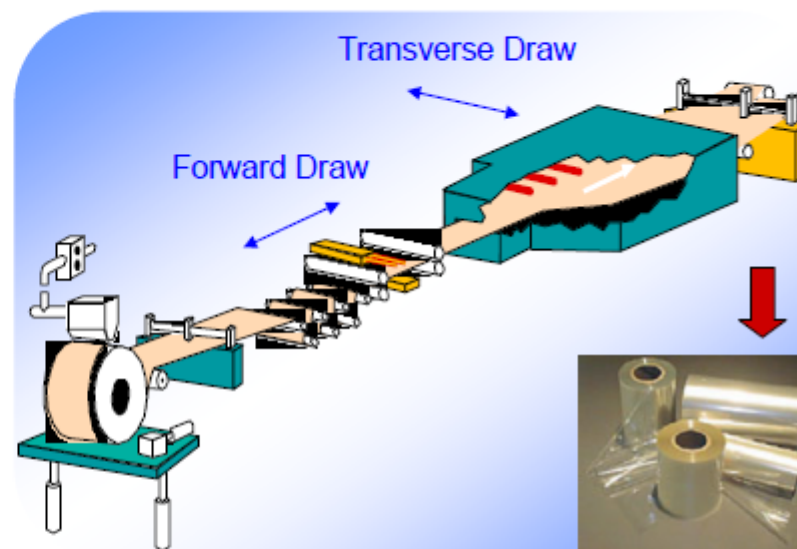
The most appealing plastic substrate is PET for which the processing TCO cannot exceed 80°C (see the inset).

The Pulsed Plasma Deposition technique (PPD) developed by Organic Spintronics is a **novel thin film fabrication method** that allows to process TCO at **room temperature**.

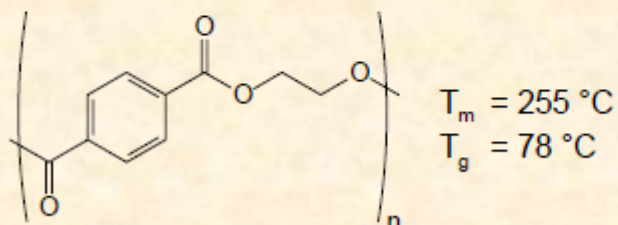


Polyester Film Technology (1)

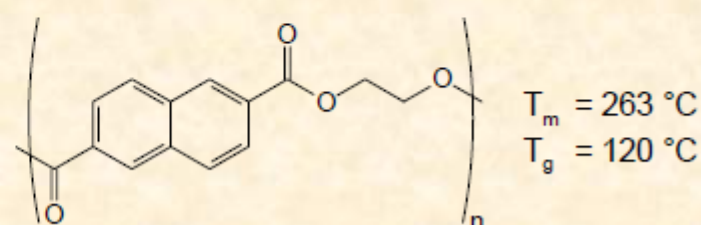
- ❑ PET and PEN polyester films
- ❑ Biaxially oriented, semi-crystalline
 - High stiffness
 - Dimensional stability
 - Optical transparency
 - Solvent resistance
 - Thickness = 0.5-500 μm



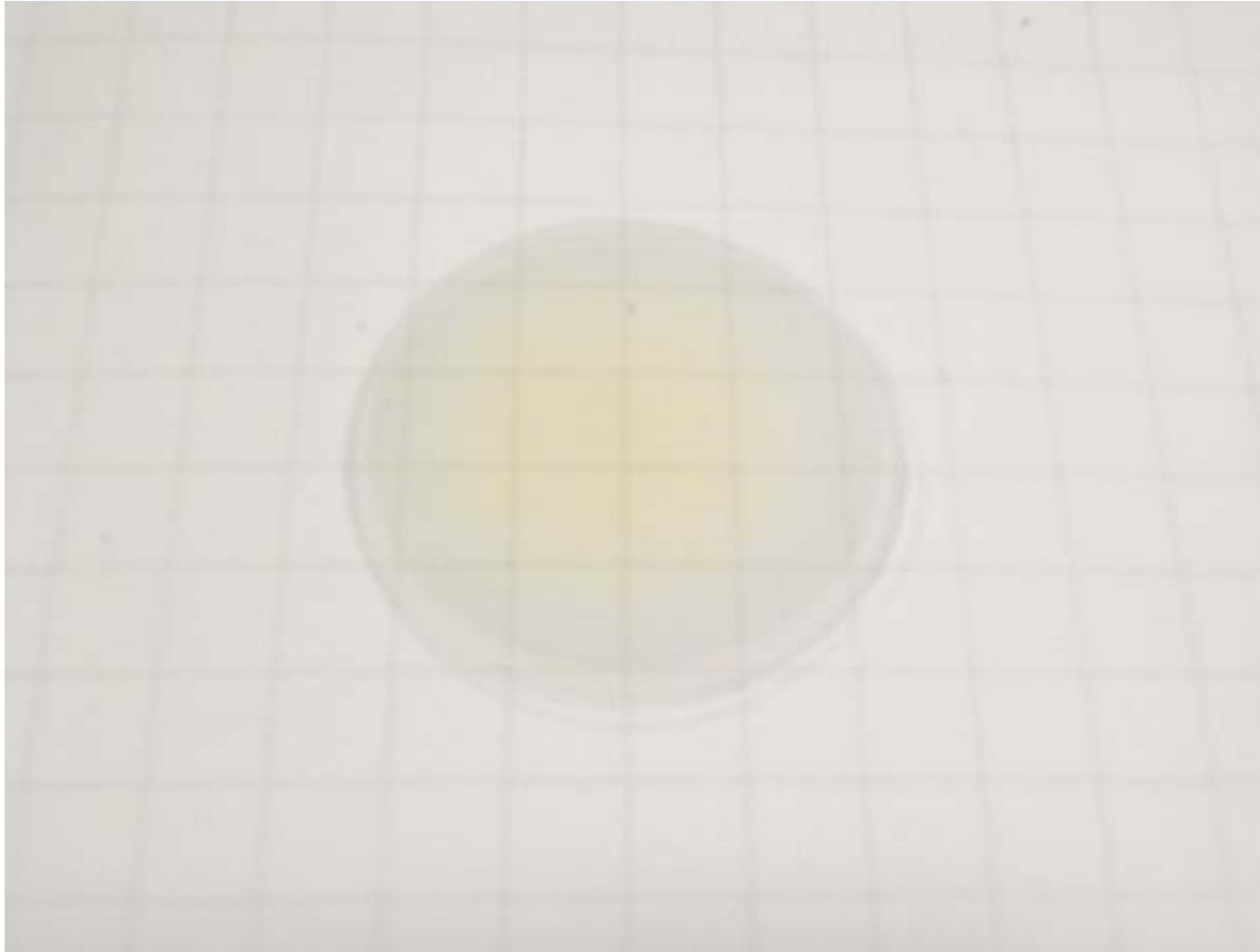
Melinex[®], Mylar[®] and Teijin[®] Teton[®]
Polyethylene terephthalate (PET)



Teonex[®]
Polyethylene naphthalate (PEN)



Transparent Conducting Oxide on PET by the PPD at room temperature

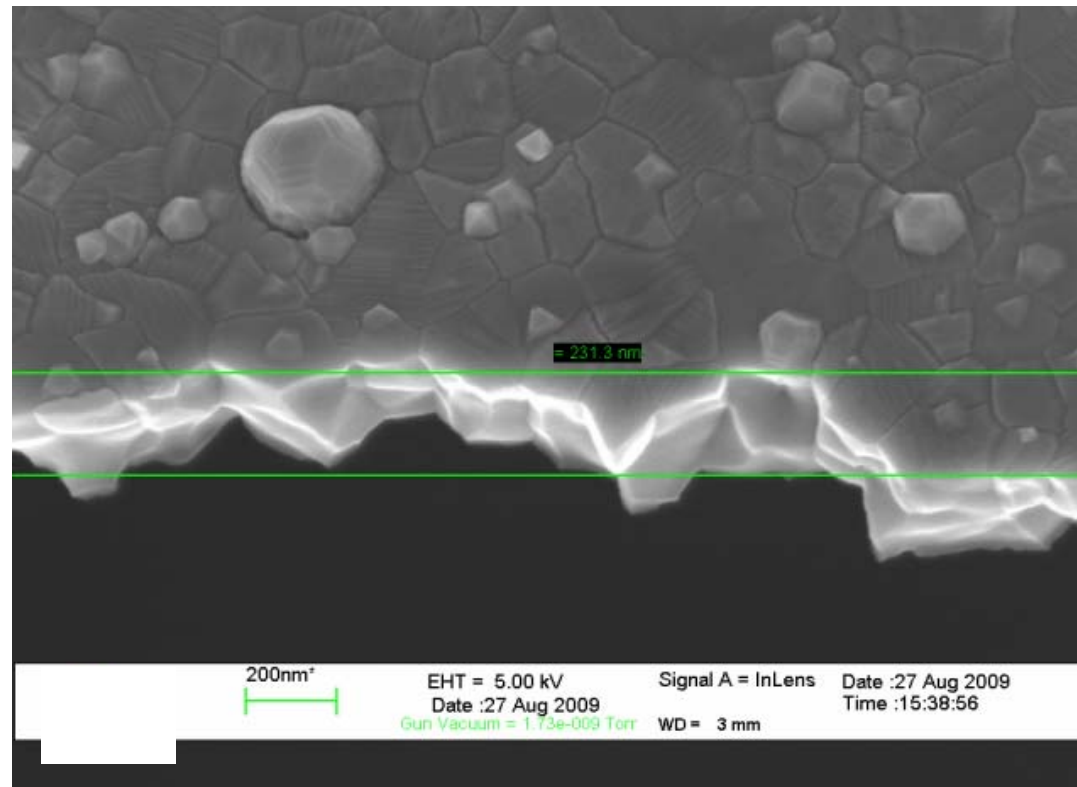


RT PPD deposition on plastics: OS Patent pending

Characteristics of n_ ZnO on PET by PPD at room temperature

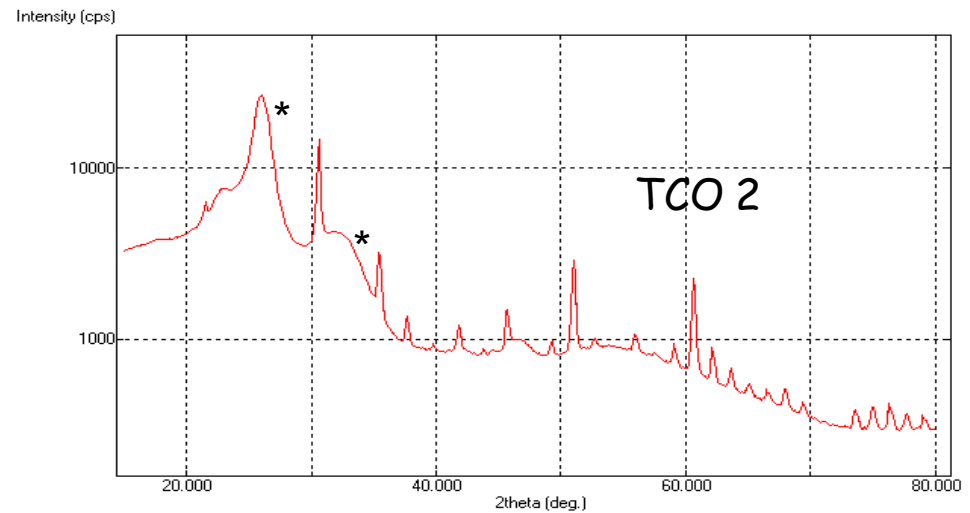
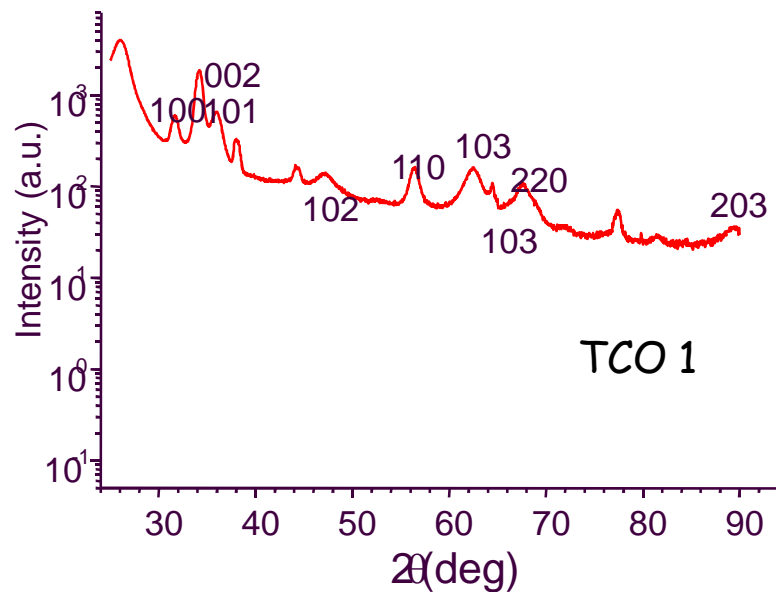
Characteristics	
Substrate	Melinex ST 504 (Du Pont)
Thickness	200 nm
Sheet resistance	Approx. 10 ohm square
Average VIS transmittance (T%)	Higher than 90 T%
Roughness (Rq)	19 nm
Uniformity (with two guns)	8% at 3 sigma

SEM of n-ZnO on PET by the PPD at RT

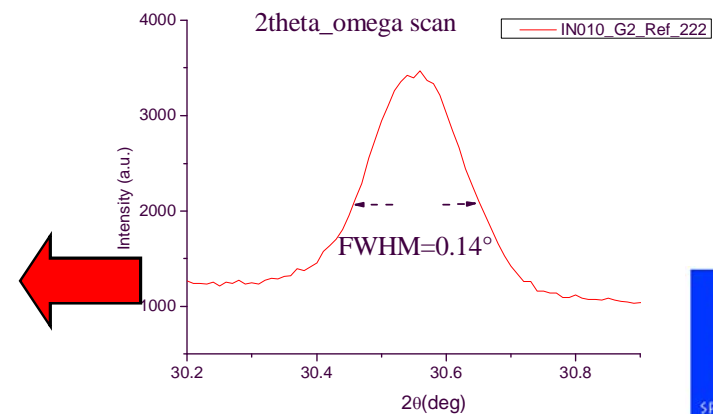


Dense and highly connected cristalline layer from the phase SPM
Excellent conductivity.

High cristallinity at RT growth XRD grazing incidence



Randomly oriented
Cristallites
Size (LRO) of **65 nm**

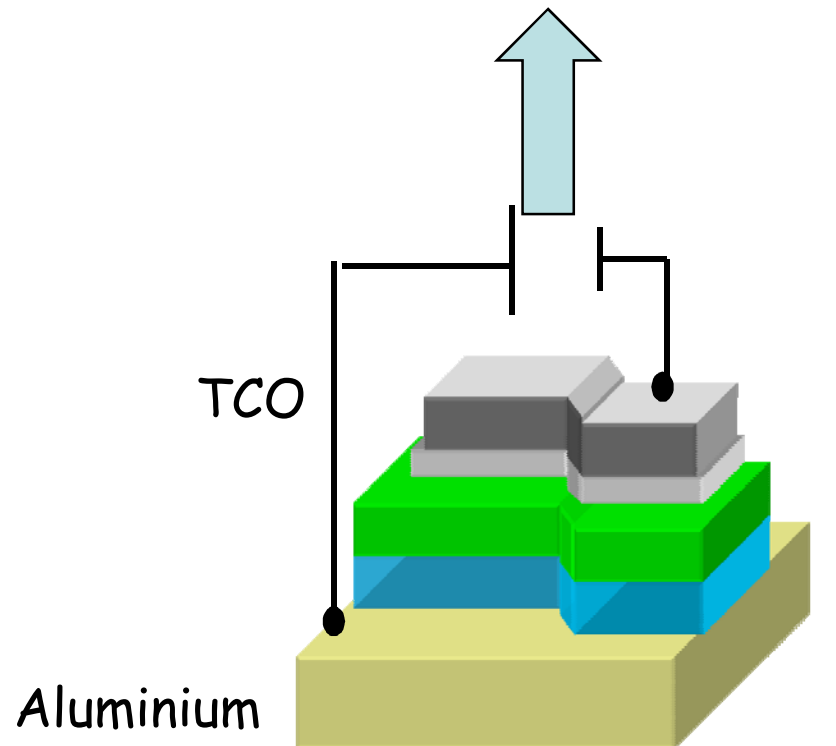


TCO on flexible substrates
enabling flexible OLED

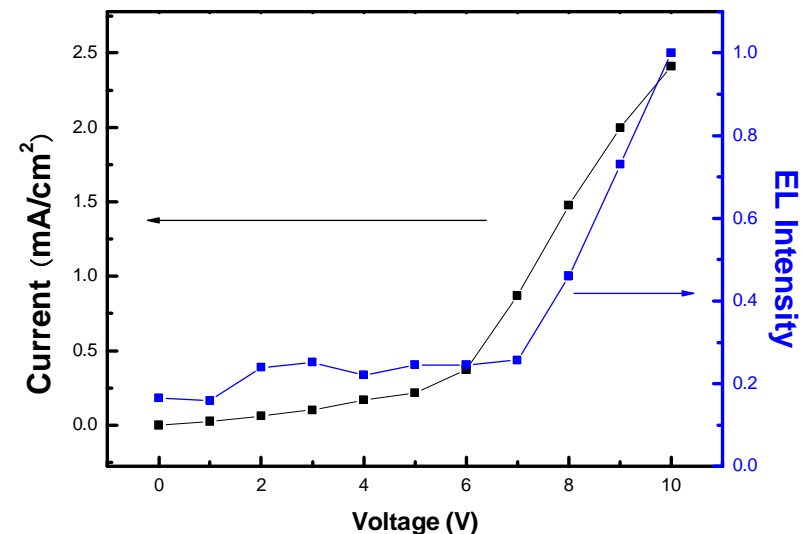
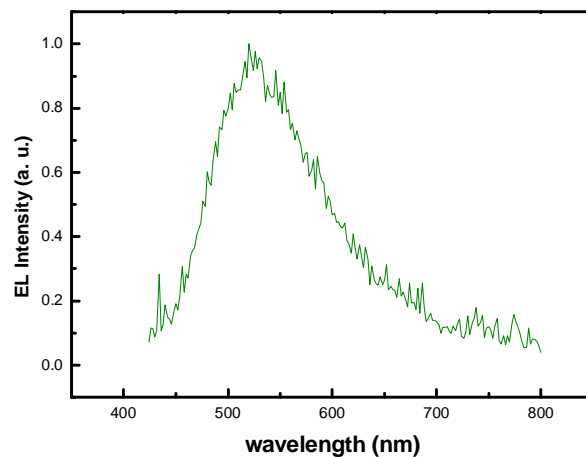
Top emitting OLED

RT TCO (IMO) on Organic Semiconductors

Y. Zhang, E. Lunedei



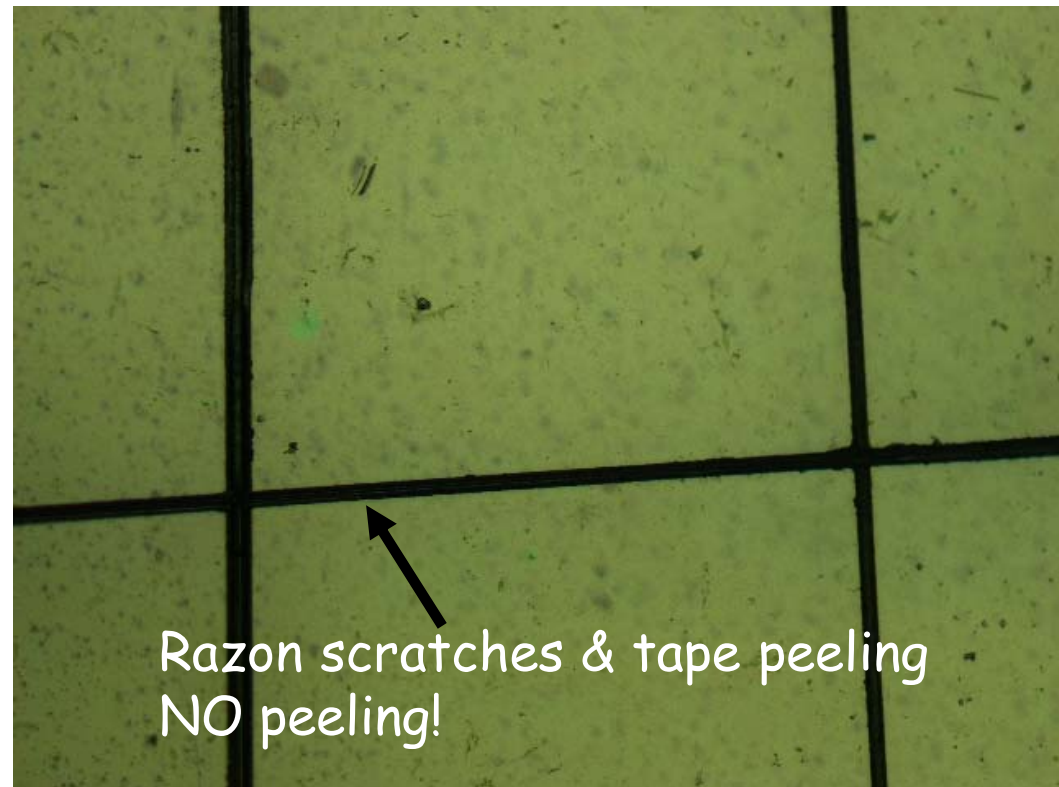
TCO (IMO) is deposited
on top of the organic
semiconductor (AlQ3)



Adhesion

Spec: MIL - M - 13508

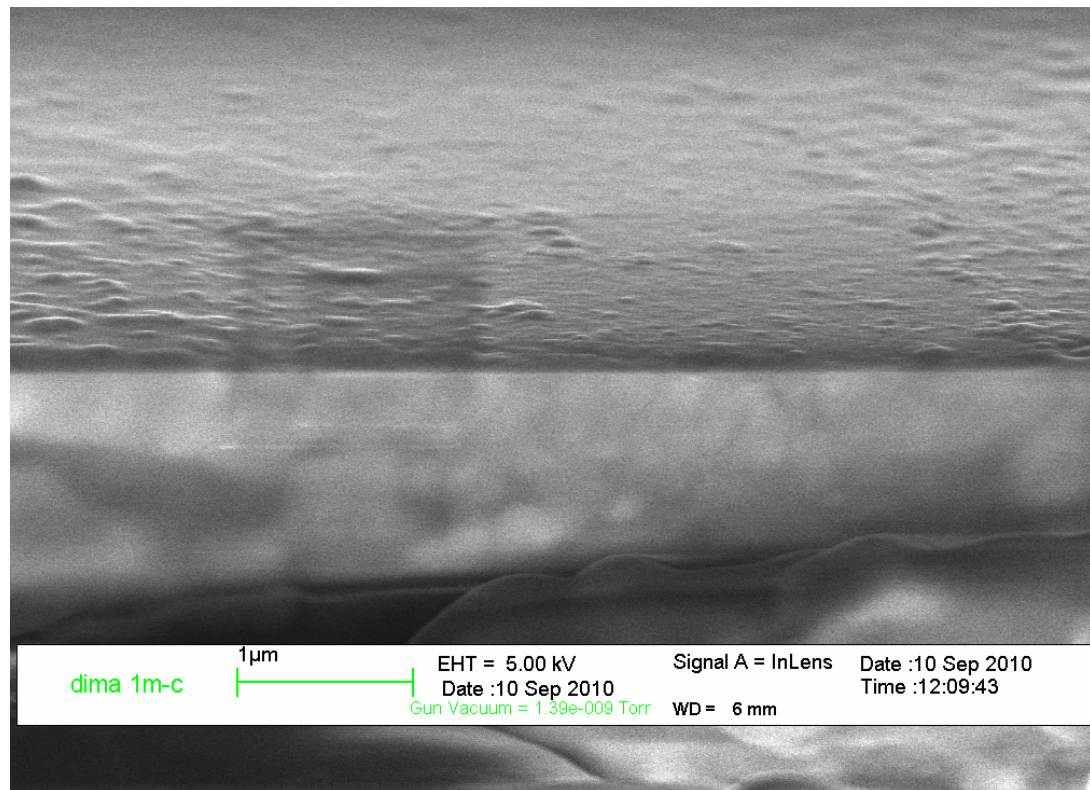
Surface of TCO on
PET (x500)
After scratching and
Peeling
(scratch test)

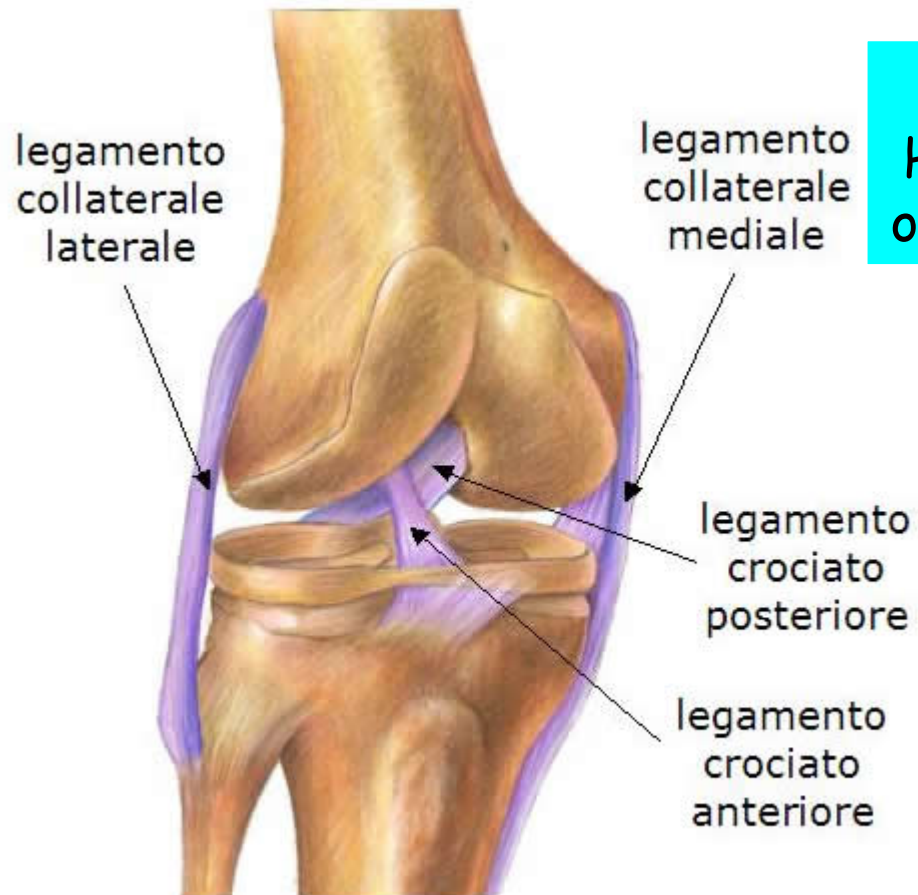


Room Temperature deposition on plastics: Patented

Hard coatings for implants

Zirconia (ZrO_x) on PET by PPD

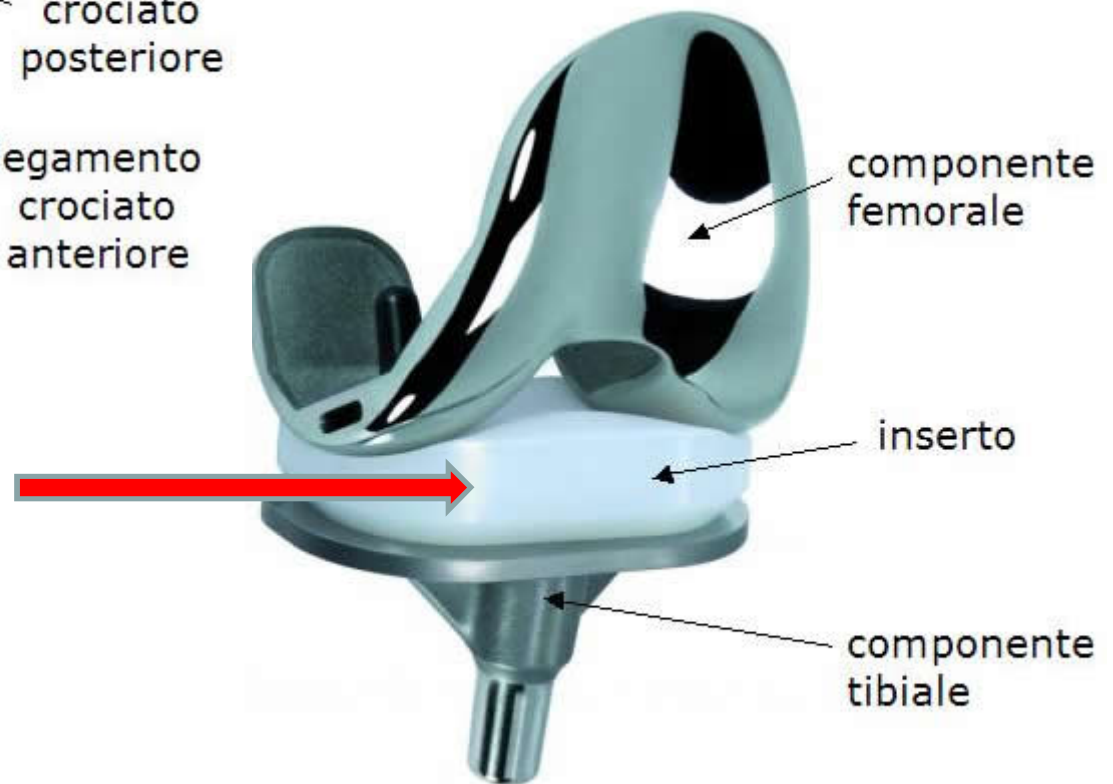




Problem:

HDPE insert has a limited lifetime
only 2 may be executed on a patient

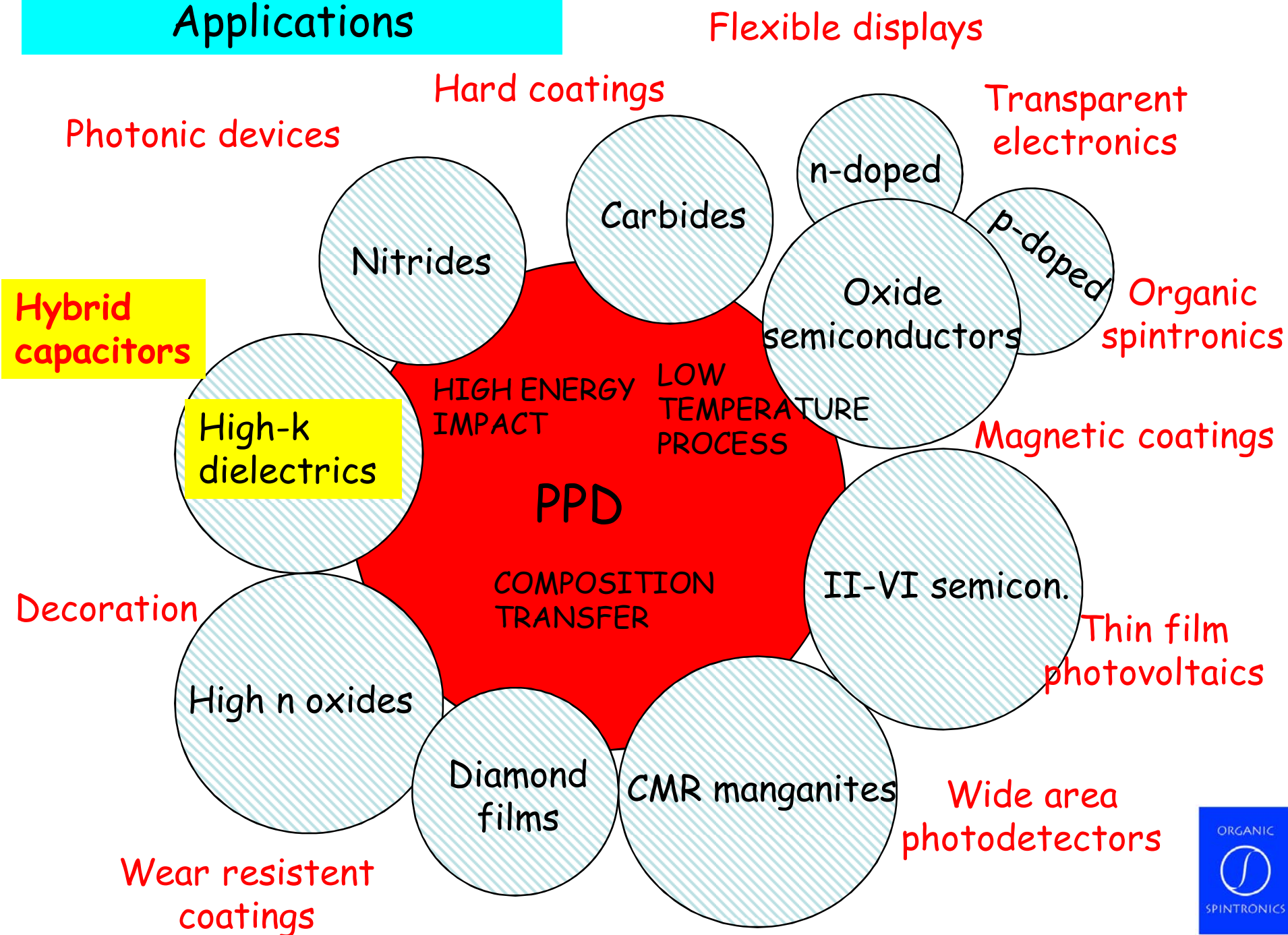
Need of a hard coating
on HDPE



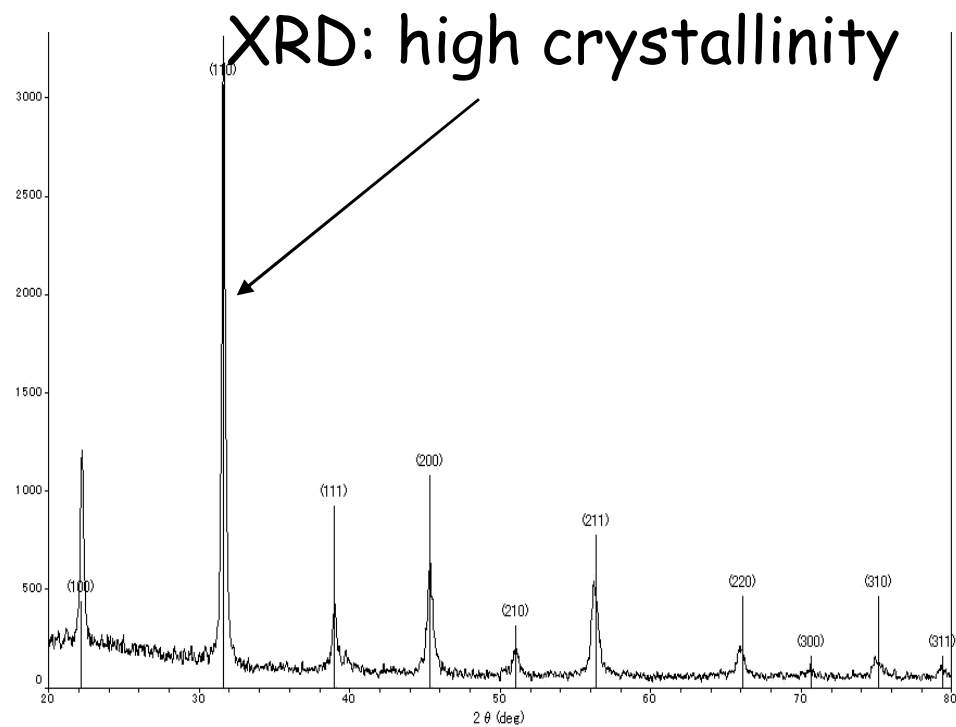
(immagine concessa da Lima-Lto SpA)

More applications of the PPD

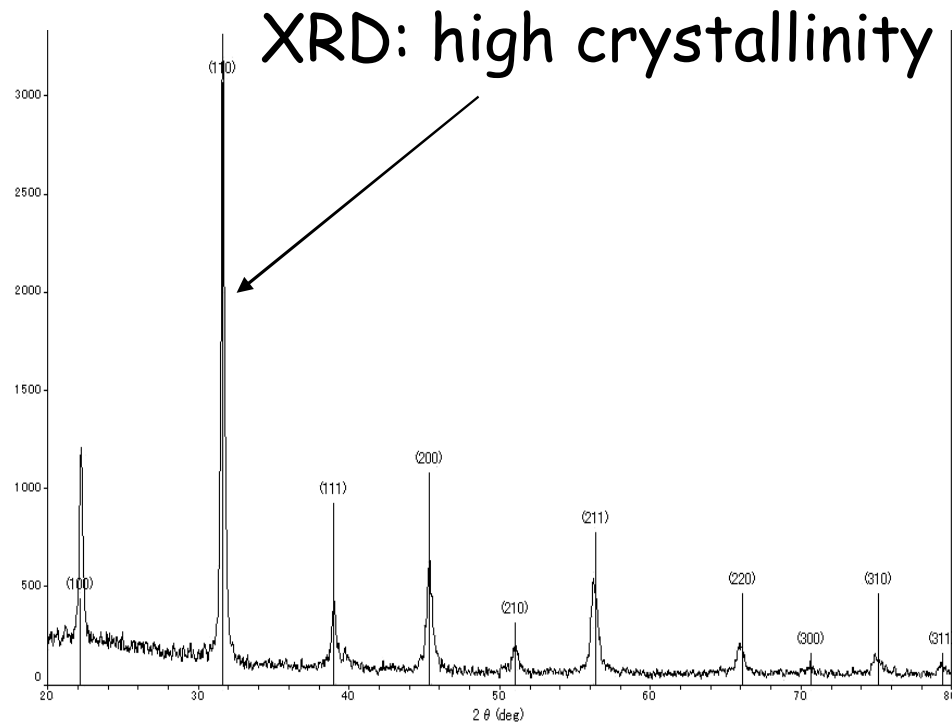
Applications



Barium Strontium Titanate (BST) by PPD on sapphire

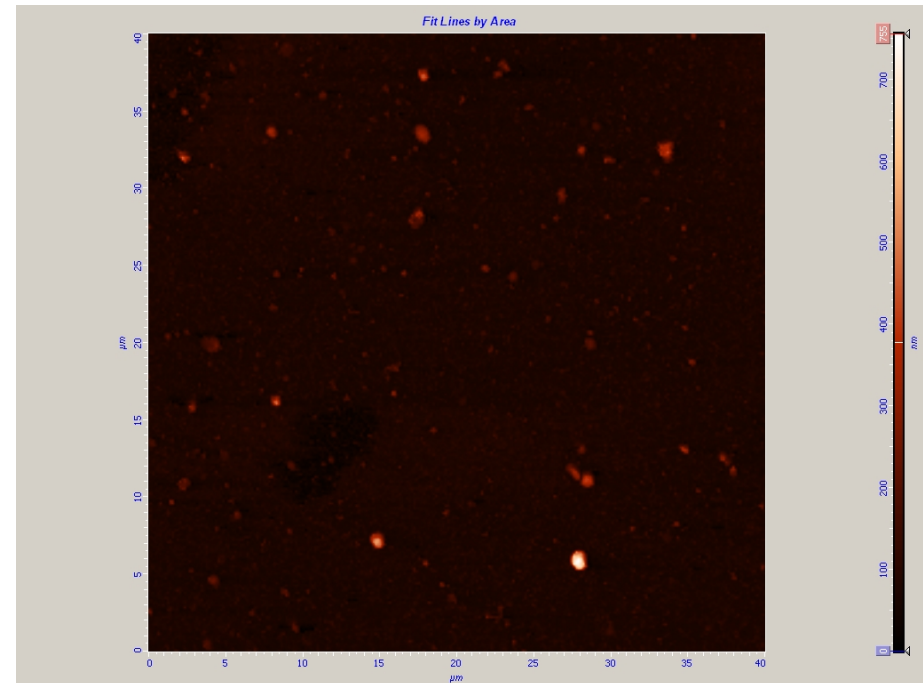


Barium Strontium Titanate (BST) by PPD on sapphire

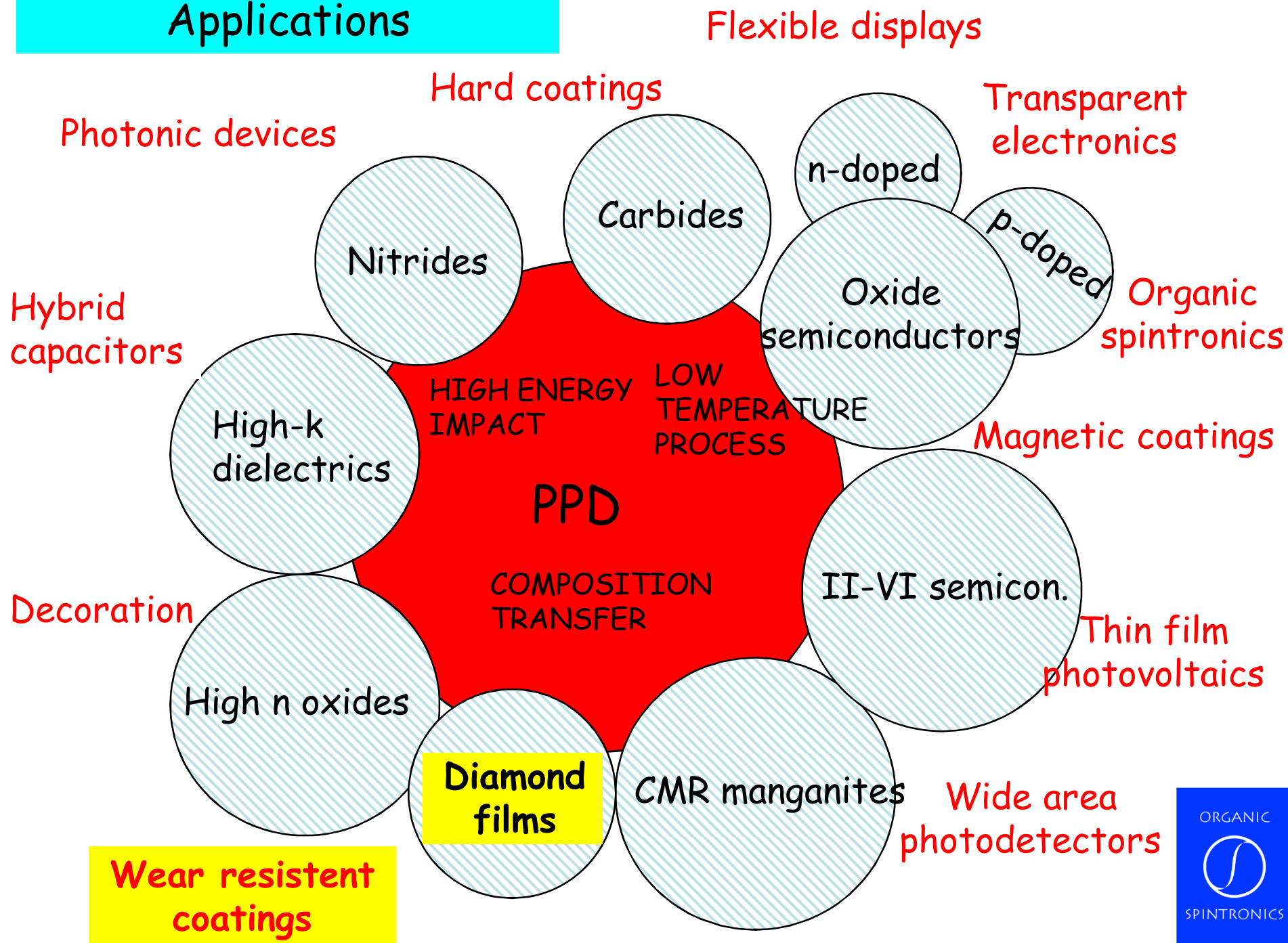


Dielectric constant : 500

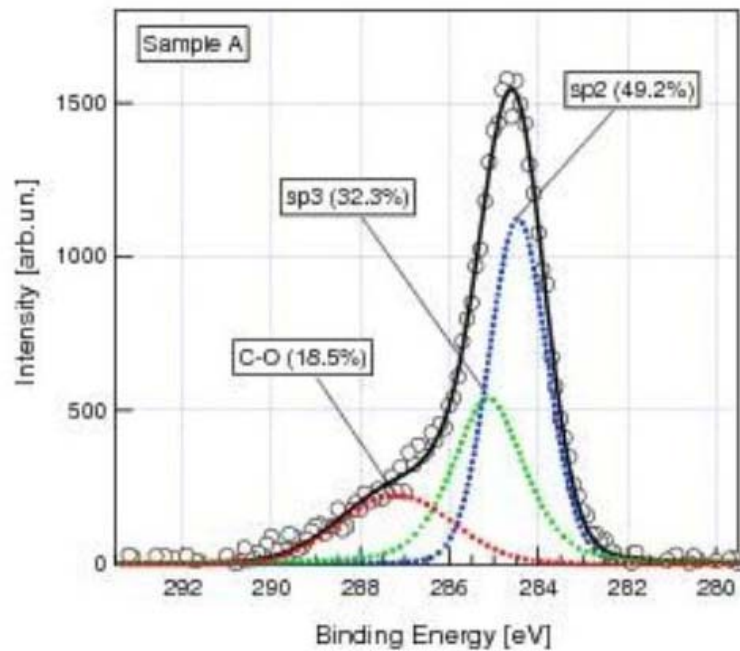
AFM: low roughness



Applications



Tetrahedral α carbon by PPD on WC



XPS: 80% sp^3
 α carbon

Conclusion

Pulsed Plasma Deposition (PPD) allows to:

- Transfer of the target **composition** to the sample
- Fabricate thin films at low temperature

PPD **enables** the fabrication of:

- Chalcogenide photovoltaic thin films
- Transparent conducting oxides (TCO) at room temperature
- High dielectrics like barium strontium titanate (BST)
- Many more

PPD is industrially **scalable, efficient and with a high rep. rate**

Team

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